

#### 8/4/2 kB ISP Flash MCU Family

#### **Analog Peripherals**

#### - 12-Bit ADC

- ±1 LSB INL; no missing codes
- Programmable throughput up to 200 ksps
- Up to 6/16 external inputs
- Data dependent windowed interrupt generator
  Built-in temperature sensor
- Comparator
  - Programmable hysteresis and response time
  - Configurable as wake-up or reset source
- Low current
   POR/Brownout Detector
- Voltage Reference—1.5 and 2.2 V (programmable)

#### **On-Chip Debug**

- On-chip debug circuitry facilitates full-speed, nonintrusive in-system debug (No emulator required)
- Provides breakpoints, single stepping
- Inspect/modify memory and registers
- Complete development kit

#### Supply Voltage 1.8 to 5.25 V

- Built-in LDO regulator

#### High Speed 8051 µC Core

- Pipelined instruction architecture; executes 70% of instructions in 1 or 2 system clocks
- Up to 25 MIPS throughput with 25 MHz system clock
- Expanded interrupt handler

#### Memory

- 8/4/2 kB Flash; In-system byte programmable in 512 byte sectors
- 256 bytes internal data RAM

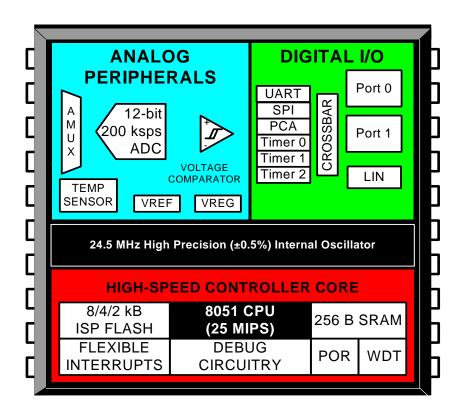
#### **Digital Peripherals**

- 16/6 port I/O; push-pull or open-drain, 5 V tolerant
- Hardware SPI™, and UART serial port
- Hardware LIN (both master and slave, compatible with V1.3 and V2.0)
- Three general purpose 16-bit counter/timers
- Programmable 16-bit counter/timer array with three capture/compare modules, WDT

#### **Clock Sources**

- Internal oscillators: 24.5 MHz ±0.5% accuracy supports UART and LIN-Master operation
- External oscillator: Crystal, RC, C, or Clock (1 or 2 pin modes)
- Can switch between clock sources on-the-fly **Packages:**
- 10-Pin DFN (3 x 3 mm)
- 20-pin QFN (4 x 4 mm)
- 20-pin TSSOP

Temperature Range: -40 to +125 °C



NOTES:



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### 1. System Overview

The C8051F52x/52xA/53x/53xA family of devices are fully integrated, low power, mixed-signal system-ona-chip MCUs. Highlighted features are listed below. Refer to Table 1.1 for specific product feature selection.

- High-speed pipelined 8051-compatible microcontroller core (up to 25 MIPS)
- In-system, full-speed, non-intrusive debug interface (on-chip)
- True 12-bit 200 ksps ADC with analog multiplexer and up to 16 analog inputs
- Precision programmable 24.5 MHz internal oscillator that is ±0.5% across voltage and temperature
- Up to 7680 bytes of on-chip Flash memory
- 256 bytes of on-chip RAM
- Enhanced UART, and SPI serial interfaces implemented in hardware
- LIN 2.0 peripheral (V2.0 and V1.3 compatible, master and slave modes)
- Three general-purpose 16-bit timers
- Programmable Counter/Timer Array (PCA) with three capture/compare modules and Watchdog Timer function
- On-chip Power-On Reset, V<sub>DD</sub> Monitor, and Temperature Sensor
- On-chip Voltage Comparator
- Up to 16 Port I/O

With on-chip Power-On Reset,  $V_{DD}$  monitor, Watchdog Timer, and clock oscillator, the C8051F52x/52xA/53x/53xA devices are truly standalone system-on-a-chip solutions. The Flash memory is byte writable and can be reprogrammed in-circuit, providing non-volatile data storage, and also allowing field upgrades of the 8051 firmware. User software has complete control of all peripherals, and may individually shut down any or all peripherals for power savings.

The on-chip Silicon Laboratories 2-Wire (C2) Development Interface allows non-intrusive (uses no on-chip resources), full speed, in-circuit debugging using the production MCU installed in the final application. This debug logic supports inspection and modification of memory and registers, setting breakpoints, single stepping, run and halt commands. All analog and digital peripherals are fully functional while debugging using C2. The two C2 interface pins can be shared with user functions, allowing in-system programming and debugging without occupying package pins.

Each device is specified for 1.8 to 5.25 V operation (supply voltage can be up to 5.25 V using on-chip regulator) over the automotive temperature range (-40 to +125 °C). The F52x/F52xA is available in the DFN10 (3 x 3 mm) package. The F53x/F53xA is available in the QFN20 (4 x 4 mm) or the TSSOP20 package.



Drdering Part Number Ordering Part Number	G MIPS (Peak)	ଇ Flash Memory	WY2 256	ດ ທີ Calibrated Internal 24.5 MHz Oscillator Tolerance	SPI	< UART	ພ Timers (16-bit)	Programmable 3 Channels Counter Array	ත Port I/Os	<ul> <li>12-bit ADC ±1 LSB INL</li> </ul>		Internal Voltage Reference	<ul> <li>Temperature Sensor</li> </ul>	Analog Comparator	<ul> <li>Recommended for New Designs</li> </ul>	ackage DFN-10
C8051F521A-IM	25	8 kB	256	0.5%	· •		3	· /	6	· ·		· ~	· /	· ~	· •	DFN-10
C8051F523A-IM	25	4 kB	256	0.5%	V	V	3	· √	6	~	$\checkmark$	~	~	~	~	DFN-10
C8051F524A-IM	25	4 kB	256	0.5%	~	$\checkmark$	3	~	6	~		~	$\checkmark$	~	~	DFN-10
C8051F526A-IM	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	6	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	DFN-10
C8051F527A-IM	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	~	6	$\checkmark$		$\checkmark$	$\checkmark$	~	$\checkmark$	DFN-10
C8051F530A-IM	25	8 kB	256	0.5%	~	~	3	~	16	~	~	~	$\checkmark$	~	~	QFN-20
C8051F531A-IM	25	8 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$		$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	QFN-20
C8051F533A-IM	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	QFN-20
C8051F534A-IM	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	QFN-20
C8051F536A-IM	25	2 kB	256	0.5%	~	~	3	$\checkmark$	16	$\checkmark$	~	$\checkmark$	$\checkmark$	~	$\checkmark$	QFN-20
C8051F537A-IM	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$		$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	QFN-20
C8051F530A-IT	25	8 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	$\checkmark$	V	$\checkmark$	$\checkmark$	$\checkmark$	TSSOP-20
C8051F531A-IT	25	8 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	TSSOP-20
C8051F533A-IT	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	TSSOP-20
C8051F534A-IT	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	TSSOP-20
C8051F536A-IT	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	TSSOP-20
C8051F537A-IT	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	_	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	TSSOP-20
C8051F520-IM	25	8 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	6	$\checkmark$	$\checkmark$	V	$\checkmark$	$\checkmark$	—	DFN-10
C8051F521-IM	25	8 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	6	$\checkmark$	_	$\checkmark$	$\checkmark$	$\checkmark$	_	DFN-10
C8051F523-IM	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	6	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	_	DFN-10
C8051F524-IM	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	6	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$	—	DFN-10
C8051F526-IM	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	6	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	—	DFN-10
C8051F527-IM	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	6	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$	—	DFN-10
C8051F530-IM	25	8 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	—	QFN-20

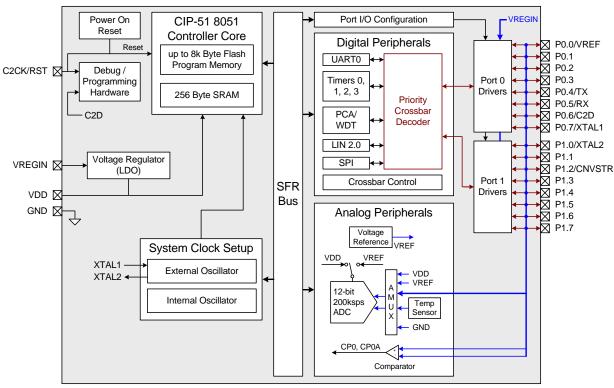
### Table 1.1. Product Selection Guide

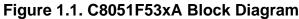


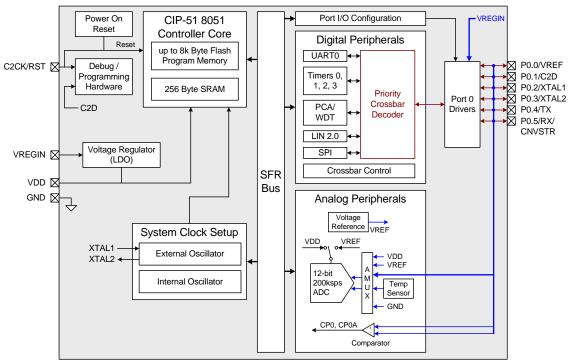
#### Table 1.1. Product Selection Guide

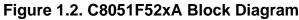
Ordering Part Number	MIPS (Peak)	Flash Memory	RAM	Calibrated Internal 24.5 MHz Oscillator Tolerance	SPI	UART	Timers (16-bit)	Programmable 3 Channels Counter Array	Port I/Os	12-bit ADC ±1 LSB INL	LIN	Internal Voltage Reference	Temperature Sensor	Analog Comparator	Recommended for New Designs	Package
C8051F531-IM	25	8 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	_	$\checkmark$	$\checkmark$	$\checkmark$		QFN-20
C8051F533-IM	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$		QFN-20
C8051F534-IM	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$	—	QFN-20
C8051F536-IM	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	—	QFN-20
C8051F537-IM	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$	—	QFN-20
C8051F530-IT	25	8 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	—	TSSOP-20
C8051F531-IT	25	8 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$		TSSOP-20
C8051F533-IT	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	—	TSSOP-20
C8051F534-IT	25	4 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	_	$\checkmark$	$\checkmark$	$\checkmark$	_	TSSOP-20
C8051F536-IT	25	2 kB	256	0.5%	~	~	3	$\checkmark$	16	~	$\checkmark$	~	$\checkmark$	$\checkmark$	—	TSSOP-20
C8051F537-IT	25	2 kB	256	0.5%	$\checkmark$	$\checkmark$	3	$\checkmark$	16	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$	—	TSSOP-20













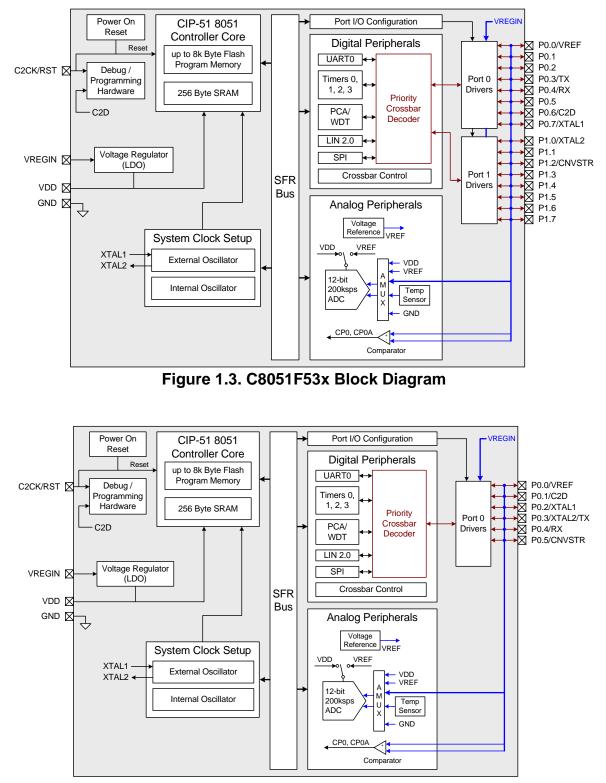


Figure 1.4. C8051F52x Block Diagram



### 1.1. CIP-51<sup>™</sup> Microcontroller

#### 1.1.1. Fully 8051 Compatible Instruction Set

The C8051F52x/52xA/53x/53xA devices use Silicon Laboratories' proprietary CIP-51 microcontroller core. The CIP-51 is fully compatible with the MCS-51<sup>™</sup> instruction set. Standard 803x/805x assemblers and compilers can be used to develop software. The C8051F52x/52xA/53x/53xA family has a superset of all the peripherals included with a standard 8052.

#### 1.1.2. Improved Throughput

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute, and usually have a maximum system clock of 12-to-24 MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with no instructions taking more than eight system clock cycles.

With the CIP-51's system clock running at 25 MHz, it has a peak throughput of 25 MIPS. The CIP-51 has a total of 109 instructions. The table below shows the total number of instructions that require each execution time..

Clocks to Execute	1	2	2/3	3	3/4	4	4/5	5	8
Number of Instructions	26	50	5	14	7	3	1	2	1

#### 1.1.3. Additional Features

The C8051F52x/52xA/53x/53xA family includes several key enhancements to the CIP-51 core and peripherals to improve performance and ease of use in end applications.

An extended interrupt handler allows the numerous analog and digital peripherals to operate independently of the controller core and interrupt the controller only when necessary. By requiring less intervention from the microcontroller core, an interrupt-driven system is more efficient and allows for easier implementation of multi-tasking, real-time systems.

Eight reset sources are available: power-on reset circuitry (POR), an on-chip  $V_{DD}$  monitor, a Watchdog Timer, a Missing Clock Detector, a voltage level detection from Comparator, a forced software reset, an external reset pin, and an illegal Flash access protection circuit. Each reset source except for the POR, Reset Input Pin, or Flash error may be disabled by the user in software. The WDT may be permanently enabled in software after a power-on reset during MCU initialization.

The internal oscillator is factory calibrated to 24.5 MHz  $\pm 0.5\%$  across the entire operating temperature and voltage range. An external oscillator drive circuit is also included, allowing an external crystal, ceramic resonator, capacitor, RC, or CMOS clock source to generate the system clock.

#### 1.1.4. On-Chip Debug Circuitry

The C8051F52x/52xA/53x/53xA devices include on-chip Silicon Laboratories 2-Wire (C2) debug circuitry that provides non-intrusive, full speed, in-circuit debugging of the production part *installed in the end application*.

Silicon Laboratories' debugging system supports inspection and modification of memory and registers, breakpoints, and single stepping. No additional target RAM, program memory, timers, or communications channels are required. All the digital and analog peripherals are functional and work correctly while debug-



ging. All the peripherals (except for the ADC) are stalled when the MCU is halted, during single stepping, or at a breakpoint in order to keep them synchronized.

The C8051F530A-DK development kit provides all the hardware and software necessary to develop application code and perform in-circuit debugging with the C8051F52x/52xA/53x/53xA MCUs. The kit includes software with a developer's studio and debugger, a USB debug adapter, a target application board with the associated MCU installed, and the required cables and wall-mount power supply. The development kit requires a computer with Windows installed. As shown in Figure 1.5, the PC is connected to the USB debug adapter. A six-inch ribbon cable connects the USB debug adapter to the user's application board, picking up the two C2 pins and GND.

The Silicon Laboratories IDE interface is a vastly superior developing and debugging configuration, compared to standard MCU emulators that use on-board "ICE Chips" and require the MCU in the application board to be socketed. Silicon Laboratories' debug paradigm increases ease of use and preserves the performance of the precision analog peripherals.

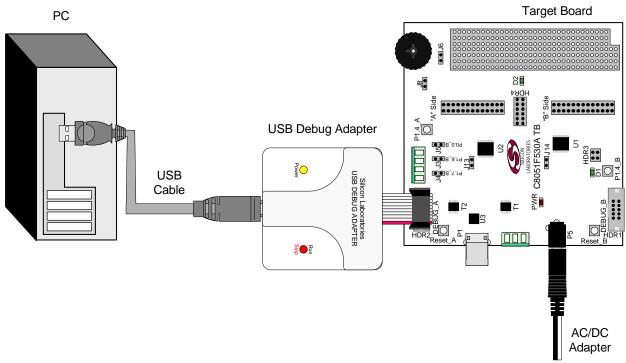


Figure 1.5. Development/In-System Debug Diagram



### 1.2. On-Chip Memory

The CIP-51 has a standard 8051 program and data address configuration. It includes 256 bytes of data RAM, with the upper 128 bytes dual-mapped. Indirect addressing accesses the upper 128 bytes of general purpose RAM, and direct addressing accesses the 128 byte SFR address space. The lower 128 bytes of RAM are accessible via direct and indirect addressing. The first 32 bytes are addressable as four banks of general purpose registers, and the next 16 bytes can be byte addressable or bit addressable.

Program memory consists of 7680 bytes ('F520/0A/1/1A and 'F530/0A/1/1A), 4 kB ('F523/3A/4/4A and C8051F53x/53xA), or 2 kB ('F526/6A/7/7A and 'F536/6A/7/7A) of Flash. This memory is byte writable and erased in 512-byte sectors, and requires no special off-chip programming voltage.

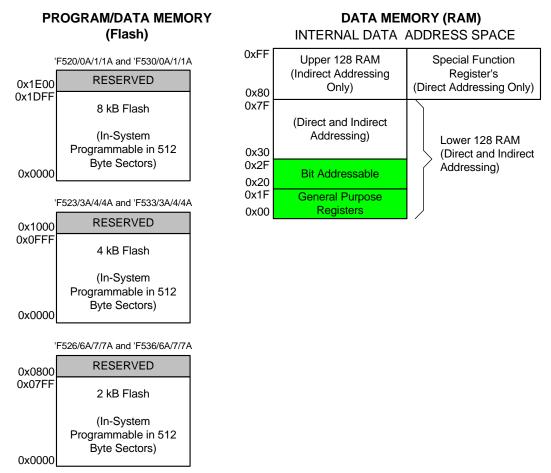


Figure 1.6. Memory Map



### 1.3. Operating Modes

The C8051F52x/52xA/53x/53xA devices have four operating modes: Active (Normal), Idle, Suspend, and Stop. Active mode occurs during normal operation when the oscillator and peripherals are active. Idle mode halts the CPU while leaving the peripherals and internal clocks active. In Suspend and Stop mode, the CPU is halted, all interrupts and timers are inactive, and the internal oscillator is stopped. The various operating modes are described in Table 1.2 below:

	Properties	Power Consumption	How Entered?	How Exited?
Active	<ul> <li>SYSCLK active</li> <li>CPU active (accessing Flash)</li> <li>Peripherals active or inactive depending on user settings</li> </ul>	Full	_	_
ldle	<ul> <li>SYSCLK active</li> <li>CPU inactive (not accessing Flash)</li> <li>Peripherals active or inactive depending on user settings</li> </ul>	Less than Full	IDLE (PCON.0)	Any enabled interrupt or device reset
Suspend	<ul> <li>Internal oscillator inactive</li> <li>If SYSCLK is derived from the internal oscillator, the peripher- als and the CIP-51 will be stopped</li> </ul>	Low	SUSPEND (OSCICN.5)	Port 0 event match Port 1 event match Comparator 0 enabled and output is logic '0'
Stop	<ul> <li>SYSCLK inactive</li> <li>CPU inactive (not accessing Flash)</li> <li>Digital peripherals inactive; ana- log peripherals active or inactive depending on user settings</li> </ul>	Very low	STOP (PCON.1)	Device Reset

See Section "9.3. Power Management Modes" on page 86 for Idle and Stop mode details. See Section "15.1.1. Internal Oscillator Suspend Mode" on page 136 for more information on Suspend mode.



### 1.4. 12-Bit Analog to Digital Converter

The C8051F52x/52xA/53x/53xA devices include an on-chip 12-bit SAR ADC with a maximum throughput of 200 ksps. The ADC system includes a configurable analog multiplexer that selects the positive ADC input, which is measured with respect to GND. Ports 0 and 1 are available as ADC inputs; additionally, the ADC includes an innovative programmable gain stage which allows the ADC to sample inputs sources greater than the VREF voltage. The on-chip Temperature Sensor output and the core supply voltage (V<sub>DD</sub>) are also available as ADC inputs. User firmware may shut down the ADC or use it in Burst Mode to save power.

Conversions can be initiated in four ways: a software command, an overflow of Timer 1, an overflow of Timer 2, or an external convert start signal. This flexibility allows the start of conversion to be triggered by software events, a periodic signal (timer overflows), or external HW signals. Conversion completions are indicated by a status bit and an interrupt (if enabled) and occur after 1, 4, 8, or 16 samples have been accumulated by a hardware accumulator. The resulting 12-bit to 16-bit data word is latched into the ADC data SFRs upon completion of a conversion. When the system clock is slow, Burst Mode allows ADC0 to automatically wake from a low power shutdown state, acquire and accumulate samples, then re-enter the low power shutdown state without CPU intervention.

Window compare registers for the ADC data can be configured to interrupt the controller when ADC data is either within or outside of a specified range. The ADC can monitor a key voltage continuously in background mode, but not interrupt the controller unless the converted data is within/outside the specified range.

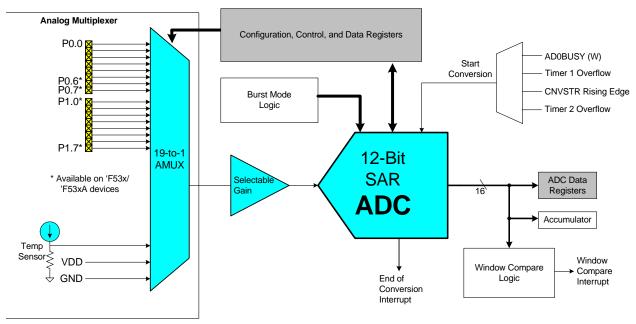


Figure 1.7. 12-Bit ADC Block Diagram



### 1.5. Programmable Comparator

C8051F52x/52xA/53x/53xA devices include a software-configurable voltage comparator with an input multiplexer. The comparator offers programmable response time and hysteresis and an output that is optionally available at the Port pins: a synchronous "latched" output (CP0). The comparator interrupt may be generated on rising, falling, or both edges. When in IDLE or SUSPEND mode, these interrupts may be used as a "wake-up" source for the processor. The Comparator may also be configured as a reset source. A block diagram of the comparator is shown in Figure 1.8.

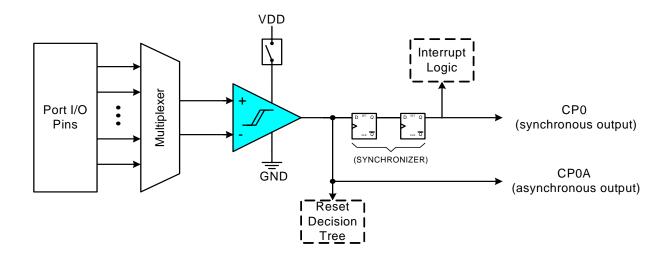


Figure 1.8. Comparator Block Diagram

#### 1.6. Voltage Regulator

C8051F52x/52xA/53x/53xA devices include an on-chip low dropout voltage regulator (REG0). The input to REG0 at the V<sub>REGIN</sub> pin can be as high as 5.25 V. The output can be selected by software to 2.1 or 2.6 V. When enabled, the output of REG0 powers the device and drives the V<sub>DD</sub> pin. The voltage regulator can be used to power external devices connected to V<sub>DD</sub>.

#### 1.7. Serial Port

The C8051F52x/52xA/53x/53xA family includes a full-duplex UART with enhanced baud rate configuration, and an Enhanced SPI interface. Each of the serial buses is fully implemented in hardware and makes extensive use of the CIP-51's interrupts, thus requiring very little CPU intervention.



### 1.8. Port Input/Output

C8051F52x/52xA/53x/53xA devices include up to 16 I/O pins. Port pins are organized as two byte-wide ports. The port pins behave like typical 8051 ports with a few enhancements. Each port pin can be configured as a digital or analog I/O pin. Pins selected as digital I/O can be configured for push-pull or open-drain operation. The "weak pullups" that are fixed on typical 8051 devices may be globally disabled to save power.

The Digital Crossbar allows mapping of internal digital system resources to port I/O pins. On-chip counter/timers, serial buses, hardware interrupts, and other digital signals can be configured to appear on the port pins using the Crossbar control registers. This allows the user to select the exact mix of general-purpose port I/O, digital, and analog resources needed for the application.

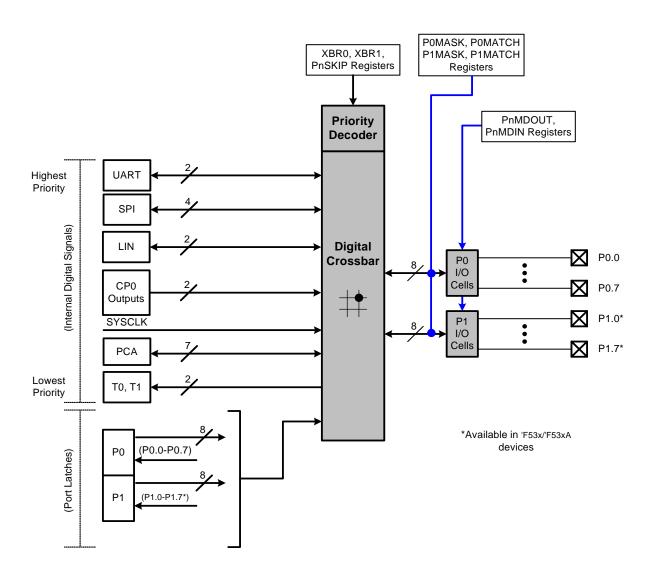


Figure 1.9. Port I/O Functional Block Diagram



### 2. Absolute Maximum Ratings

### Table 2.1. Absolute Maximum Ratings

Parameter	Conditions	Min	Тур	Max	Units				
Ambient temperature under bias		-55	—	135	°C				
Storage Temperature		-65	—	150	°C				
Voltage on V <sub>REGIN</sub> with respect to GND		-0.3		5.5	V				
Voltage on V <sub>DD</sub> with respect to GND		-0.3		2.8	V				
Voltage on XTAL1 with respect to GND		-0.3		V <sub>DD</sub> + 0.3	V				
Voltage on XTAL2 with respect to GND		-0.3		V <sub>DD</sub> + 0.3	V				
Voltage on any Port I/O Pin or $\overline{RST}$ with respect to GND		-0.3	—	$V_{REGIN} + 0.3$	V				
Maximum output current sunk by any Port pin			—	100	mA				
Maximum output current sourced by any Port pin			_	100	mA				
Maximum Total current through V <sub>REGIN</sub> , and GND — — 500 m/									
Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.									



### 3. Global DC Electrical Characteristics

### **Table 3.1. Global DC Electrical Characteristics**

-40 to +125 °C, 25 MHz System Clock unless otherwise specified. Typical values are given at 25 °C

Parameter	Conditions	Min.	Тур.	Max.	Units
Supply Input Voltage (V <sub>REGIN</sub> ) <sup>1</sup>	Output Current = 1 mA C8051F52x/53x C8051F52xA/53xA	2.7 1.8 <sup>1</sup>		5.25 5.25	V V
Digital Supply Voltage (V <sub>DD</sub> )	C8051F52x/53x C8051F52xA/53xA	2.0 1.8	_	2.7 2.7	V V
Core Supply RAM Data Retention Voltage		_	1.5	_	V
SYSCLK (System Clock) <sup>2</sup>		0		25	MHz
Specified Operating Temperature Range		-40		+125	°C
Digital Supply Current—CPU Active (I	Normal Mode, fetching instru	ctions f	rom Fla	sh)	1
I <sub>DD</sub> <sup>3</sup>	$V_{DD} = 2.1 V:$ Clock = 32 kHz Clock = 200 kHz Clock = 1 MHz Clock = 25 MHz $V_{DD} = 2.6 V:$ Clock = 32 kHz Clock = 200 kHz Clock = 1 MHz Clock = 25 MHz		13 40 0.25 9 21 100 0.45 11		μΑ μΑ mA μΑ μΑ mA
I <sub>DD</sub> Supply Sensitivity <sup>3</sup>	F = 25 MHz F = 1 MHz	_	TBD TBD	_	%/V %/V
I <sub>DD</sub> Frequency Sensitivity <sup>3,4</sup>	T = 25  °C: $V_{DD} = 2.1 \text{ V}, \text{ F} <= 15 \text{ MHz}$ $V_{DD} = 2.1 \text{ V}, \text{ F} > 15 \text{ MHz}$ $V_{DD} = 2.7 \text{ V}, \text{ F} <= 15 \text{ MHz}$ $V_{DD} = 2.7 \text{ V}, \text{ F} > 15 \text{ MHz}$	 	TBD TBD TBD TBD TBD	 	mA/MHz mA/MHz mA/MHz mA/MHz

#### Notes:

1. For more information on  $V_{\mbox{REGIN}}$  characteristics, see Table 7.1 on page 71.

2. SYSCLK must be at least 32 kHz to enable debugging.

3. Based on device characterization data; Not production tested.

4. I<sub>DD</sub> can be estimated for frequencies <= 15 MHz by multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate I<sub>DD</sub> > 15 MHz, the estimate should be the current at 25 MHz minus the difference in current indicated by the frequency sensitivity number. For example: V<sub>DD</sub> = 2.6 V; F = 20 MHz, I<sub>DD</sub> = 11 mA - (25 MHz - 20 MHz) \* TBD mA/MHz = TBD mA.

5. Idle  $I_{DD}$  can be estimated for frequencies <= 1 MHz by multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate  $I_{DD}$  > 1 MHz, the estimate should be the current at 25 MHz minus the difference in current indicated by the frequency sensitivity number. For example:  $V_{DD}$  = 2.6 V; F= 5 MHz, Idle  $I_{DD}$  = 4 mA - (25 MHz - 5 MHz) \* TBD mA/MHz = TBD mA.



### Table 3.1. Global DC Electrical Characteristics

-40 to +125 °C, 25 MHz System Clock unless otherwise specified. Typical values are given at 25 °C

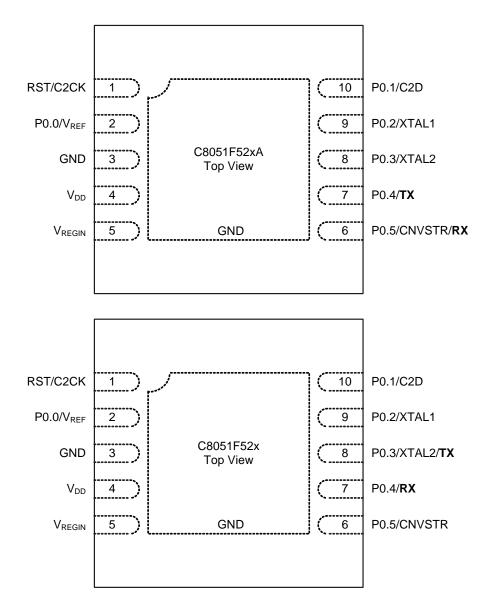
Parameter	Conditions	Min.	Тур.	Max.	Units				
Digital Supply Current—CPU Inactive	Idle Mode, not fetching instructions from Flash)								
Idle I <sub>DD</sub> <sup>3</sup>	V <sub>DD</sub> = 2.1 V: Clock = 32 kHz Clock = 200 kHz Clock = 1 MHz Clock = 25 MHz V <sub>DD</sub> = 2.6 V: Clock = 32 kHz Clock = 200 kHz Clock = 1 MHz Clock = 25 MHz		10 22 0.15 3 15 34 0.23 4		μΑ μΑ mA mA μΑ μΑ mA				
Idle I <sub>DD</sub> Supply Sensitivity <sup>3</sup>	F = 25 MHz F = 1 MHz		TBD TBD		%/V %/V				
Idle I <sub>DD</sub> Frequency Sensitivity <sup>3,5</sup>	T = 25 °C: $V_{DD}$ = 2.1 V, F <= 1 MHz $V_{DD}$ = 2.1 V, F > 1 MHz $V_{DD}$ = 2.7 V, F <= 1 MHz $V_{DD}$ = 2.7 V, F > 1 MHz		TBD TBD TBD TBD TBD		mA/MHz mA/MHz mA/MHz mA/MHz				
Digital Supply Current (Suspend Mode) <sup>2</sup>	Oscillator not running, V <sub>DD</sub> Monitor Disabled	_	2	_	μA				
Digital Supply Current (Stop Mode, shut- down)	Oscillator not running, V <sub>DD</sub> Monitor Disabled	_	2	_	μA				

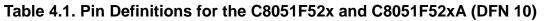
#### Notes:

- 1. For more information on  $V_{REGIN}$  characteristics, see Table 7.1 on page 71.
- 2. SYSCLK must be at least 32 kHz to enable debugging.
- 3. Based on device characterization data; Not production tested.
- 4. I<sub>DD</sub> can be estimated for frequencies <= 15 MHz by multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate I<sub>DD</sub> > 15 MHz, the estimate should be the current at 25 MHz minus the difference in current indicated by the frequency sensitivity number. For example: V<sub>DD</sub> = 2.6 V; F = 20 MHz, I<sub>DD</sub> = 11 mA (25 MHz 20 MHz) \* TBD mA/MHz = TBD mA.
- 5. Idle  $I_{DD}$  can be estimated for frequencies <= 1 MHz by multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate  $I_{DD} > 1$  MHz, the estimate should be the current at 25 MHz minus the difference in current indicated by the frequency sensitivity number. For example:  $V_{DD} = 2.6$  V; F= 5 MHz, Idle  $I_{DD} = 4$  mA (25 MHz 5 MHz) \* TBD mA/MHz = TBD mA.



### 4. Pinout and Package Definitions





Name	Pin Numbers		Туре	Description					
Name	ʻF52xA	'F52x	Type	beschption					
RST/	1	1		Device Reset. Open-drain output of internal POR or V <sub>DD</sub> monitor. An external source can initiate a system reset by driving this pin low for at least 15 $\mu$ s. A 1 k $\Omega$ pullup to V <sub>REGIN</sub> is recommended. See Reset Sources Section for a complete description.					
C2CK			D I/O	Clock signal for the C2 Debug Interface.					
*Note: Please refer to Section "21. Device Specific Behavior" on page 213.									



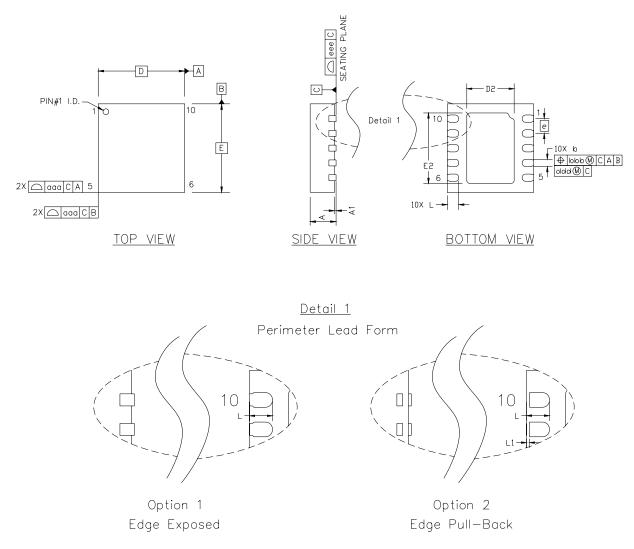
Nomo	Pin Nu	mbers	Turna	Description
Name	'F52xA	'F52x	Туре	Description
P0.0/			D I/O or A In	Port 0.0. See Port I/O Section for a complete description.
V <sub>REF</sub>	V <sub>REF</sub> 2 2		A O or D In	External V <sub>REF</sub> Input. See V <sub>REF</sub> Section.
GND	3	3		Ground.
V <sub>DD</sub>	4	4		Core Supply Voltage.
V <sub>REGIN</sub>	5	5		On-Chip Voltage Regulator Input.
P0.5/RX*/			D I/O or A In	Port 0.5. See Port I/O Section for a complete description.
CNVSTR	6	_	D In	External Converter start input for the ADC0, see Section "5. 12-Bit ADC (ADC0)" on page 47 for a complete description.
P0.5/		6	D I/O or A In	Port 0.5. See Port I/O Section for a complete description.
CNVSTR		0	D In	External Converter start input for the ADC0, see Section "5. 12-Bit ADC (ADC0)" on page 47 for a complete description.
P0.4/TX*	7	_	D I/O or A In	Port 0.4. See Port I/O Section for a complete description.
P0.4/RX*	_	7	D I/O or A In	Port 0.4. See Port I/O Section for a complete description.
P0.3			D I/O or A In	Port 0.3. See Port I/O Section for a complete description.
XTAL2	8	_	D I/O	External Clock Output. For an external crystal or resonator, this pin is the excitation driver. This pin is the external clock input for CMOS, capacitor, or RC oscillator configurations. See Section "15. Oscillators" on page 135.
P0.3/TX*/			D I/O or A In	Port 0.3. See Port I/O Section for a complete description.
XTAL2	_	8	D I/O	External Clock Output. For an external crystal or resonator, this pin is the excitation driver. This pin is the external clock input for CMOS, capacitor, or RC oscillator configurations. See Section "15. Oscillators" on page 135.
*Note: Please	e refer to S	Section	"21. Device	Specific Behavior" on page 213.



### Table 4.1. Pin Definitions for the C8051F52x and C8051F52xA (DFN 10) (Continued)

Name	Pin Nu	nbers	Туре	Description
Name	'F52xA	'F52x	Type	Description
P0.2			D I/O or	Port 0.2. See Port I/O Section for a complete description.
	9	9		
XTAL1			A In	External Clock Input. This pin is the external oscillator return for a crystal or resonator. Section "15. Oscillators" on page 135.
P0.1/			D I/O or A In	Port 0.1. See Port I/O Section for a complete description.
	10	10		
C2D			D I/O	Bi-directional data signal for the C2 Debug Interface
*Note: Please	e refer to S	Section	"21. Device	Specific Behavior" on page 213.





### Figure 4.1. DFN-10 Package Diagram\*

\*Note: The Package Dimensions are given in Table 4.2, "DFN-10 Package Diagram Dimensions," on page 34.



Dimension	Min	Nom	Max	
A	0.80	0.90	1.00	
A1	0.03	0.07	0.11	
b	0.18	0.25	0.30	
D		3.00 BSC.		
D2	1.50 1.65		1.80	
е	0.50 BSC.			
E	3.00 BSC.			
E2	2.23	2.38	2.53	
L	0.30	0.40	0.50	
L1	0.00	_	0.15	
aaa	—	_	0.15	
bbb	—	_	0.15	
ddd	—	_	0.05	
eee	—	_	0.08	
<ol> <li>Notes:         <ol> <li>All dimensions shown are in millimeters (mm) unless otherwise noted.</li> <li>Dimensioning and Tolerancing per ANSI Y14.5M-1994.</li> <li>This drawing conforms to JEDEC outline MO-243, variation VEED except for</li> </ol> </li> </ol>				

### Table 4.2. DFN-10 Package Diagram Dimensions

custom features D2, E2, L, and L1, which are toleranced per supplier designation.4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C

specification for Small Body Components.



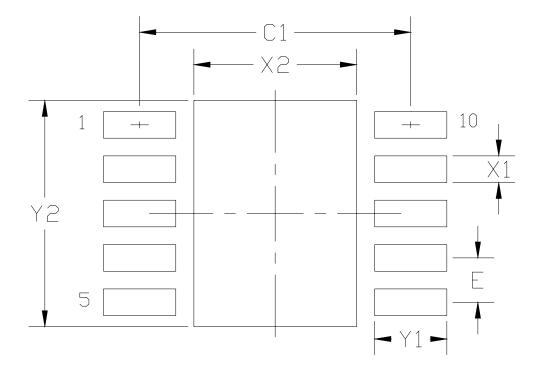


Figure 4.2. DFN-10 Landing Diagram

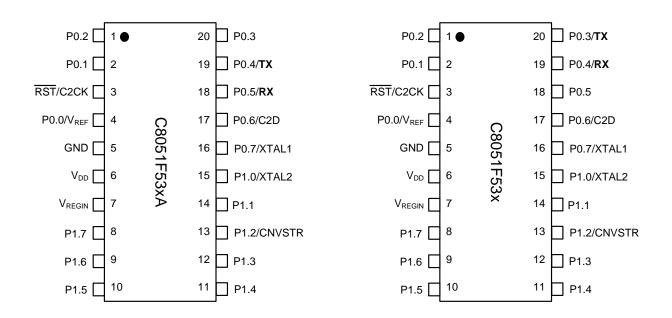
Dimension	Min	Max	
C1	2.90	3.00	
E	0.50 BSC.		
X1	0.20	0.30	
X2	1.70	1.80	
Y1	0.70	0.80	
Y2	2.45	2.55	
lotes:	hown are in millime	ters (mm) unless	

### Table 4.3. DFN-10 Landing Diagram Dimensions

otherwise noted. 2. This land pattern design is based on the IPC-7351

guidelines.





### Table 4.4. Pin Definitions for the C8051F53x and C805153xA (TSSOP 20)

Name	Pin Numbers		Type	Description	
Name	ʻF53xA	'F53x	Туре	Description	
P0.2	1	1	D I/O or A In	Port 0.2. See Port I/O Section for a complete description.	
P0.1	2	2	D I/O or A In	Port 0.1. See Port I/O Section for a complete description.	
RST/	3	3	D I/O	Device Reset. Open-drain output of internal POR or V <sub>DD</sub> monitor. An external source can initiate a system reset by driving this pin low for at least 15 $\mu$ s. A 1 k $\Omega$ pullup to V <sub>REGIN</sub> is recommended. See Reset Sources Section for a complete description.	
C2CK			D I/O	Clock signal for the C2 Debug Interface.	
P0.0/	4	4	D I/O or A In	Port 0.0. See Port I/O Section for a complete description.	
V <sub>REF</sub>		т	A O or D In	External V <sub>REF</sub> Input. See V <sub>REF</sub> Section.	
GND	5	5		Ground.	
V <sub>DD</sub>	6	6		Core Supply Voltage.	
V <sub>REGIN</sub>	7	7		On-Chip Voltage Regulator Input.	
P1.7	8	8	D I/O or A In	Port 1.7. See Port I/O Section for a complete description.	
*Note: Please	Note: Please refer to Section "21. Device Specific Behavior" on page 213.				



## Table 4.4. Pin Definitions for the C8051F53x and C805153xA (TSSOP 20)

Pin Numbers		Trues							
Name	ʻF53xA	'F53x	Туре	Description					
P1.6	9	9	D I/O or A In	Port 1.6. See Port I/O Section for a complete description.					
P1.5	10	10	D I/O or A In	Port 1.5. See Port I/O Section for a complete description.					
P1.4	11	11	D I/O or A In	Port 1.4. See Port I/O Section for a complete description.					
P1.3	12	12	D I/O or A In	Port 1.3. See Port I/O Section for a complete description.					
P1.2/			D I/O or A In	Port 1.2. See Port I/O Section for a complete description.					
CNVSTR	13	13	D In	External Converter start input for the ADC0, see Section "5. 12-Bit ADC (ADC0)" on page 47 for a complete description.					
P1.1	14	14	D I/O or A In	Port 1.1. See Port I/O Section for a complete description.					
P1.0/			D I/O or A In	Port 1.0. See Port I/O Section for a complete description.					
XTAL2	15	15	D I/O	External Clock Output. For an external crystal or resonator, this pin is the excitation driver. This pin is the external clock input for CMOS, capacitor, or RC oscillator configurations. See Section "15. Oscillators" on page 135.					
P0.7/	10	4.0	D I/O or A In	Port 0.7. See Port I/O Section for a complete description.					
XTAL1	16	16	A In	External Clock Input. This pin is the external oscillator return for a crystal or resonator. Section "15. Oscillators" on page 135.					
P0.6/	17	17	D I/O or A In	Port 0.6. See Port I/O Section for a complete description.					
C2D			D I/O	Bi-directional data signal for the C2 Debug Interface.					
P0.5/RX*	18	_	D I/O or A In	Port 0.5. See Port I/O Section for a complete description.					
P0.5	_	18	D I/O or A In	Port 0.5. See Port I/O Section for a complete description.					
P0.4/TX*	19	—	D I/O or A In	Port 0.4. See Port I/O Section for a complete description.					
P0.4/RX*	_	19	D I/O or A In	Port 0.4. See Port I/O Section for a complete description.					
*Note: Please	e refer to S	Section	"21. Device	Specific Behavior" on page 213.					



Name	Pin Nu	mbers	Type	Description						
Name	ʻF53xA	'F53x	Type	2-scription						
P0.3	20	_	D I/O or A In	Port 0.3. See Port I/O Section for a complete description.						
P0.3/TX*	_	20	D I/O or A In	Port 0.3. See Port I/O Section for a complete description.						
*Note: Please	e refer to S	Section	"21. Device	Specific Behavior" on page 213.						

## Table 4.4. Pin Definitions for the C8051F53x and C805153xA (TSSOP 20)



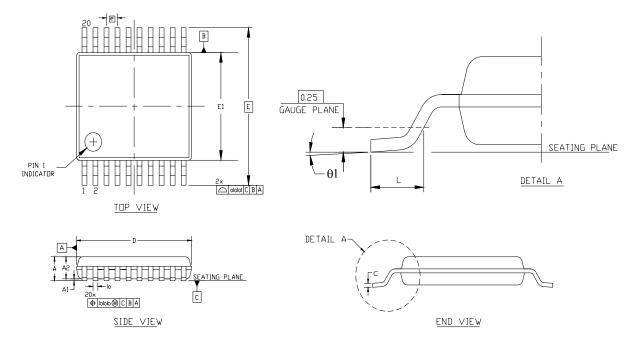


Figure 4.3. TSSOP-20 Package Diagram

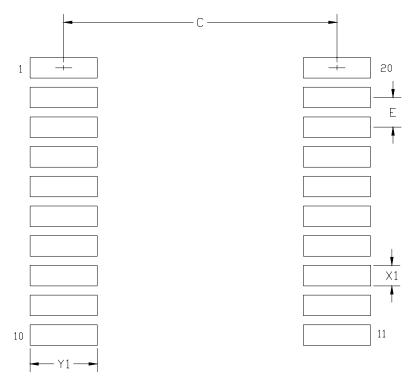
Symbol	Min	Nom	Max					
A			1.20					
A1	0.05	_	0.15					
A2	0.80	1.00	1.05					
b	0.19	_	0.30					
С	0.09	_	0.20					
D	6.40	6.50	6.60					
е	0.65 BSC.							
E		6.40 BSC.						
E1	4.30	4.40	4.50					
L	0.45	0.60	0.75					
θ1	0°	—	8°					
bbb		0.10						
ddd		0.20						
otes:								
1 All dimension	ons shown are in m	illimeters (mm)						

## Table 4.5. TSSOP-20 Package Diagram Dimensions

- 3. This drawing conforms to JEDEC outline MO-153, variation AC.
- 4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C
- specification for Small Body Components.



## C8051F52x/F52xA/F53x/F53xA

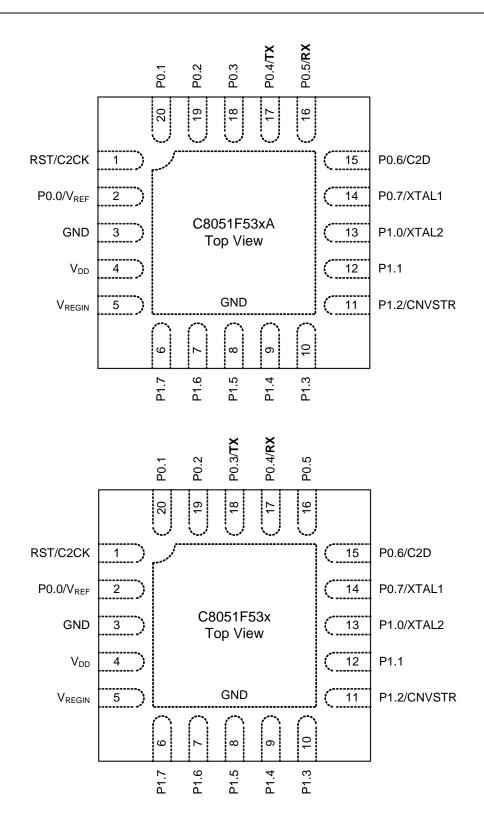


## Figure 4.4. TSSOP-20 Landing Diagram

Symbol	Min	Max							
С	5.80	5.90							
E	0.65 BSC.								
X1	0.35	0.45							
Y1	1.35	1.45							
<ul> <li>Notes:</li> <li>1. All dimensions shown are in millimeters (mm) unless otherwise noted.</li> <li>2. This land pattern design is based on the IPC-7351 guidelines.</li> </ul>									



## C8051F52x/F52xA/F53x/F53xA





## Table 4.7. Pin Definitions for the C8051F53x and C805153xA (QFN 20)

Nomo	Pin Numbers		Turno	Description					
Name	ʻF53xA	'F53x	Туре	Description					
RST/	1	1	D I/O	Device Reset. Open-drain output of internal POR or V <sub>DD</sub> monitor. An external source can initiate a system reset by driving this pin low for at least 15 $\mu$ s. A 1 k $\Omega$ pullup to V <sub>REGIN</sub> is recommended. See Reset Sources Section for a complete description.					
C2CK			D I/O	Clock signal for the C2 Debug Interface.					
P0.0/ V <sub>REF</sub>	2	2	D I/O or A In A O or D In	Port 0.0. See Port I/O Section for a complete description. External V <sub>REF</sub> Input. See V <sub>REF</sub> Section.					
GND	3	3		Ground.					
V <sub>DD</sub>	4	4		Core Supply Voltage.					
V <sub>REGIN</sub>	5	5		On-Chip Voltage Regulator Input.					
P1.7	6	6	D I/O or A In	Port 1.7. See Port I/O Section for a complete description.					
P1.6	7	7	D I/O or A In	Port 1.6. See Port I/O Section for a complete description.					
P1.5	8	8	D I/O or A In	Port 1.5. See Port I/O Section for a complete description.					
P1.4	9	9	D I/O or A In	Port 1.4. See Port I/O Section for a complete description.					
P1.3	10	10	D I/O or A In	Port 1.3. See Port I/O Section for a complete description.					
P1.2/ CNVSTR	11	11	D I/O or A In D In	Port 1.2. See Port I/O Section for a complete description. External Converter start input for the ADC0, see Section "5. 12-Bit ADC (ADC0)" on page 47 for a complete description.					
P1.1	12	12	D I/O or A In	Port 1.1. See Port I/O Section for a complete description.					
P1.0/ XTAL2	13	13	D I/O or A In D I/O	Port 1.0. See Port I/O Section for a complete description. External Clock Output. For an external crystal or resonator, this pin is the excitation driver. This pin is the external clock input for CMOS, capacitor, or RC oscillator configurations. Section					
*Note: Please	e refer to S	Section	"21. Device	"15. Oscillators" on page 135. Specific Behavior" on page 213.					



## C8051F52x/F52xA/F53x/F53xA

## Table 4.7. Pin Definitions for the C8051F53x and C805153xA (QFN 20) (Continued)

Namo	Name Pin Numbers		Туре	Description	
Name	ʻF53xA	'F53x	Type	Description	
P0.7/			D I/O or	Port 0.7. See Port I/O Section for a complete description.	
XTAL1	14	14	A In	External Clock Input. This pin is the external oscillator return for a crystal or resonator. See Oscillator Section.	
P0.6/	15	15	D I/O or A In	Port 0.6. See Port I/O Section for a complete description.	
C2D			D I/O	Bi-directional data signal for the C2 Debug Interface.	
P0.5/RX*	16	_	D I/O or A In	Port 0.5. See Port I/O Section for a complete description.	
P0.5	_	16	D I/O or A In	Port 0.5. See Port I/O Section for a complete description.	
P0.4/TX*	17		D I/O or A In	Port 0.4. See Port I/O Section for a complete description.	
P0.4/RX*	_	17	D I/O or A In	Port 0.4. See Port I/O Section for a complete description.	
P0.3	18		D I/O or A In	Port 0.3. See Port I/O Section for a complete description.	
P0.3/TX*	_	18	D I/O or A In	Port 0.3. See Port I/O Section for a complete description.	
P0.2	19	19	D I/O or A In	Port 0.2. See Port I/O Section for a complete description.	
P0.1	20	20	D I/O or A In	Port 0.1. See Port I/O Section for a complete description.	
*Note: Please	e refer to S	Section	"21. Device	Specific Behavior" on page 213.	



## C8051F52x/F52xA/F53x/F53xA

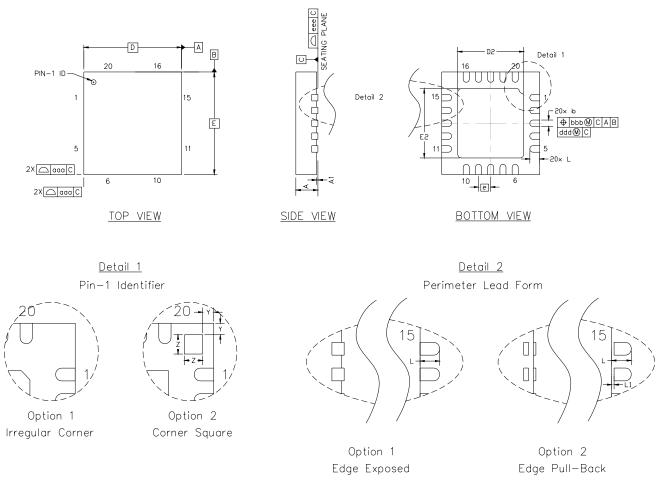


Figure 4.5. QFN-20 Package Diagram\*

\*Note: The Package Dimensions are given in Table 4.8, "QFN-20 Package Diagram Dimensions," on page 45.



г								
Dimension	MIN	NOM	MAX					
А	0.80	0.90	1.00					
A1	0.00	0.02	0.05					
b	0.18	0.18 0.25						
D		4.00 BSC.	1					
D2	2.55	2.55 2.70 2.8						
е	0.50 BSC.							
E	4.00 BSC.							
E2	2.55	2.70	2.85					
L	0.30	0.40	0.50					
L1	0.00		0.15					
aaa			0.15					
bbb			0.10					
ddd			0.05					
eee			0.08					
Z		0.43						
Y		0.18						

#### Table 4.8. QFN-20 Package Diagram Dimensions

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.

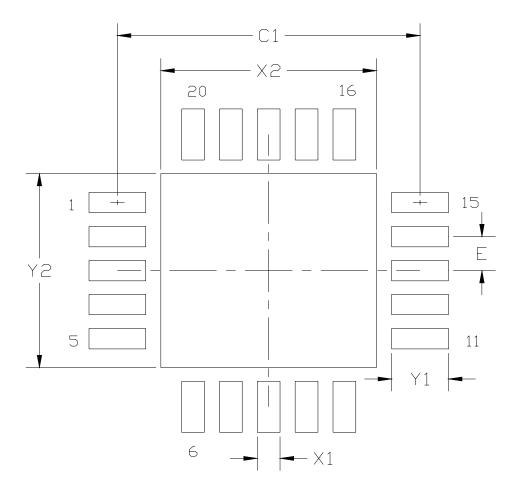
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

**3.** This drawing conforms to JEDEC outline MO-220, variation VGGD except for custom features D2, E2, Z, Y, L, and L1, which are toleranced per supplier designation.

**4.** Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.



## C8051F52x/F52xA/F53x/F53xA





## Table 4.9. QFN-20 Landing Diagram Dimensions

Symbol	Min	Max								
C1	3.90	4.00								
E	0.50 BSC.									
X1	0.20	0.30								
X2	2.75	2.85								
Y1	0.65	0.75								
Y2	2.75	2.85								
Notes:										
	<ol> <li>All dimensions shown are in millimeters (mm) unless otherwise noted.</li> </ol>									
	<ol> <li>This land pattern design is based on the IPC- 7351 guidelines.</li> </ol>									



## 5. 12-Bit ADC (ADC0)

The ADC0 on the C8051F52x/F52xA/F53x/F53xA Family consists of an analog multiplexer (AMUX0) with 16/6 total input selections, and a 200 ksps, 12-bit successive-approximation-register (SAR) ADC with integrated track-and-hold, programmable window detector, programmable gain, and hardware accumulator. The ADC0 subsystem has a special Burst Mode which can automatically enable ADC0, capture and accumulate samples, then place ADC0 in a low power shutdown mode without CPU intervention. The AMUX0, data conversion modes, and window detector are all configurable under software control via the Special Function Registers shown in Figure 5.1. ADC0 inputs are single-ended and may be configured to measure P0.0-P1.7, the Temperature Sensor output,  $V_{DD}$ , or GND with respect to GND. The voltage reference for the ADC is selected as described in Section "6. Voltage Reference" on page 67. ADC0 is enabled when the AD0EN bit in the ADC0 Control register (ADC0CN) is set to logic 1, or when performing conversions in Burst Mode. ADC0 is in low power shutdown when AD0EN is logic 0 and no Burst Mode conversions are taking place.

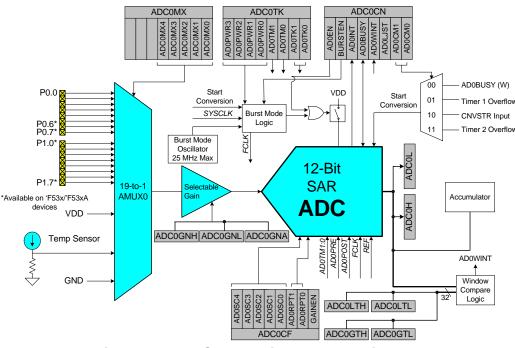


Figure 5.1. ADC0 Functional Block Diagram

### 5.1. Analog Multiplexer

AMUX0 selects the input channel to the ADC. Any of the following may be selected as an input: P0.0–P1.7, the on-chip temperature sensor, the core power supply ( $V_{DD}$ ), or ground (GND). **ADC0 is single-ended and all signals measured are with respect to GND.** The ADC0 input channels are selected using the ADC0MX register as described in SFR Definition 5.4.

**Important Note About ADC0 Input Configuration:** Port pins selected as ADC0 inputs should be configured as analog inputs, and should be skipped by the Digital Crossbar. To configure a Port pin for analog input, set to '0' the corresponding bit in register PnMDIN (for n = 0,1). To force the Crossbar to skip a Port pin, set to '1' the corresponding bit in register PnSKIP (for n = 0,1). See Section "14. Port Input/Output" on page 118 for more Port I/O configuration details.



### 5.2. Temperature Sensor

An on-chip temperature sensor is included on the C8051F52x/F52xA/F53x/F53xA devices which can be directly accessed via the ADC0 multiplexer. To use ADC0 to measure the temperature sensor, the ADC multiplexer channel should be configured to connect to the temperature sensor. The temperature sensor transfer function is shown in Figure 5.2. The output voltage ( $V_{TEMP}$ ) is the positive ADC input selected by bits AD0MX[4:0] in register ADC0MX. The TEMPE bit in register REF0CN enables/disables the temperature sensor defaults to a high impedance state and any ADC measurements performed on the sensor will result in meaningless data. Refer to Table 5.1 for the slope and offset parameters of the temperature sensor.

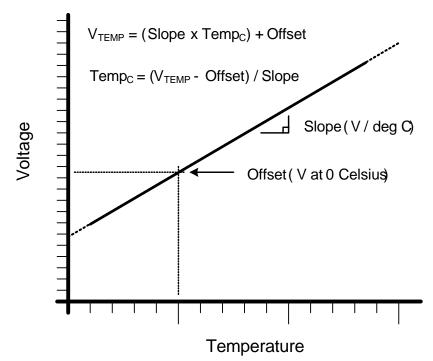


Figure 5.2. Typical Temperature Sensor Transfer Function



#### 5.3. ADC0 Operation

In a typical system, ADC0 is configured using the following steps:

- Step 1. If a gain adjustment is required, refer to Section "5.4. Selectable Gain" on page 54.
- Step 2. Choose the start of conversion source.
- Step 3. Choose Normal Mode or Burst Mode operation.
- Step 4. If Burst Mode, choose the ADC0 Idle Power State and set the Power-Up Time.
- Step 5. Choose the tracking mode. Note that Pre-Tracking Mode can only be used with Normal Mode.
- Step 6. Calculate required settling time and set the post convert-start tracking time using the AD0TK bits.
- Step 7. Choose the repeat count.
- Step 8. Choose the output word justification (Right-Justified or Left-Justified).
- Step 9. Enable or disable the End of Conversion and Window Comparator Interrupts.

#### 5.3.1. Starting a Conversion

A conversion can be initiated in one of four ways, depending on the programmed states of the ADC0 Start of Conversion Mode bits (AD0CM1–0) in register ADC0CN. Conversions may be initiated by one of the following:

•Writing a '1' to the AD0BUSY bit of register ADC0CN

- •A rising edge on the CNVSTR input signal (pin P0.6)
- •A Timer 1 overflow (i.e., timed continuous conversions)
- •A Timer 2 overflow (i.e., timed continuous conversions)

Writing a '1' to AD0BUSY provides software control of ADC0 whereby conversions are performed "ondemand." During conversion, the AD0BUSY bit is set to logic 1 and reset to logic 0 when the conversion is complete. The falling edge of AD0BUSY triggers an interrupt (when enabled) and sets the ADC0 interrupt flag (AD0INT). Note: When polling for ADC conversion completions, the ADC0 interrupt flag (AD0INT) should be used. Converted data is available in the ADC0 data registers, ADC0H:ADC0L, when bit AD0INT is logic 1. Note that when Timer 2 overflows are used as the conversion source, Low Byte overflows are used if Timer2 is in 8-bit mode; High byte overflows are used if Timer 2 is in 16-bit mode. See Section "19. Timers" on page 184 for timer configuration.

**Important Note:** The CNVSTR input pin also functions as Port pin P0.5 on C8051F52x/52xA devices and P1.2 on C8051F53x/53xA devices. When the CNVSTR input is used as the ADC0 conversion source, Port pin P0.5 or P1.2 should be skipped by the Digital Crossbar. To configure the Crossbar to skip P0.5 or P1.2, set to '1' to the appropriate bit in the PnSKIP register. See Section X on Page # for details on Port I/O configuration.

#### 5.3.2. Tracking Modes

Each ADC0 conversion must be preceded by a minimum tracking time for the converted result to be accurate, as shown in Table 5.1. ADC0 has three tracking modes: Pre-Tracking, Post-Tracking, and Dual-Tracking. Pre-Tracking Mode provides the minimum delay between the convert start signal and end of conversion by tracking continuously before the convert start signal. This mode requires software management in order to meet minimum tracking requirements. In Post-Tracking Mode, a programmable tracking time starts after the convert start signal and is managed by hardware. Dual-Tracking Mode maximizes tracking time by tracking before and after the convert start signal. Figure 5.3 shows examples of the three tracking modes.



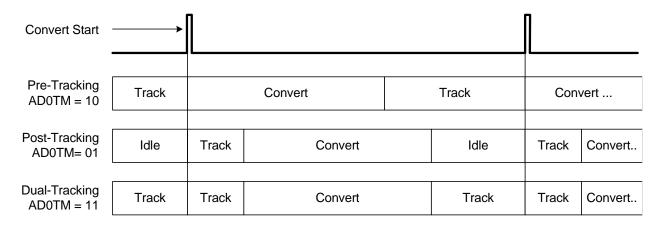
## C8051F52x/F52xA/F53x/F5

Pre-Tracking Mode is selected when AD0TM is set to 10b. Conversions are started immediately following the convert start signal. ADC0 is tracking continuously when not performing a conversion. Software must allow at least the minimum tracking time between each end of conversion and the next convert start signal. The minimum tracking time must also be met prior to the first convert start signal after ADC0 is enabled.

Post-Tracking Mode is selected when AD0TM is set to 01b. A programmable tracking time based on AD0TK is started immediately following the convert start signal. Conversions are started after the programmed tracking time ends. After a conversion is complete, ADC0 does not track the input. Rather, the sampling capacitor remains disconnected from the input making the input pin high-impedance until the next convert start signal.

Dual-Tracking Mode is selected when AD0TM is set to 11b. A programmable tracking time based on AD0TK is started immediately following the convert start signal. Conversions are started after the programmed tracking time ends. After a conversion is complete, ADC0 tracks continuously until the next conversion is started.

Depending on the output connected to the ADC input, additional tracking time, more than is specified in Table 5.1, may be required after changing MUX settings. See the settling time requirements described in Section "5.3.6. Settling Time Requirements" on page 54.



### Figure 5.3. ADC0 Tracking Modes

#### 5.3.3. Timing

ADC0 has a maximum conversion speed specified in Table 5.1. ADC0 is clocked from the ADC0 Subsystem Clock (FCLK). The source of FCLK is selected based on the BURSTEN bit. When BURSTEN is logic 0, FCLK is derived from the current system clock. When BURSTEN is logic 1, FCLK is derived from the Burst Mode Oscillator, an independent clock source with a maximum frequency of 25 MHz.

When ADC0 is performing a conversion, it requires a clock source that is typically slower than FCLK. The ADC0 SAR conversion clock (SAR clock) is a divided version of FCLK. The divide ratio can be configured using the AD0SC bits in the ADC0CF register. The maximum SAR clock frequency is listed in Table 5.1.

ADC0 can be in one of three states at any given time: tracking, converting, or idle. Tracking time depends on the tracking mode selected. For Pre-Tracking Mode, tracking is managed by software and ADC0 starts conversions immediately following the convert start signal. For Post-Tracking and Dual-Tracking Modes, the tracking time after the convert start signal is equal to the value determined by the AD0TK bits plus 2



FCLK cycles. Tracking is immediately followed by a conversion. The ADC0 conversion time is always 13 SAR clock cycles plus an additional 2 FCLK cycles to start and complete a conversion. Figure 5.4 shows timing diagrams for a conversion in Pre-Tracking Mode and tracking plus conversion in Post-Tracking or Dual-Tracking Mode. In this example, repeat count is set to one.

Convert Start		
	Pre-Tracking Mode	
Time	F S1 S2 S12 S13 F	
ADC0 State	Convert	
AD0INT Flag		
Time	Post-Tracking or Dual-Tracking Modes (AD0TK = '00')         F       S1       S2       F       F       S1       S2        S12       S13       F	
ADC0 State	Track Convert	
AD0INT Flag		
	Key         F       Equal to one period of FCLK.         Sn       Each Sn is equal to one period of the SAR clock.	

Figure 5.4. 12-Bit ADC Tracking Mode Example



#### 5.3.4. Burst Mode

Burst Mode is a power saving feature that allows ADC0 to remain in a very low power state between conversions. When Burst Mode is enabled, ADC0 wakes from a very low power state, accumulates 1, 4, 8, or 16 samples using an internal Burst Mode clock (approximately 25 MHz), then re-enters a very low power state. Since the Burst Mode clock is independent of the system clock, ADC0 can perform multiple conversions then enter a very low power state within a single system clock cycle, even if the system clock is slow (e.g. 32.768 kHz), or suspended.

Burst Mode is enabled by setting BURSTEN to logic 1. When in Burst Mode, AD0EN controls the ADC0 idle power state (i.e. the state ADC0 enters when not tracking or performing conversions). If AD0EN is set to logic 0, ADC0 is powered down after each burst. If AD0EN is set to logic 1, ADC0 remains enabled after each burst. On each convert start signal, ADC0 is awakened from its Idle Power State. If ADC0 is powered down, it will automatically power up and wait the programmable Power-Up Time controlled by the AD0PWR bits. Otherwise, ADC0 will start tracking and converting immediately. Figure 5.5 shows an example of Burst Mode Operation with a slow system clock and a repeat count of 4.

Important Note: When Burst Mode is enabled, only Post-Tracking and Dual-Tracking modes can be used.

When Burst Mode is enabled, a single convert start will initiate a number of conversions equal to the repeat count. When Burst Mode is disabled, a convert start is required to initiate each conversion. In both modes, the ADC0 End of Conversion Interrupt Flag (AD0INT) will be set after "repeat count" conversions have been accumulated. Similarly, the Window Comparator will not compare the result to the greater-than and less-than registers until "repeat count" conversions have been accumulated.

**Note:** When using Burst Mode, care must be taken to issue a convert start signal no faster than once every four SYSCLK periods. This includes external convert start signals.

System Clock																ſ					
Convert Start	<b>`</b>																				
Post-Tracking AD0TM = 01 AD0EN = 0	Powered Down		owe and			т	С	т	С	Т	-	С	Т	С	Powe		owe and			Т	C
Dual-Tracking AD0TM = 11 AD0EN = 0	Powered Down		owe nd T			т	С	Т	С	Т	-	С	Т	С	Powe	Power-U and Trac				Т	C
		►A	DOF	۶W	/ R ≯	-															
Post-Tracking AD0TM = 01 AD0EN = 1	Idle	т	С	Т	С	Т	С	Т	С						ldle	т	С	Т	С	т	С
Dual-Tracking AD0TM = 11 AD0EN = 1	Track	т	С	Т	С	т	С	т	С						Track	 т	С	т	С	Т	C
	T = Tracking C = Converti																				

Figure 5.5. 12-Bit ADC Burst Mode Example with Repeat Count Set to 4



#### 5.3.5. Output Conversion Code

The registers ADC0H and ADC0L contain the high and low bytes of the output conversion code. When the repeat count is set to 1, conversion codes are represented in 12-bit unsigned integer format and the output conversion code is updated after each conversion. Inputs are measured from '0' to  $V_{REF} \times 4095/4096$ . Data can be right-justified or left-justified, depending on the setting of the AD0LJST bit (ADC0CN.2). Unused bits in the ADC0H and ADC0L registers are set to '0'. Example codes are shown below for both right-justified data.

Input Voltage	Right-Justified ADC0H:ADC0L (AD0LJST = 0)	Left-Justified ADC0H:ADC0L (AD0LJST = 1)
V <sub>REF</sub> x 4095/4096	0x0FFF	0xFFF0
V <sub>REF</sub> x 2048/4096	0x0800	0x8000
V <sub>REF</sub> x 2047/4096	0x07FF	0x7FF0
0	0x0000	0x0000

When the ADC0 Repeat Count is greater than 1, the output conversion code represents the accumulated result of the conversions performed and is updated after the last conversion in the series is finished. Sets of 4, 8, or 16 consecutive samples can be accumulated and represented in unsigned integer format. The repeat count can be selected using the AD0RPT bits in the ADC0CF register. The value must be right-justified (AD0LJST = "0"), and unused bits in the ADC0H and ADC0L registers are set to '0'. The following example shows right-justified codes for repeat counts greater than 1. Notice that accumulating  $2^n$  samples is equivalent to left-shifting by *n* bit positions when all samples returned from the ADC have the same value.

Input Voltage	Repeat Count = 4	Repeat Count = 8	Repeat Count = 16
V <sub>REF</sub> x 4095/4096	0x3FFC	0x7FF8	0xFFF0
V <sub>REF</sub> x 2048/4096	0x2000	0x4000	0x8000
V <sub>REF</sub> x 2047/4096	0x1FFC	0x3FF8	0x7FF0
0	0x0000	0x0000	0x0000



#### 5.3.6. Settling Time Requirements

A minimum tracking time is required before an accurate conversion can be performed. This tracking time is determined by the AMUX0 resistance, the ADC0 sampling capacitance, any external source resistance, and the accuracy required for the conversion.

Figure 5.6 shows the equivalent ADC0 input circuit. The required ADC0 settling time for a given settling accuracy (SA) may be approximated by Equation 5.1. See Table 5.1 for ADC0 minimum settling time requirements.

$$t = \ln\left(\frac{2^n}{SA}\right) \times R_{TOTAL} C_{SAMPLE}$$

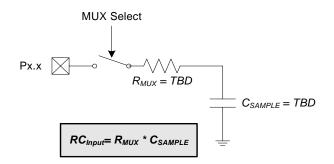
### **Equation 5.1. ADC0 Settling Time Requirements**

Where:

SA is the settling accuracy, given as a fraction of an LSB (for example, 0.25 to settle within 1/4 LSB) *t* is the required settling time in seconds

 $R_{TOTAL}$  is the sum of the AMUX0 resistance and any external source resistance.

*n* is the ADC resolution in bits (12).



### Figure 5.6. ADC0 Equivalent Input Circuits

#### 5.4. Selectable Gain

ADC0 on the C8051F52x/52xA/53x/53xA family of devices implements a selectable gain adjustment option. By writing a value to the gain adjust address range, the user can select gain values between 0 and 1.016.

For example, three analog sources to be measured have full-scale outputs of 5.0 V, 4.0 V, and 3.0 V, respectively. Each ADC measurement would ideally use the full dynamic range of the ADC with an internal voltage reference of 1.5 V or 2.2 V (set to 2.2 V for this example). When selecting signal one (5.0 V full-scale), a gain value of 0.44 (5 V full scale \* 0.44 = 2.2 V full scale) provides a full-scale signal of 2.2 V when the input signal is 5.0 V. Likewise, a gain value of 0.55 (4 V full scale \* 0.55 = 2.2 V full scale) for the second source and 0.73 (3 V full scale \* 0.73 = 2.2 V full scale) for the third source provide full-scale ADCO measurements when the input signal is full-scale.

Additionally, some sensors or other input sources have small part-to-part variations that must be accounted for to achieve accurate results. In this case, the programmable gain value could be used as a calibration value to eliminate these part-to-part variations.



#### 5.4.1. Calculating the Gain Value

The ADC0 selectable gain feature is controlled by 13 bits in three registers. ADC0GNH contains the 8 upper bits of the gain value and ADC0GNL contains the 4 lower bits of the gain value. The final GAINADD bit (ADC0GNA.0) controls an optional extra 1/64 (0.016) of gain that can be added in addition to the ADC0GNH and ADC0GNL gain. The ADC0GNA.0 bit is set to '1' after a power-on reset.

The equivalent gain for the ADC0GNH, ADC0GNL and ADC0GNA registers is:

$$gain = \left(\frac{GAIN}{4096}\right) + GAINADD \times \left(\frac{1}{64}\right)$$

#### Equation 5.2. Equivalent Gain from the ADC0GNH and ADC0GNL Registers

Where:

*GAIN* is the 12-bit word of ADC0GNH[7:0] and ADC0GNL[7:4] *GAINADD* is the value of the GAINADD bit (ADC0GNA.0) *gain* is the equivalent gain value from 0 to 1.016

For example, if ADC0GNH = 0xFC, ADC0GNL = 0x00, and GAINADD = '1', GAIN = 0xFC0 = 4032, and the resulting equation is:

$$gain = \left(\frac{4032}{4096}\right) + 1 \times \left(\frac{1}{64}\right) = 0.984 + 0.016 = 1.0$$

The table below equates values in the ADC0GNH, ADC0GNL, and ADC0GNA registers to the equivalent gain using this equation.

ADC0GNH Value	ADC0GNL Value	GAINADD Value	GAIN Value	Equivalent Gain
0xFC (default)	0x00 (default)	1 (default)	4032 + 64	1.0 (default)
0x7C	0x00	1	1984 + 64	0.5
0xBC	0x00	1	3008 + 64	0.75
0x3C	0x00	1	960 + 64	0.25
0xFF	0xF0	0	4095 + 0	~1.0
0xFC	0xF0	1	4096 + 64	1.016

For any desired gain value, the GAIN registers can be calculated by:

$$GAIN = \left(gain - GAINADD \times \left(\frac{1}{64}\right)\right) \times 4096$$

## Equation 5.3. Calculating the ADC0GNH and ADC0GNL Values from the Desired Gain



Where:

*GAIN* is the 12-bit word of ADC0GNH[7:0] and ADC0GNL[7:4] *GAINADD* is the value of the GAINADD bit (ADC0GNA.0) *gain* is the equivalent gain value from 0 to 1.016

When calculating the value of GAIN to load into the ADC0GNH and ADC0GNL registers, the GAINADD bit can be turned on or off to reach a value closer to the desired gain value.

For example, the initial example in this section requires a gain of 0.44 to convert 5 V full scale to 2.2 V full scale. Using Equation 5.3:

$$GAIN = \left(0.44 - GAINADD \times \left(\frac{1}{64}\right)\right) \times 4096$$

If GAINADD is set to '1', this makes the equation:

$$GAIN = \left(0.44 - 1 \times \left(\frac{1}{64}\right)\right) \times 4096 = 0.424 \times 4096 = 1738 = 0.06CA$$

The actual gain from setting GAINADD to '1' and ADC0GNH and ADC0GNL to 0x6CA is 0.4399. A similar gain can be achieved if GAINADD is set to '0' with a different value for ADC0GNH and ADC0GNL.

#### 5.4.2. Setting the Gain Value

The three programmable gain registers are accessed indirectly using the ADC0H and ADC0L registers when the GAINEN bit (ADC0CF.0) bit is set. ADC0H acts as the address register, and ADC0L is the data register. The programmable gain registers can only be written to and cannot be read. See Gain Register Definition 5.1, Gain Register Definition 5.2, and Gain Register Definition 5.3 for more information.

The gain is programmed using the following steps:

- Step 1. Set the GAINEN bit (ADC0CF.0)
- Step 2. Load the ADC0H with the ADC0GNH, ADC0GNL, or ADC0GNA address.
- Step 3. Load ADC0L with the desired value for the selected gain register.
- Step 4. Reset the GAINEN bit (ADC0CF.0)

Notes:

- 1. An ADC conversion should not be performed while the GAINEN bit is set.
- 2. Even with gain enabled, the maximum input voltage must be less than  $V_{REGIN}$  and the maximum voltage of the signal after gain must be less than or equal to  $V_{REF}$ .

In code, changing the value to 0.44 gain from the previous example looks like:

```
// in `C':
ADC0CF |= 0x01; // GAINEN = `1'
ADC0H = 0x04; // Load the ADC0GNH address
ADC0L = 0x6C; // Load the upper byte of 0x6CA to ADC0GNH
ADC0H = 0x07; // Load the ADC0GNL address
ADC0L = 0xA0; // Load the lower nibble of 0x6CA to ADC0GNL
ADC0H = 0x08; // Load the ADC0GNA address
ADC0L = 0x01; // Set the GAINADD bit
```



ADC0CF &= ~0x01; // G	
MOV ADC0H,#04H       ; Lo         MOV ADC0L,#06CH       ; Lo         MOV ADC0L,#07H       ; Lo         MOV ADC0L,#00H       ; Lo         MOV ADC0L,#08H       ; Lo         MOV ADC0L,#01H       ; Se	INEN = `1' ad the ADCOGNH address ad the upper byte of 0x6CA to ADCOGNH ad the ADCOGNL address ad the lower nibble of 0x6CA to ADCOGNL ad the ADCOGNA address t the GAINADD bit INEN = `0'

#### Gain Register Definition 5.1. ADC0GNH: ADC0 Selectable Gain High Byte

_	R/W	R/W	R/W	R/W GAINI	R/W	R/W	R/W	R/W	Reset Value		
	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Address: 0x04		
E	<b>Bits7–0</b> : High byte of Selectable Gain Word.										
		0 ,									

### Gain Register Definition 5.2. ADC0GNL: ADC0 Selectable Gain Low Byte

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
	GAINI	_[3:0]		Reserved	Reserved	Reserved	Reserved	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Address:
								0x07
	Lower 4 bits Reserved. N			in Word.				

## Gain Register Definition 5.3. ADC0GNA: ADC0 Additional Selectable Gain

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	GAINADD	0000001
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Address:
								0x08
Bit0: C	Reserved. I GAINADD: Setting this registers.	Additional	Gain Bit.	gain to the g	gain value i	n the ADC0	)GNH and <i>i</i>	ADCOGNL



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## SFR Definition 5.4. ADC0MX: ADC0 Channel Select

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	-			AD0MX			00011111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address
								0xBB
ito7 E			a. Write a	lon't coro				
	UNUSED. R AD0MX4-0:							
JII3 <del>4</del> -0.			Usitive inpt					
	AD0MX	4–0	AD	C0 Input C	hannel			
	0000			P0.0				
	0000			P0.1				
	0001			P0.2				
	0001		P0.3					
	0010			P0.4				
	0010		P0.5					
	0011			P0.6*				
	0011			P0.7*				
	0100			P1.0*				
	0100			P1.1*				
	0101			P1.2*				
	0101			P1.3*				
	0110			P1.4*				
	0110			P1.5*				
	0111			P1.6*				
	0111			P1.7*				
	1100			Temp Sen	sor			
	1100			V <sub>DD</sub>				
	11010 - 1	11111		GND				



## SFR Definition 5.5. ADC0CF: ADC0 Configuration

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
		AD0SC			AD0		GAINEN	11111000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xBC
Bits7–3:	AD0SC4-0: SAR Converto the 5-bit v Table 5.1. BURSTEN = BURSTEN = AD0SC =	rsion clock is ralue held in = 0: FCLK is = 1: FCLK is $\frac{FCLK}{CLK_{SAR}}$	derived fro bits ADOS the curren a maximui - 1 * c	om FCLK by C4–0. SAR t system clo m of 25 MH	y the followin Conversior ock.	ent of the c	irements ar	e given in
Bits2–1:	ADORPT1–C Controls the Conversion start is requi convert start accumulated than '00', th 00: 1 conver 01: 4 conver 10: 8 conver 11: 16 conver	number of o (ADCINT) and red for each that can initiate d in the ADC the AD0LJST resion is performed resions are per- resions are per-	conversion nd ADC0 V conversio multiple se 0H:ADC0L <b>bit in the</b> prmed. erformed an	s taken and Vindow Cor n unless Bu If-timed con register. <b>W</b> ADCOCN r nd accumul nd accumul	nparator (Al Irst Mode is nversions. F <b>/hen AD0R</b> egister mus ated. ated.	DCWINT) ir enabled. Ir Results in be <b>PT1–0 are</b>	nterrupts. A n Burst Mod oth modes a <b>set to a va</b>	convert le, a single are <b>lue other</b>
Bit0:	GAINEN: Ga Controls the chapter: Sec	gain progra	mming. Fo			ne usage, ro	efer to the f	ollowing

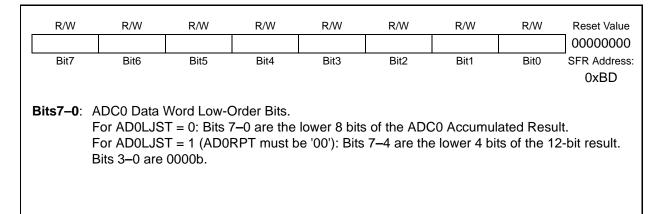


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### SFR Definition 5.6. ADC0H: ADC0 Data Word MSB

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value 0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xBE
	ADC0 Data \ For AD0LJS 00: Bits 3–0 01: Bits 4–0 10: Bits 5–0 11: Bits 7–0 For AD0LJS 12-bit result.	T = 0 and A are the upp are the upp are the upp are the upp T = 1 (AD0I	DORPT as ber 4 bits of ber 5 bits of ber 6 bits of er 8 bits of	the 12-bit re the 14-bit re the 15-bit re the 16-bit re	esult. Bits 7 esult. Bits 7 esult.	–5 are 000k –6 are 00b.	Э.	of the ADC0

### SFR Definition 5.7. ADC0L: ADC0 Data Word LSB





### SFR Definition 5.8. ADC0CN: ADC0 Control

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value					
ADOEN		ADOINT	ADOBUSY		ADOLJST	AD0CM1	AD0CM0	00000000					
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:					
2	2.10	2.10	2	2.10	2.12		t addressable)						
						(5)		0XE0					
Bit7:	ADOEN: ADO	C0 Enable	Bit.										
	0: ADC0 Disa	abled. ADC	CO is in low-	power shute	down.								
	1: ADC0 Enabled. ADC0 is active and ready for data conversions.												
Bit6:	BURSTEN: A												
	0: ADC0 Bur	st Mode D	isabled.										
	1: ADC0 Bur	st Mode E	nabled.										
Bit5:	ADOINT: ADO		•		•								
	0: ADC0 has	•			since the la	ast time AD	DINT was cl	eared.					
	1: ADC0 has			version.									
Bit4:	AD0BUSY: A	ADC0 Busy	/ Bit.										
	Read:		• .										
	0: ADC0 con				on is not cu	rrently in pro	ogress. AD	JINT is set					
	to logic 1 on												
	1: ADC0 con Write:	version is	in progress.										
	0: No Effect.												
	1: Initiates Al		arsion if AD	$0 \le M \le 1 = 0 = 0$	)0h								
Bit3:	ADOWINT: A												
5.00.	This bit must				lug.								
	0: ADC0 Win				not occurre	ed since this	s flag was la	ast cleared.					
	1: ADC0 Win						5						
Bit2:	ADOLJST: A												
	0: Data in AD	COH:ADC	0L registers	s is right just	tified.								
	1: Data in AD	DC0H:ADC	0L registers	s is left justif	ied. This op	otion should	not be use	d with a					
	repeat count	•	``			)b, or 11b).							
Bits1-0:	AD0CM1-0:												
	00: ADC0 co					BUSY.							
	01: ADC0 co												
	10: ADC0 co					INVSTR.							
	11: ADC0 co	nversion ir	intiated on o	vertiow of 1	imer 2.								



### SFR Definition 5.9. ADC0TK: ADC0 Tracking Mode Select

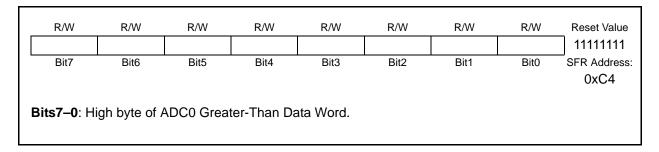
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
	AD0F	WR		AD	0TM	AD	0TK	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
						(bi	t addressable	) 0xBA
Bits7–4:	ADOPWR3-0 For BURSTE ADC0 power For BURSTE ADC0 remain For BURSTE ADC0 enters convert start ADOPWR =	N = 0: state contr N = 1 and s enabled N = 1 and the very lossignal. The	rolled by AE AD0EN = 1 and does r AD0EN = 0 w power st Power Up	DOEN. ; iot enter the : ate as spec time is proc	cified in Tabl grammed ac	e 5.1 and is cording to t	he followin	
	AD0TM1–0: 00: Reserved 01: ADC0 is of 10: ADC0 is of 11: ADC0 is of AD0TK1–0: ./ Post-Tracking 00: Post-Tracking 01: Post-Tracking 10: Post-Tracking 11: Post-Tracking	I. configured configured configured ADC0 Post g time is co cking time i cking time i cking time i	to Post-Trac to Pre-Trac to Dual-Tra -Track Time ontrolled by s equal to 2 s equal to 2 s equal to 2	cking Mode king Mode cking Mode a. AD0TK as SAR clock SAR clock SAR clock	e. (default). follows: cycles + 2 cycles + 2 cycles + 2	FCLK cycle FCLK cycle	es. es.	

#### 5.5. Programmable Window Detector

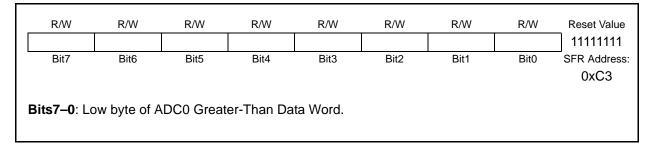
The ADC Programmable Window Detector continuously compares the ADC0 output registers to user-programmed limits, and notifies the system when a desired condition is detected. This is especially effective in an interrupt-driven system, saving code space and CPU bandwidth while delivering faster system response times. The window detector interrupt flag (AD0WINT in register ADC0CN) can also be used in polled mode. The ADC0 Greater-Than (ADC0GTH, ADC0GTL) and Less-Than (ADC0LTH, ADC0LTL) registers hold the comparison values. The window detector flag can be programmed to indicate when measured data is inside or outside of the user-programmed limits, depending on the contents of the ADC0 Less-Than and ADC0 Greater-Than registers.



## SFR Definition 5.10. ADC0GTH: ADC0 Greater-Than Data High Byte



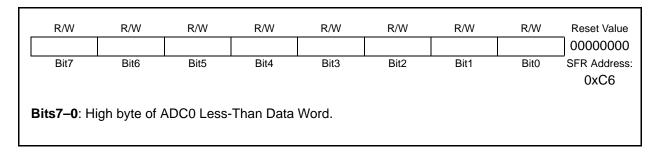
## SFR Definition 5.11. ADC0GTL: ADC0 Greater-Than Data Low Byte



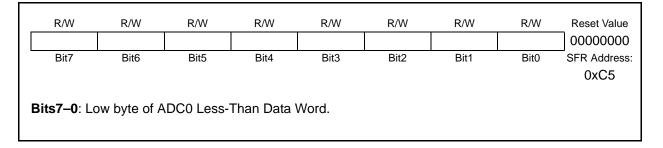


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## SFR Definition 5.12. ADC0LTH: ADC0 Less-Than Data High Byte



## SFR Definition 5.13. ADC0LTL: ADC0 Less-Than Data Low Byte





#### 5.5.1. Window Detector In Single-Ended Mode

Figure 5.7 shows two example window comparisons for right-justified with data ADC0LTH:ADC0LTL = 0x0200 (512d) and ADC0GTH:ADC0GTL = 0x0100 (256d). The input voltage can range from '0' to V<sub>REF</sub> x (4095/4096) with respect to GND, and is represented by a 12-bit unsigned integer value. The repeat count is set to one. In the left example, an AD0WINT interrupt will be generated if the ADC0 conversion word (ADC0H:ADC0L) is within the range defined by ADC0GTH:ADC0GTL and ADC0LTH:ADC0LTL (if 0x0100 < ADC0H:ADC0L < 0x0200). In the right example, and AD0WINT interrupt will be generated if the ADC0 conversion word is outside of the range defined by the ADC0GT and ADC0LT registers (if ADC0H:ADC0L < 0x0100 or ADC0H:ADC0L > 0x0200). Figure 5.8 shows an example using left-justified data with the same comparison values.

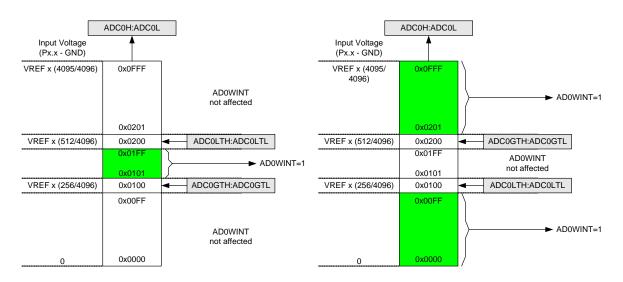


Figure 5.7. ADC Window Compare Example: Right-Justified Single-Ended Data

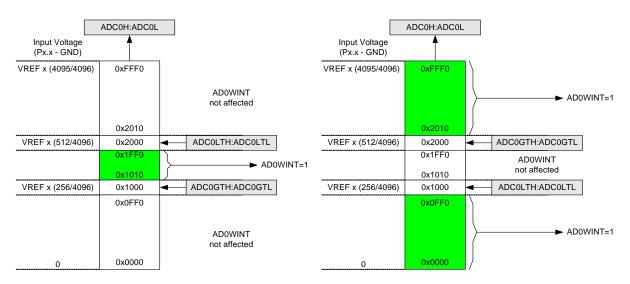


Figure 5.8. ADC Window Compare Example: Left-Justified Single-Ended Data



#### **Table 5.1. ADC0 Electrical Characteristics**

 $V_{DD}$  = 2.1 V,  $V_{REF}$  = 1.5 V (REFSL=0), –40 to +125 °C unless otherwise specified.

Guaranteed Monotonic	· 	12		bits
Guaranteed Monotonic		12		hite
Guaranteed Monotonic	—			0115
Guaranteed Monotonic			±1	LSB
		—	±1	LSB
	-7	±1	+15	LSB
	-10	±1	+4	LSB
e-wave Single-ended input,	to 1 dB	below F	ull Scale,	200 ksps
	60	66	—	dB
Up to the 5 <sup>th</sup> harmonic	—	74	—	dB
	-	88	—	dB
	1	1	11	
	—		3	MHz
	—	13	—	clocks
	1		—	μs
	-		200	ksps
		1		
gain = 1.0 (default) gain = n	0 0	_	V <sub>REF</sub> V <sub>REF</sub> / n	V
	0	_	V <sub>REGIN</sub>	V
	-	12	—	pF
		1		
	—	0.1	—	°C
	—	2.84	—	mV/°C
	—	±100	—	μV/°C
(Temp = 25 °C)		890	—	mV
(Temp = 25 °C)	—	±15	—	mV
Operating Mode, 200 ksps	_	880	TBD	μA
	—	930		μA
	—	5		μs
	—	1	—	mV/V
	Up to the 5 <sup>th</sup> harmonic gain = 1.0 (default) gain = n (Temp = 25 °C) (Temp = 25 °C)	e-wave Single-ended input, 0 to 1 dB         60         Up to the 5 <sup>th</sup> harmonic         —         —         —         —         —         —         —         —         —         —         —         —         —         —         —         —         1         —         1         —         1         —         gain = 1.0 (default)         0         gain = n         0         —      <	e-wave Single-ended input, 0 to 1 dB below F         60       66         Up to the 5 <sup>th</sup> harmonic       —       74         —       88         —       —       88         —       —       13         1       —       —         gain = 1.0 (default)       0       —         gain = n       0       —         0       —       12         —       0.11       —         —       2.84       —         —       2.84       —         —       2.84       —         0       —       \$100         (Temp = 25 °C)       —       890         (Temp = 25 °C)       —       \$80         —       930       —         930       —       5	e-wave Single-ended input, 0 to 1 dB below Full Scale, 2         60       66       —         Up to the 5 <sup>th</sup> harmonic       —       74       —         —       88       —         —       88       —         —       —       3         —       13       —         1       —       —         1       —       —         2       —       200         gain = 1.0 (default)       0       —       VREF         gain = n       0       —       VREF         0       —       VREF       N         1       —       —       200         gain = n       0       —       VREF       N         0       —       VREF       N         12       —       N       N       N         12       —       12       —         12       —       12       —         13       —       12       —         14       0       —       12       —         15       —       890       —       13         16       =       880       TBD<

Notes:

1. An additional 2 FCLK cycles are required to start and complete a conversion.

2. Additional tracking time may be required depending on the output impedance connected to the ADC input. See Section "5.3.6. Settling Time Requirements" on page 54.

**3.** Represents one standard deviation from the mean.

4. Includes ADC offset, gain, and linearity variations.



## 6. Voltage Reference

The Voltage reference MUX on C8051F52x/52xA/F53x/53xA devices is configurable to use an externally connected voltage reference, the internal reference voltage generator, or the V<sub>DD</sub> power supply voltage (see Figure 6.1). The REFSL bit in the Reference Control register (REF0CN) selects the reference source. For an external source or the internal reference applied to the V<sub>REF</sub> pin, REFSL should be set to '0'. To use V<sub>DD</sub> as the reference source, REFSL should be set to '1'.

The BIASE bit enables the internal voltage bias generator, which is used by the ADC, Temperature Sensor, and internal oscillators. This bit is forced to logic 1 when any of the aforementioned peripherals are enabled. The bias generator may be enabled manually by writing a '1' to the BIASE bit in register REF0CN; see SFR Definition 6.1 for REF0CN register details. The electrical specifications for the voltage reference circuit are given in Table 6.1.

The internal voltage reference circuit consists of a temperature stable bandgap voltage reference generator and a gain-of-two output buffer amplifier. The output voltage is selectable between 1.5 V and 2.2 V. The internal voltage reference can be driven out on the  $V_{REF}$  pin by setting the REFBE bit in register REFOCN to a '1' (see Figure 6.1). The load seen by the  $V_{REF}$  pin must draw less than 200 µA to GND. When using the internal voltage reference, bypass capacitors of 0.1 µF and 4.7 µF are recommended from the  $V_{REF}$  pin to GND. If the internal reference is not used, the REFBE bit should be cleared to '0'. Electrical specifications for the internal voltage reference are given in Table 6.1.

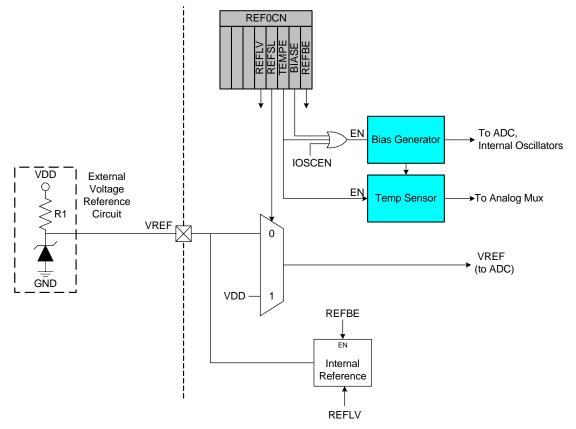


Figure 6.1. Voltage Reference Functional Block Diagram



**Important Note About the V<sub>REF</sub> Pin:** Port pin P0.0 is used as the external V<sub>REF</sub> input and as an output for the internal V<sub>REF</sub>. When using either an external voltage reference or the internal reference circuitry, P0.0 should be configured as an analog pin, and skipped by the Digital Crossbar. To configure P0.0 as an analog pin, clear Bit 0 in register P0MDIN to '0'. To configure the Crossbar to skip P0.0, set Bit 0 in register P0SKIP to '1'. Refer to Section "14. Port Input/Output" on page 118 for complete Port I/O configuration details.

The TEMPE bit in register REF0CN enables/disables the temperature sensor. While disabled, the temperature sensor defaults to a high impedance state and any ADC0 measurements performed on the sensor result in meaningless data.

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value	
Reserve	d Reserved	ZTCEN	REFLV	REFSL	TEMPE	BIASE	REFBE	00000000	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:	
								0xD1	
	RESERVED								
Bit5:	ZTCEN: Zero								
	0: ZeroTC Bias Generator automatically enabled when needed.								
	1: ZeroTC Bias Generator forced on.								
Bit4:	<b>REFLV</b> : Voltage Reference Output Level Select.								
	This bit selects the output voltage level for the internal voltage reference. 0: Internal voltage reference set to 1.5 V.								
		-							
Bit3:	1: Internal vo								
Dito.	<b>REFSL</b> : Voltage Reference Select. This bit selects the source for the internal voltage reference.								
	0: V <sub>REF</sub> pin used as voltage reference.								
	1: V <sub>DD</sub> used as voltage reference.								
Bit2:	<b>TEMPE</b> : Temperature Sensor Enable Bit.								
DILZ.	0: Internal Temperature Sensor off.								
	1: Internal Temperature Sensor on.								
Bit1:	BIASE: Internal Analog Bias Generator Enable Bit.								
	0: Internal Analog Bias Generator automatically enabled when needed.								
	1: Internal Analog Bias Generator on.								
Bit0:	REFBE: Internal Reference Buffer Enable Bit.								
	0: Internal R	eference B	uffer disable	ed.					
	1: Internal Reference Buffer enabled. Internal voltage reference driven on the $V_{REF}$ pin.							<sub>REF</sub> pin.	

## SFR Definition 6.1. REF0CN: Reference Control



# Table 6.1. Voltage Reference Electrical Characteristics $V_{DD} = 2.1 \text{ V}; -40 \text{ to } +125 \text{ °C}$ unless otherwise specified.

Parameter	Conditions	Min	Тур	Max	Units			
Internal Reference (REFBE = 1)								
Output Voltage	25 °C ambient (REFLV = 0) 25 °C ambient (REFLV = 1), V <sub>DD</sub> = 2.6 V	1.45 2.15	1.5 2.2	1.55 2.25	V			
V <sub>REF</sub> Short-Circuit Current			2.5		mA			
V <sub>REF</sub> Temperature Coefficient			33		ppm/°C			
Load Regulation	Load = 0 to 200 µA to GND	_	10	—	ppm/µA			
V <sub>REF</sub> Turn-on Time 1	4.7 $\mu$ F tantalum, 0.1 $\mu$ F ceramic bypass		2		ms			
V <sub>REF</sub> Turn-on Time 2	0.1 µF ceramic bypass		TBD		μs			
Power Supply Rejection			TBD		ppm/V			
External Reference (REFBE = 0)								
Input Voltage Range		0		V <sub>DD</sub>	V			
Input Current	Sample Rate = 200 ksps; V <sub>REF</sub> = 1.5 V		35		μA			
Bias Generators								
ADC Bias Generator	BIASE = '1'	—	30		μA			
Power Consumption (Internal)			35		μA			



## 7. Voltage Regulator (REG0)

C8051F52x/52xA/53x/53xA devices include an on-chip low dropout voltage regulator (REG0). The input to REG0 at the V<sub>REGIN</sub> pin can be as high as 5.25 V. The output can be selected by software to 2.1 V or 2.6 V. When enabled, the output of REG0 appears on the V<sub>DD</sub> pin, powers the microcontroller core, and can be used to power external devices. On reset, REG0 is enabled and can be disabled by software.

The input (V<sub>REGIN</sub>) and output (V<sub>DD</sub>) of the voltage regulator should both be bypassed with a large capacitor (4.7  $\mu$ F + 0.1  $\mu$ F) to ground. This capacitor will eliminate power spikes and provide any immediate power required by the microcontroller. The settling time associated with the voltage regulator is shown in Table 7.1.

The voltage regulator can also generate an interrupt (if enabled by EREG0, EIE1.6) that is triggered whenever the  $V_{\text{REGIN}}$  input voltage drops below the dropout threshold (see Table 7.1). This dropout interrupt has no pending flag. The recommended procedure to use the interrupt is as follows:

- Step 1. Wait enough time to ensure the V<sub>REGIN</sub> input voltage is stable.
- Step 2. Enable the dropout interrupt (EREG0, EIE1.6) and select the proper priority (PREG0, EIP1.6).
- Step 3. If triggered, disable the interrupt in the Interrupt Service Routine (clear EREG0, EIE1.6) and execute all necessary procedures to put the system in "safe mode," leaving the interrupt disabled.
- Step 4. The main application, now running in safe mode, should regularly check the DROPOUT bit (REG0CN.0). Once it is cleared by the regulator hardware, the application can reenable the interrupt (EREG0, EIE1.6) and return to normal mode operation.

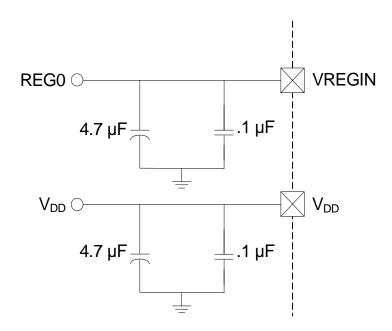


Figure 7.1. External Capacitors for Voltage Regulator Input/Output



### SFR Definition 7.1. REG0CN: Regulator Control

R/W	R/W	R	R/W	R	R	R	R	Reset Value		
REGDIS	S Reserved		REG0MD				DROPOUT	00010000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	-		
							SFR Address	0xC9		
Bit7:	REGDIS: Vo	ltage Regu	lator Disable	e Bit.						
	This bit disables/enables the Voltage Regulator.									
	0: Voltage Regulator Enabled.									
	1: Voltage Re	1: Voltage Regulator Disabled.								
Bit6:	RESERVED. Read = 0b. Must write 0b.									
Bit5:	<b>UNUSED</b> . Read = 0b. Write = don't care.									
Bit4:	REG0MD: Voltage Regulator Mode Select Bit.									
	This bit selects the Voltage Regulator output voltage.									
	0: Voltage Regulator output is 2.1 V.									
	1: Voltage Regulator output is 2.6 V (default).									
Bits3–1:	<b>UNUSED</b> . Read = 000b. Write = don't care.									
Bit0:	DROPOUT: Voltage Regulator Dropout Indicator Bit.									
	0: Voltage Regulator is not in dropout.									
	1: Voltage Regulator is in or near dropout.									
	-	-		-						

#### Table 7.1. Voltage Regulator Electrical Specifications

 $V_{DD}$  = 2.1 or 2.6 V; -40 to +125 °C unless otherwise specified.

Parameter	Conditions	Min	Тур	Max	Units	
	C8051F52x/53x C8051F52xA/53xA	2.7 <sup>1</sup>		5.25		
Input Voltage Range (V <sub>REGIN</sub> )	$V_{DD}$ connected to $V_{REGIN}$ $V_{DD}$ not connected to $V_{REGIN}$	1.8 2.2 <sup>2</sup>	_	2.7 5.25	V	
Dropout Voltage (V <sub>DO</sub> )	Output Current = 1-50 mA		10	TBD	mV/mA	
Output Voltage (V <sub>DD</sub> )	Output Current = 1 to 50 mA REG0MD = '0' REG0MD = '1'	2.0 2.5	2.1 2.6	2.2 2.7	V	
Bias Current	2.1 V operation (REG0MD = '0') 2.6 V operation (REG0MD = '1')	_	1 1	TBD TBD	μA	
Dropout Indicator Detection Threshold		_	65	_	mV	
Output Voltage Tempco		_	2	—	mV/ºC	
VREG Settling Time	50 mA load with $V_{REGIN} = 2.4$ V and $V_{DD}$ load capacitor of 4.8 $\mu$ F	_	250	_	μs	
<b>Notes:</b> <b>1.</b> The minimum input voltage is 2.7 V or $V_{DD}$ + $V_{DO}$ (max load), whichever is greater.						

1. The minimum input voltage is 2.7 V or  $V_{DD} + V_{DO}(max load)$ , whichever is greater. 2. The minimum input voltage is 2.2 V or  $V_{DD} + V_{DO}(max load)$ , whichever is greater.



## 8. Comparator

C8051F52x/52xA/53x/53xA devices include one on-chip programmable voltage comparator. The Comparator is shown in Figure 8.1.

The Comparator offers programmable response time and hysteresis, an analog input multiplexer, and two outputs that are optionally available at the Port pins: a synchronous "latched" output (CP0), or an asynchronous "raw" output (CP0A). The asynchronous CP0A signal is available even when the system clock is not active. This allows the Comparator to operate and generate an output with the device in STOP or SUS-PEND mode. When assigned to a Port pin, the Comparator output may be configured as open drain or push-pull (see Section "14.2. Port I/O Initialization" on page 125). The Comparator may also be used as a reset source (see Section "12.5. Comparator Reset" on page 106).

The Comparator inputs are selected in the CPT0MX register (SFR Definition 8.2). The CMX0P3–CMX0P0 bits select the Comparator0 positive input; the CMX0N3–CMX0N0 bits select the Comparator0 negative input.

**Important Note About Comparator Inputs:** The Port pins selected as Comparator inputs should be configured as analog inputs in their associated Port configuration register and configured to be skipped by the Crossbar (for details on Port configuration, see Section "14.3. General Purpose Port I/O" on page 127).

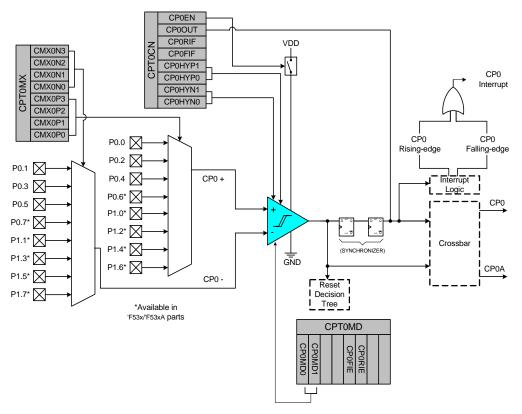


Figure 8.1. Comparator Functional Block Diagram

The Comparator output can be polled in software, used as an interrupt source, internal oscillator suspend awakening source and/or routed to a Port pin. When routed to a Port pin, the Comparator output is available asynchronous or synchronous to the system clock; the asynchronous output is available even in



STOP or SUSPEND mode (with no system clock active). When disabled, the Comparator output (if assigned to a Port I/O pin via the Crossbar) defaults to the logic low state, and its supply current falls to less than 100 nA. See Section "14.1. Priority Crossbar Decoder" on page 120 for details on configuring Comparator outputs via the digital Crossbar. Comparator inputs can be externally driven from -0.25 V to (V<sub>REGIN</sub>) + 0.25 V without damage or upset. The complete Comparator electrical specifications are given in Table 8.1.

The Comparator response time may be configured in software via the CPTnMD register (see SFR Definition 8.3). Selecting a longer response time reduces the Comparator supply current. See Table 8.1 for complete timing and current consumption specifications.

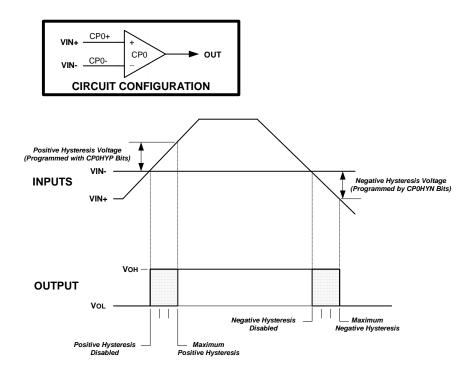


Figure 8.2. Comparator Hysteresis Plot

The Comparator hysteresis is software-programmable via its Comparator Control register CPT0CN. The user can program both the amount of hysteresis voltage (referred to the input voltage) and the positive and negative-going symmetry of this hysteresis around the threshold voltage.

The Comparator hysteresis is programmed using Bits3–0 in the Comparator Control Register CPT0CN (shown in SFR Definition 8.1). The amount of negative hysteresis voltage is determined by the settings of the CP0HYN bits. As shown in Table 8.1, settings of 20, 10 or 5 mV of negative hysteresis can be programmed, or negative hysteresis can be disabled. In a similar way, the amount of positive hysteresis is determined by the setting the CP0HYP bits.

Comparator interrupts can be generated on both rising-edge and falling-edge output transitions. (For Interrupt enable and priority control, see Section "11. Interrupt Handler" on page 95). The CP0FIF flag is set to logic 1 upon a Comparator falling-edge detect, and the CP0RIF flag is set to logic 1 upon the Comparator rising-edge detect. Once set, these bits remain set until cleared by software. The output state of the Com-



parator can be obtained at any time by reading the CP0OUT bit. The Comparator is enabled by setting the CP0EN bit to logic 1 and is disabled by clearing this bit to logic 0. When the Comparator is enabled, the internal oscillator is awakened from SUSPEND mode if the Comparator output is logic 0.

Note that false rising edges and falling edges can be detected when the comparator is first powered-on or if changes are made to the hysteresis or response time control bits. Therefore, it is recommended that the rising-edge and falling-edge flags be explicitly cleared to logic 0 a short time after the comparator is enabled or its mode bits have been changed. This Power Up Time is specified in Table 8.1 on page 77.

R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
CP0EN	CP0OUT	<b>CP0RIF</b>	CP0FIF	CP0HYP1	CP0HYP0	CP0HYN1	CP0HYN0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
			0x9B					
Bit7:	CP0EN: Cor	•						
	0: Comparat							
	1: Comparat							
Bit6:	CPOOUT: Co	•	•	ite Flag.				
	0: Voltage or							
D:46.	1: Voltage or							
Bit5:	CPORIF: Col				ainaa thia fla		alaarad	
	0: No Compa 1: Comparat				since this ha	ag was last	cleared.	
Bit4:	CP0FIF: Cor							
DIL4.	0: No Compa				since this fl	an was las	t cleared	
	1: Comparat					ug muo luo		
Bits3-2:	CP0HYP1-0	-	-		s Control Bit	s.		
	00: Positive	•		<b>,</b>				
	01: Positive	Hysteresis	= 5 mV.					
	10: Positive	Hysteresis	= 10 mV.					
	11: Positive I							
Bits1-0:	CP0HYN1-0			ve Hysteres	sis Control B	its.		
1	00: Negative							
	01: Negative							
	10: Negative							
	11: Negative	Hysteresis	= 20 mV.					

## SFR Definition 8.1. CPT0CN: Comparator0 Control



## SFR Definition 8.2. CPT0MX: Comparator0 MUX Selection

CMX0N3	R/W CMX0N2	R/W 2 CMX0N	R/W 1 CMX0N	R/W	R/W P3 CMX0P2	R/W CMX0P1	R/W CMX0P0	Reset Value
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address
Biti	Bito	DIG	Dit4	DIG	Ditz	DILI	Bito	0x9F
								0791
Rite7_4·	CMX0N3_	CMXONO.	Comparato	r0 Negative	e Input MUX Se	alact		
<b>710</b> 7 4.			•	•	the Comparato		input	
			ant ortpin		and Comparate	no nogative	, in pour	
	CMX0N3	CMX0N2	CMX0N1	CMX0N0	Negative Inp	out		
	0	0	0	0	P0.1			
	0	0	0	1	P0.3			
	0	0	1	0	P0.5			
	0	0	1	1	P0.7*			
	0	1	0	0	P1.1*			
			-	4	D4 0*			
	0	1	0	1	P1.3*			
	0	1 1	0	0	P1.5*			
	0 0 * <b>Note:</b> Avai	1 1 lable only or	1 1 n the C8051	0 1 F53x/53xA d	P1.5* P1.7* Vevices			
	0 0 *Note: Avai CMX0P3–( These bits	1 1 lable only or CMX0P0: ( select whice	1 1 Comparato Ch Port pin	0 1 F53x/53xA d r0 Positive is used as	P1.5* P1.7* <i>levices</i> Input MUX Sel the Comparato	or0 positive	input.	
	0 0 *Note: Avai CMX0P3–0 These bits CMX0P3	1 1 CMX0P0: ( select whice CMX0P2	1 1 Comparator Ch Port pin CMX0P1	0 1 F53x/53xA d r0 Positive is used as CMX0P0	P1.5* P1.7* levices Input MUX Sel the Comparato <b>Positive Inp</b>	or0 positive	input.	
	0 0 *Note: Avai CMX0P3–0 These bits CMX0P3 0	1 1 CMX0P0: C select whic CMX0P2 0	1 1 Comparator Comparator Ch Port pin CMX0P1 0	0 1 <i>F53x/53xA d</i> r0 Positive is used as <b>CMX0P0</b> 0	P1.5* P1.7* P1.7* Philosoft Positive Inp P0.0	or0 positive	input.	
	0 0 *Note: <i>Avai</i> CMX0P3-0 These bits CMX0P3 0 0	1 1 CMX0P0: C select white CMX0P2 0 0	1 1 Comparato Comparato Ch Port pin CMX0P1 0 0	0 1 <i>F53x/53xA d</i> r0 Positive is used as <b>CMX0P0</b> 0 1	P1.5* P1.7* Philiphic P1.7* Philiphic Pices Positive Inp P0.0 P0.2	or0 positive	input.	
	0 0 *Note: <i>Avai</i> CMX0P3-( These bits CMX0P3 0 0 0	1 1 CMX0P0: C Select whic CMX0P2 0 0 0	1 1 Comparato ch Port pin <b>CMX0P1</b> 0 0 1	0 1 <i>F53x/53xA d</i> r0 Positive is used as <b>CMX0P0</b> 0 1 0	P1.5* P1.7* levices Input MUX Sel the Comparato <b>Positive Inp</b> P0.0 P0.2 P0.4	or0 positive	input.	
	0 0 *Note: Avai CMX0P3-0 These bits CMX0P3 0 0 0 0	1 1 CMX0P0: ( select whice CMX0P2 0 0 0 0 0	1 1 Comparator Comparator CMX0P1 0 0 1 1	0 1 <i>F53x/53xA d</i> r0 Positive is used as <b>CMX0P0</b> 0 1 0 1	P1.5* P1.7* levices Input MUX Sel the Comparato <b>Positive Inp</b> P0.0 P0.2 P0.4 P0.6*	or0 positive	input.	
	0 0 *Note: Avai CMX0P3-0 These bits CMX0P3 0 0 0 0 0 0	1 1 CMX0P0: C select white CMX0P2 0 0 0 0 0 1	1 1 Comparator Comparator Ch Port pin <b>CMX0P1</b> 0 0 1 1 1 0	0 1 <i>F53x/53xA d</i> r0 Positive is used as <b>CMX0P0</b> 0 1 0 1 0 1 0	P1.5* P1.7* P1.7* P1.7* P1.7* P1.7* P1.0* P1.5* P1.0*	or0 positive	input.	
	0 0 *Note: Avai CMX0P3-( These bits CMX0P3 0 0 0 0 0 0 0 0	1 1 CMX0P0: C Select whice 0 0 0 0 0 1 1	1 1 Comparator Comparator Ch Port pin 0 0 1 1 1 0 0 0	0 1 <i>F53x/53xA d</i> r0 Positive is used as <b>CMX0P0</b> 0 1 0 1 0 1 0	P1.5* P1.7* P1.7* P1.7* P1.7* P1.7* P1.0* P1.2*	or0 positive	input.	
	0 0 *Note: Avai CMX0P3-0 These bits CMX0P3 0 0 0 0 0 0	1 1 CMX0P0: C select white CMX0P2 0 0 0 0 0 1	1 1 Comparator Comparator Ch Port pin <b>CMX0P1</b> 0 0 1 1 1 0	0 1 <i>F53x/53xA d</i> r0 Positive is used as <b>CMX0P0</b> 0 1 0 1 0 1 0	P1.5* P1.7* P1.7* P1.7* P1.7* P1.7* P1.0* P1.5* P1.0*	or0 positive	input.	



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value				
Reserve	d —	CP0RIE	CP0FIE		_	CP0MD1	CP0MD0	00000010				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:				
								0x9D				
Bit7:	RESERVE	<b>D</b> . Read = 0	b. Must write	e 0b.								
Bit6:	UNUSED.	Read = 0b. \	Write = don'	t care.								
Bit5:	CPORIE: Comparator Rising-Edge Interrupt Enable.											
		•	dge interrupt									
		0	dge interrup									
Bit4:			alling-Edge		able.							
		•	dge interrup									
		•	dge interrup									
		ecessary to	enable both	CP0xIE an	d the corres	spondent E	CPx bit loca	ited in EIE1				
B:402 2	SFR. UNUSED. I	Dood OOh	Write dor	't ooro								
	CP0MD1-0				+							
DII31-0.			esponse time									
	Mode	CP0MD1	CP0MD0	CP0 Fal	ing Edge I	Response						
					Time (TYF							
	0	0	0	Faste	st Respons	se Time						
	1	0	1		—							
	2	1	0		—							
	3	1	1	Lowest	Power Cor	sumption						
		g Edge resp	onse times	are approxi	mately dou	ble the Falli	ng Edge re	sponse				
	times.											

## SFR Definition 8.3. CPT0MD: Comparator0 Mode Selection



## **Table 8.1. Comparator Electrical Characteristics**

 $V_{DD} = 2.1$  V, -40 to +125 °C unless otherwise noted.

All specifications apply to both Comparator0 and Comparator1 unless otherwise noted.

Parameter	Conditions	Min	Тур	Max	Units
Response Time:	CP0+ - CP0- = 100 mV		780	—	ns
Mode 0, Vcm <sup>1</sup> = 1.5 V	CP0+ - CP0- = -100  mV		980	—	ns
Response Time:	CP0+ - CP0- = 100 mV		850	—	ns
Mode 1, Vcm <sup>1</sup> = 1.5 V	CP0+ - CP0- = -100  mV		1120	—	ns
Response Time:	CP0+ - CP0- = 100 mV		870	—	ns
Mode 2, Vcm <sup>1</sup> = 1.5 V	CP0+ - CP0- = -100  mV		1310	—	ns
Response Time:	CP0+ - CP0- = 100 mV		1980	—	ns
Mode 3, Vcm <sup>1</sup> = 1.5 V	CP0+ - CP0- = -100  mV		4770	—	ns
Common-Mode Rejection Ratio		—	1.5	TBD	mV/V
Positive Hysteresis 1	CP0HYP1-0 = 00		0.7	2	mV
Positive Hysteresis 2	CP0HYP1-0 = 01	2	5	10	mV
Positive Hysteresis 3	CP0HYP1-0 = 10	5	10	20	mV
Positive Hysteresis 4	CP0HYP1-0 = 11	13	20	40	mV
Negative Hysteresis 1	CP0HYN1-0 = 00	—	0.7	2	mV
Negative Hysteresis 2	CP0HYN1-0 = 01	2	5	10	mV
Negative Hysteresis 3	CP0HYN1-0 = 10	5	10	20	mV
Negative Hysteresis 4	CP0HYN1-0 = 11	13	20	40	mV
Inverting or Non-Inverting Input Voltage Range		-0.25	_	V <sub>DD</sub> + 0.25	V
Input Capacitance			4	—	pF
Input Bias Current			0.5	—	nA
Input Offset Voltage		-10		10	mV
Input Impedance			TBD	—	kΩ
Power Supply					
Power Supply Rejection <sup>2</sup>			0.2	4	mV/V
Power-up Time		_	2.3	—	μs
	Mode 0	—	13	TBD	μA
Supply Current at DC	Mode 1	—	6	TBD	μA
	Mode 2	—	3	TBD	μA
	Mode 3	—	1	TBD	μA
Notes:					

1. Vcm is the common-mode voltage on CP0+ and CP0-.

2. Guaranteed by design and/or characterization.



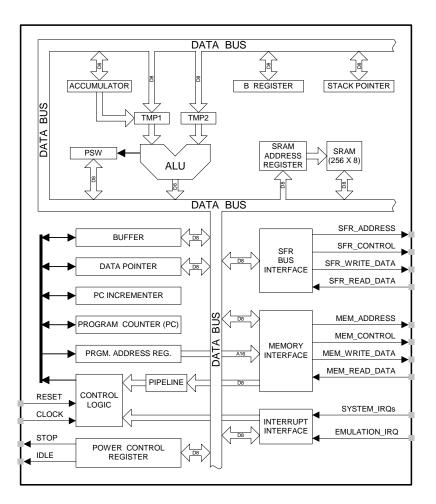
## 9. CIP-51 Microcontroller

The MCU system controller core is the CIP-51 microcontroller. The CIP-51 is fully compatible with the MCS-51<sup>™</sup> instruction set. Standard 803x/805x assemblers and compilers can be used to develop software. The C8051F52x/52xA/53x/53xA family has a superset of all the peripherals included with a standard 8051. See Section "1. System Overview" on page 15 for more information about the available peripherals. The CIP-51 includes on-chip debug hardware which interfaces directly with the analog and digital subsystems, providing a complete data acquisition or control-system solution in a single integrated circuit.

The CIP-51 Microcontroller core implements the standard 8051 organization and peripherals as well as additional custom peripherals and functions to extend its capability (see Figure 9.1 for a block diagram). The CIP-51 core includes the following features:

- Fully Compatible with MCS-51 Instruction Set
- 25 MIPS Peak Throughput
- 256 Bytes of Internal RAM
- Extended Interrupt Handler

- Reset Input
- Power Management Modes
- Integrated Debug Logic
- Program and Data Memory Security







#### Performance

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute, and usually have a maximum system clock of 12 MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with no instructions taking more than eight system clock cycles.

With the CIP-51's system clock running at 25 MHz, it has a peak throughput of 25 MIPS. The CIP-51 has a total of 109 instructions. The table below shows the total number of instructions that require each execution time.

Clocks to Execute	1	2	2/3	3	3/4	4	4/5	5	8
Number of Instructions	26	50	5	14	7	3	1	2	1

#### Programming and Debugging Support

In-system programming of the Flash program memory and communication with on-chip debug support logic is accomplished via the Silicon Labs 2-Wire (C2) interface. Note that the re-programmable Flash can also be read and written a single byte at a time by the application software using the MOVC and MOVX instructions. This feature allows program memory to be used for non-volatile data storage as well as updating program code under software control.

The on-chip debug support logic facilitates full speed in-circuit debugging, allowing the setting of hardware breakpoints, starting, stopping and single stepping through program execution (including interrupt service routines), examination of the program's call stack, and reading/writing the contents of registers and memory. This method of on-chip debugging is completely non-intrusive, requiring no RAM, Stack, timers, or other on-chip resources.

The CIP-51 is supported by development tools from Silicon Laboratories, Inc. and third party vendors. Silicon Laboratories provides an integrated development environment (IDE) including editor, evaluation compiler, assembler, debugger and programmer. The IDE's debugger and programmer interface to the CIP-51 via the on-chip debug logic to provide fast and efficient in-system device programming and debugging. Third party macro assemblers and C compilers are also available.

#### 9.1. Instruction Set

The instruction set of the CIP-51 System Controller is fully compatible with the standard MCS-51<sup>™</sup> instruction set. Standard 8051 development tools can be used to develop software for the CIP-51. All CIP-51 instructions are the binary and functional equivalent of their MCS-51<sup>™</sup> counterparts, including opcodes, addressing modes and effect on PSW flags. However, instruction timing is different than that of the standard 8051.

#### 9.1.1. Instruction and CPU Timing

In many 8051 implementations, a distinction is made between machine cycles and clock cycles, with machine cycles varying from 2 to 12 clock cycles in length. However, the CIP-51 implementation is based solely on clock cycle timing. All instruction timings are specified in terms of clock cycles.

Due to the pipelined architecture of the CIP-51, most instructions execute in the same number of clock cycles as there are program bytes in the instruction. Conditional branch instructions take two less clock cycles to complete when the branch is not taken as opposed to when the branch is taken. Table 9.1 is the CIP-51 Instruction Set Summary, which includes the mnemonic, number of bytes, and number of clock cycles for each instruction.



#### 9.1.2. MOVX Instruction and Program Memory

The MOVX instruction is typically used to access data stored in XDATA memory space. In the CIP-51, the MOVX instruction can also be used to write or erase on-chip program memory space implemented as reprogrammable Flash memory. The Flash access feature provides a mechanism for the CIP-51 to update program code and use the program memory space for non-volatile data storage. Refer to Section "13. Flash Memory" on page 110 for further details.

Witemonic	Mnemonic Description		Clock Cycles			
	Arithmetic Operations	•				
ADD A, Rn	Add register to A	1	1			
ADD A, direct	Add direct byte to A	2	2			
ADD A, @Ri	Add indirect RAM to A	1	2			
ADD A, #data	Add immediate to A	2	2			
ADDC A, Rn						
ADDC A, direct	Add direct byte to A with carry	2	2			
ADDC A, @Ri	Add indirect RAM to A with carry	1	2			
ADDC A, #data	Add immediate to A with carry	2	2			
SUBB A, Rn	Subtract register from A with borrow	1	1			
SUBB A, direct	Subtract direct byte from A with borrow	2	2			
SUBB A, @Ri	Subtract indirect RAM from A with borrow	1	2			
SUBB A, #data	Subtract immediate from A with borrow	2	2			
INC A	Increment A	1	1			
INC Rn	Increment register	1	1			
INC direct	Increment direct byte	2	2			
INC @Ri	Increment indirect RAM	1	2			
DEC A	Decrement A	1	1			
DEC Rn	Decrement register	1	1			
DEC direct	Decrement direct byte	2	2			
DEC @Ri	Decrement indirect RAM	1	2			
INC DPTR	Increment Data Pointer	1	1			
MUL AB	Multiply A and B	1	4			
DIV AB	Divide A by B	1	8			
DA A	Decimal adjust A	1	1			
	Logical Operations	·	•			
ANL A, Rn	AND Register to A	1	1			
ANL A, direct	AND direct byte to A	2	2			
ANL A, @Ri	AND indirect RAM to A	1	2			
ANL A, #data	AND immediate to A	2	2			
ANL direct, A	AND A to direct byte	2	2			
ANL direct, #data	AND immediate to direct byte	3	3			
ORL A, Rn	OR Register to A	1	1			
ORL A, direct	OR direct byte to A	2	2			
ORL A, @Ri	OR indirect RAM to A	1	2			
ORL A, #data	OR immediate to A	2	2			
ORL direct, A	OR A to direct byte	2	2			

## Table 9.1. CIP-51 Instruction Set Summary



## Table 9.1. CIP-51 Instruction Set Summary (Continued)

Mnemonic	Description	Bytes	Clock Cycles
ORL direct, #data	OR immediate to direct byte	3	3
XRL A, Rn	Exclusive-OR Register to A	1	1
XRL A, direct	Exclusive-OR direct byte to A	2	2
XRL A, @Ri	Exclusive-OR indirect RAM to A	1	2
XRL A, #data	Exclusive-OR immediate to A	2	2
XRL direct, A	Exclusive-OR A to direct byte	2	2
XRL direct, #data	Exclusive-OR immediate to direct byte	3	3
CLR A	Clear A	1	1
CPL A	Complement A	1	1
RL A	Rotate A left	1	1
RLC A	Rotate A left through Carry	1	1
RR A	Rotate A right	1	1
RRC A	Rotate A right through Carry	1	1
SWAP A	Swap nibbles of A	1	1
	Data Transfer		
MOV A, Rn	Move Register to A	1	1
MOV A, direct	Move direct byte to A	2	2
MOV A, @Ri	Move indirect RAM to A	1	2
MOV A, #data	Move immediate to A	2	2
MOV Rn, A	Move A to Register	1	1
MOV Rn, direct	Move direct byte to Register	2	2
MOV Rn, #data	Move immediate to Register	2	2
MOV direct, A	Move A to direct byte	2	2
MOV direct, Rn	Move Register to direct byte	2	2
MOV direct, direct	Move direct byte to direct byte	3	3
MOV direct, @Ri	Move indirect RAM to direct byte	2	2
MOV direct, #data	Move immediate to direct byte	3	3
MOV @Ri, A	Move A to indirect RAM	1	2
MOV @Ri, direct	Move direct byte to indirect RAM	2	2
MOV @Ri, #data	Move immediate to indirect RAM	2	2
MOV DPTR, #data16	Load DPTR with 16-bit constant	3	3
MOVC A, @A+DPTR	Move code byte relative DPTR to A	1	3
MOVC A, @A+PC	Move code byte relative PC to A	1	3
MOVX A, @Ri	Move external data (8-bit address) to A	1	3
MOVX @Ri, A	Move A to external data (8-bit address)	1	3
MOVX A, @DPTR	Move external data (16-bit address) to A	1	3
MOVX @DPTR, A	Move A to external data (16-bit address)	1	3
PUSH direct	Push direct byte onto stack	2	2
POP direct	Pop direct byte from stack	2	2
XCH A, Rn	Exchange Register with A	1	1
XCH A, direct	Exchange direct byte with A	2	2
XCH A, @Ri	Exchange indirect RAM with A	1	2
XCHD A, @Ri	Exchange low nibble of indirect RAM with A	1	2



Mnemonic	Description	Bytes	Clock Cycles
	Boolean Manipulation		
CLR C	Clear Carry	1	1
CLR bit	Clear direct bit	2	2
SETB C	Set Carry	1	1
SETB bit	Set direct bit	2	2
CPL C			
CPL bit	Complement direct bit	2	2
ANL C, bit	AND direct bit to Carry	2	2
ANL C, /bit	AND complement of direct bit to Carry	2	2
ORL C, bit	OR direct bit to carry	2	2
ORL C, /bit	OR complement of direct bit to Carry	2	2
MOV C, bit	Move direct bit to Carry	2	2
MOV bit, C	Move Carry to direct bit	2	2
JC rel	Jump if Carry is set	2	2/3
JNC rel	Jump if Carry is not set	2	2/3
JB bit, rel	Jump if direct bit is set	3	3/4
JNB bit, rel	Jump if direct bit is not set	3	3/4
JBC bit, rel	Jump if direct bit is set and clear bit	3	3/4
	Program Branching		
ACALL addr11	Absolute subroutine call	2	3
LCALL addr16	Long subroutine call	3	4
RET	Return from subroutine	1	5
RETI	Return from interrupt	1	5
AJMP addr11	Absolute jump	2	3
LJMP addr16	Long jump	3	4
SJMP rel	Short jump (relative address)	2	3
JMP @A+DPTR	Jump indirect relative to DPTR	1	3
JZ rel	Jump if A equals zero	2	2/3
JNZ rel	Jump if A does not equal zero	2	2/3
CJNE A, direct, rel	Compare direct byte to A and jump if not equal	3	3/4
CJNE A, #data, rel	Compare immediate to A and jump if not equal	3	3/4
CJNE Rn, #data, rel	Compare immediate to Register and jump if not equal	3	3/4
CJNE @Ri, #data, rel	Compare immediate to indirect and jump if not equal	3	4/5
DJNZ Rn, rel	Decrement Register and jump if not zero	2	2/3
DJNZ direct, rel	Decrement direct byte and jump if not zero	3	3/4
NOP	No operation	1	1

## Table 9.1. CIP-51 Instruction Set Summary (Continued)



#### Notes on Registers, Operands and Addressing Modes:

**Rn** - Register R0–R7 of the currently selected register bank.

@Ri - Data RAM location addressed indirectly through R0 or R1.

**rel** - 8-bit, signed (two's complement) offset relative to the first byte of the following instruction. Used by SJMP and all conditional jumps.

**direct** - 8-bit internal data location's address. This could be a direct-access Data RAM location (0x00–0x7F) or an SFR (0x80–0xFF).

#data - 8-bit constant

#data16 - 16-bit constant

**bit** - Direct-accessed bit in Data RAM or SFR

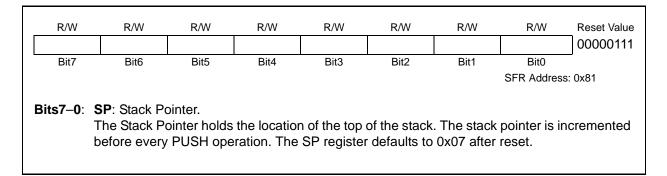
**addr11** - 11-bit destination address used by ACALL and AJMP. The destination must be within the same 2 kB page of program memory as the first byte of the following instruction.

**addr16** - 16-bit destination address used by LCALL and LJMP. The destination may be anywhere within the 7680 bytes of program memory space.

There is one unused opcode (0xA5) that performs the same function as NOP. All mnemonics copyrighted © Intel Corporation 1980.

#### 9.2. Register Descriptions

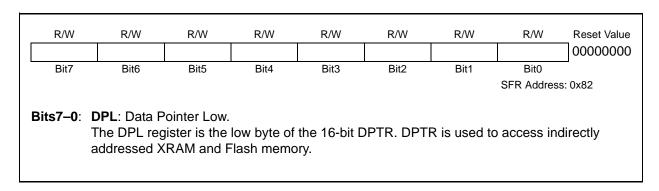
Following are descriptions of SFRs related to the operation of the CIP-51 System Controller. Reserved bits should not be set to logic 1. Future product versions may use these bits to implement new features in which case the reset value of the bit will be logic 0, selecting the feature's default state. Detailed descriptions of the remaining SFRs are included in the sections of the datasheet associated with their corresponding system function.



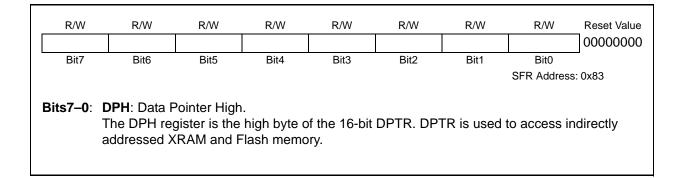
## SFR Definition 9.1. SP: Stack Pointer



## SFR Definition 9.2. DPL: Data Pointer Low Byte



## SFR Definition 9.3. DPH: Data Pointer High Byte





## SFR Definition 9.4. PSW: Program Status Word

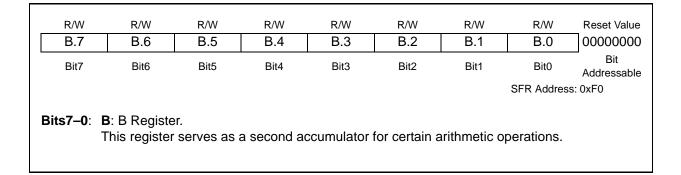
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R	Reset Value
CY	AC	F0	RS1	RS0	OV	F1	PARITY	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressable
							SFR Address	
Bit7:	CY: Carry	•						
			he last arithmeti				addition) or a	a borrow
Bit6:	AC: Auxilia		eared to 0 by all	other anti	imetic opera	alions.		
DILO.			ne last arithmetic	operation	n resulted in	a carry int	o (addition)	or a borrow
			e high order nib	•			· · ·	
Bit5:	F0: User F	,				by an other		porationo.
		0	able, general pu	rpose flac	a for use uno	der softwar	e control.	
Bits4–3:			Bank Select.	1	,			
		•	ich register bank	k is used o	during regist	ter accesse	es.	
			-					
	RS1	RS0	<b>Register Bank</b>	Add	ress			
	<b>RS1</b> 0	<b>RS0</b> 0	Register Bank	Add 0x00-				
			-		-0x07			
	0	0	0	0x00-	-0x07 -0x0F			
	0 0	0 1	0 1	0x00- 0x08-	-0x07 -0x0F -0x17			
	0 0 1	0 1 0	0 1 2	0x00- 0x08- 0x10-	-0x07 -0x0F -0x17			
Bit2:	0 0 1 1 0 <b>V</b> : Overfi	0 1 0 1 ow Flag.	0 1 2 3	0x00- 0x08- 0x10- 0x18-	-0x07 -0x0F -0x17 -0x1F			
Bit2:	0 0 1 1 0V: Overfi This bit is	0 1 0 1 ow Flag. set to 1 un	0 1 2 3 der the following	0x00- 0x08- 0x10- 0x18- g circumst	-0x07 -0x0F -0x17 -0x1F -0x1F			
Bit2:	0 0 1 1 0V: Overfi This bit is • An ADD,	0 1 0 1 ow Flag. set to 1 un ADDC, or	0 1 2 3 der the following SUBB instructio	0x00- 0x08- 0x10- 0x18- g circumst	-0x07 -0x0F -0x17 -0x1F -0x1F tances: a sign-chai			
Bit2:	0 0 1 1 OV: Overfi This bit is • An ADD, • A MUL in	0 1 0 1 ow Flag. set to 1 un ADDC, or istruction r	0 1 2 3 der the following SUBB instruction esults in an over	0x00- 0x08- 0x10- 0x18- g circumston causes rflow (rest	-0x07 -0x0F -0x17 -0x1F -0x1F tances: a sign-char ult is greate			
Bit2:	0 0 1 1 OV: Overfi This bit is • An ADD, • A MUL ir • A DIV ins	0 1 0 1 ow Flag. set to 1 un ADDC, or istruction r	0 1 2 3 der the following SUBB instructio esults in an ove auses a divide-b	0x00- 0x08- 0x10- 0x18- g circumston causes rflow (resu y-zero co	-0x07 -0x0F -0x17 -0x1F -0x1F tances: a sign-chai ult is greate ndition.	r than 255)		in all adda
Bit2:	0 0 1 1 OV: Overfi This bit is • An ADD, • A MUL in • A DIV ins The OV bi	0 1 0 1 ow Flag. set to 1 un ADDC, or istruction r	0 1 2 3 der the following SUBB instruction esults in an over	0x00- 0x08- 0x10- 0x18- g circumston causes rflow (resu y-zero co	-0x07 -0x0F -0x17 -0x1F -0x1F tances: a sign-chai ult is greate ndition.	r than 255)		in all othe
	0 0 1 1 OV: Overfi This bit is • An ADD, • A MUL in • A DIV ins The OV bit cases.	0 1 0 1 ow Flag. set to 1 un ADDC, or struction r struction ca t is cleared	0 1 2 3 der the following SUBB instructio esults in an ove auses a divide-b	0x00- 0x08- 0x10- 0x18- g circumston causes rflow (resu y-zero co	-0x07 -0x0F -0x17 -0x1F -0x1F tances: a sign-chai ult is greate ndition.	r than 255)		in all othe
	0 0 1 1 0V: Overfi This bit is • An ADD, • A MUL ir • A DIV ins The OV bi cases. F1: User F	0 1 0 1 ow Flag. set to 1 un ADDC, or struction ra truction ca t is cleared	0 1 2 3 der the following SUBB instructio esults in an ove auses a divide-b t to 0 by the ADI	0x00- 0x08- 0x10- 0x18- g circumst on causes rflow (resu y-zero co D, ADDC,	-0x07 -0x0F -0x17 -0x1F -0x1F tances: a sign-chai ult is greate ndition. SUBB, MU	r than 255) L, and DIV	instructions	in all othe
Bit1:	0 0 1 1 0V: Overfl This bit is • An ADD, • A MUL ir • A DIV ins The OV bir cases. F1: User F This is a b	0 1 0 1 ow Flag. set to 1 un ADDC, or istruction r struction ca t is cleared	0 1 2 3 der the following SUBB instructio esults in an ove auses a divide-b t to 0 by the ADI able, general pu	0x00- 0x08- 0x10- 0x18- g circumst on causes rflow (resu y-zero co D, ADDC,	-0x07 -0x0F -0x17 -0x1F -0x1F tances: a sign-chai ult is greate ndition. SUBB, MU	r than 255) L, and DIV	instructions	in all othe
Bit2: Bit1: Bit0:	0 0 1 1 0V: Overfil This bit is • An ADD, • A MUL ir • A DIV ins The OV bi cases. F1: User F This is a b PARITY: F	0 1 0 1 ow Flag. set to 1 un ADDC, or struction r struction ca t is cleared flag 1. it-addressa Parity Flag.	0 1 2 3 der the following SUBB instruction esults in an ove auses a divide-b to 0 by the ADI to 0 by the ADI	0x00- 0x08- 0x10- 0x18- g circumston causes rflow (resu y-zero con D, ADDC, rpose flag	-0x07 -0x0F -0x17 -0x17 -0x1F tances: a sign-chai ult is greate ndition. SUBB, MU SUBB, MU	r than 255) L, and DIV der softwar	instructions e control.	
Bit1:	0 0 1 1 0V: Overfil This bit is • An ADD, • A MUL ir • A DIV ins The OV bi cases. F1: User F This is a b PARITY: F	0 1 0 1 ow Flag. set to 1 un ADDC, or struction r struction ca t is cleared flag 1. it-addressa Parity Flag.	0 1 2 3 der the following SUBB instructio esults in an ove auses a divide-b t to 0 by the ADI able, general pu	0x00- 0x08- 0x10- 0x18- g circumston causes rflow (resu y-zero con D, ADDC, rpose flag	-0x07 -0x0F -0x17 -0x17 -0x1F tances: a sign-chai ult is greate ndition. SUBB, MU SUBB, MU	r than 255) L, and DIV der softwar	instructions e control.	



## SFR Definition 9.5. ACC: Accumulator

R/W ACC.7	R/W ACC.6	R/W ACC.5	R/W ACC.4	R/W ACC.3	R/W ACC.2	R/W ACC.1	R/W ACC.0	Reset Value
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 SFR Address	Bit Addressable
	ACC: Accum This register		mulator for	arithmetic o	operations.			

## SFR Definition 9.6. B: B Register



## 9.3. Power Management Modes

The CIP-51 core has two software programmable power management modes: Idle and Stop. Idle mode halts the CPU while leaving the peripherals and internal clocks active. In Stop mode, the CPU is halted, all interrupts and timers (except the Missing Clock Detector) are inactive, and the internal oscillator is stopped (analog peripherals remain in their selected states; the external oscillator is not affected). Since clocks are running in Idle mode, power consumption is dependent upon the system clock frequency and the number of peripherals left in active mode before entering Idle. Stop mode consumes the least power. SFR Definition 9.7 describes the Power Control Register (PCON) used to control the CIP-51's power management modes.

Although the CIP-51 has Idle and Stop modes built in (as with any standard 8051 architecture), power management of the entire MCU is better accomplished by enabling/disabling individual peripherals as needed. Each analog peripheral can be disabled when not in use and placed in low power mode. Digital peripherals, such as timers or serial buses, draw little power when they are not in use. Turning off the oscillators lowers power consumption considerably; however a reset is required to restart the MCU.

The C8051F52x/52xA/53x/53xA devices feature a low-power SUSPEND mode, which stops the internal oscillator until a wakening event occurs. See Section "15.1.1. Internal Oscillator Suspend Mode" on page 136 for more information.



#### 9.3.1. Idle Mode

Setting the Idle Mode Select bit (PCON.0) causes the CIP-51 to halt the CPU and enter Idle mode as soon as the instruction that sets the bit completes execution. All internal registers and memory maintain their original data. All analog and digital peripherals can remain active during Idle mode.

Idle mode is terminated when an enabled interrupt is asserted or a reset occurs. The assertion of an enabled interrupt will cause the Idle Mode Selection bit (PCON.0) to be cleared and the CPU to resume operation. The pending interrupt will be serviced and the next instruction to be executed after the return from interrupt (RETI) will be the instruction immediately following the one that set the Idle Mode Select bit. If Idle mode is terminated by an internal or external reset, the CIP-51 performs a normal reset sequence and begins program execution at address 0x0000.

If enabled, the Watchdog Timer (WDT) will eventually cause an internal watchdog reset and thereby terminate the Idle mode. This feature protects the system from an unintended permanent shutdown in the event of an inadvertent write to the PCON register. If this behavior is not desired, the WDT may be disabled by software prior to entering the Idle mode if the WDT was initially configured to allow this operation. This provides the opportunity for additional power savings, allowing the system to remain in the Idle mode indefinitely, waiting for an external stimulus to wake up the system.

#### 9.3.2. Stop Mode

Setting the Stop Mode Select bit (PCON.1) causes the CIP-51 to enter Stop mode as soon as the instruction that sets the bit completes execution. In Stop mode the internal oscillator, CPU, and all digital peripherals are stopped; the state of the external oscillator circuit is not affected. Each analog peripheral (including the external oscillator circuit) may be shut down individually prior to entering Stop Mode. Stop mode can only be terminated by an internal or external reset. On reset, the CIP-51 performs the normal reset sequence and begins program execution at address 0x0000.

If enabled, the Missing Clock Detector will cause an internal reset and thereby terminate the Stop mode. The Missing Clock Detector should be disabled if the CPU is to be put to in STOP mode for longer than the MCD timeout period of 100  $\mu$ s.

#### 9.3.3. Suspend Mode

The C8051F52x/52xA/53x/53xA devices feature a low-power SUSPEND mode, which stops the internal oscillator until a wakening event occurs. See Section Section "15.1.1. Internal Oscillator Suspend Mode" on page 136 for more information.



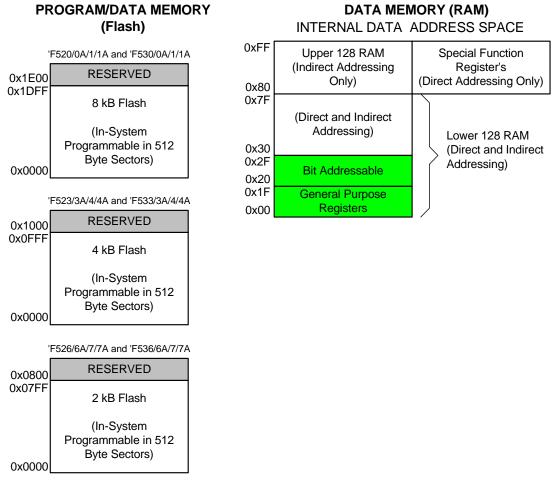
R/W	R/W	R/W	R/W	R/W	R/W	R/W		Reset Value
R/W	R/W	R/VV	R/W	R/W	K/W	R/VV	R/W	Reset value
Reserve	d Reserved	Reserved	Reserved	Reserved	Reserved	STOP	IDLE	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
							SFR Address	: 0x87
Bits7–2: Bit1: Bit0:	RESERVED STOP: STOP Writing a '1' 1: CIP-51 for IDLE: IDLE I Writing a '1' 1: CIP-51 for and all peripl	P Mode Sel to this bit w ced into po Mode Selec to this bit w ced into ID	ill place the wer-down r t. ill place the LE mode. (	node. (Turn CIP-51 into	s off interna	ll oscillator) e. This bit v	). will always r	ead '0'.

## SFR Definition 9.7. PCON: Power Control



## 10. Memory Organization and SFRs

The memory organization of the C8051F52x/52xA/53x/53xA is similar to that of a standard 8051. There are two separate memory spaces: program memory and data memory. Program and data memory share the same address space but are accessed via different instruction types. The memory map is shown in Figure 10.1.



## Figure 10.1. Memory Map

## **10.1. Program Memory**

The CIP-51 core has a 64k-byte program memory space. The C8051F520/0A/1/1A and C8051F530/0A/1/ 1A implement 8 kB of this program memory space as in-system, re-programmable Flash memory, organized in a contiguous block from addresses 0x0000 to 0x1FFF. Addresses above 0x1DFF are reserved on the 8 kB devices. The C8051F523/3A/4/4A and C8051F533/3A/4/4A implement 4 kB of Flash from addresses 0x0000 to 0x0FFF. The C8051F526/6A/7/7A and C8051F536/6A/7/7A implement 2 kB of Flash from addresses 0x0000 to 0x07FF.

Program memory is normally assumed to be read-only. However, the C8051F52x/52xA/53x/53xAcan write to program memory by setting the Program Store Write Enable bit (PSCTL.0) and using the MOVX write instruction. This feature provides a mechanism for updates to program code and use of the program mem-



ory space for non-volatile data storage. Refer to Section "13. Flash Memory" on page 110 for further details.

## 10.2. Data Memory

The C8051F52x/52xA/53x/53xAincludes 256 bytes of internal RAM mapped into the data memory space from 0x00 through 0xFF. The lower 128 bytes of data memory are used for general purpose registers and scratch pad memory. Either direct or indirect addressing may be used to access the lower 128 bytes of data memory. Locations 0x00 through 0x1F are addressable as four banks of general purpose registers, each bank consisting of eight byte-wide registers. The next 16 bytes, locations 0x20 through 0x2F, may either be addressed as bytes or as 128 bit locations accessible with the direct addressing mode.

The upper 128 bytes of data memory are accessible only by indirect addressing. This region occupies the same address space as the Special Function Registers (SFRs) but is physically separate from the SFR space. The addressing mode used by an instruction when accessing locations above 0x7F determines whether the CPU accesses the upper 128 bytes of data memory space or the SFRs. Instructions that use direct addressing will access the SFR space. Instructions using indirect addressing above 0x7F access the upper 128 bytes of data memory organization of the C8051F52x/ 52xA/53x/53xA.

## 10.3. General Purpose Registers

The lower 32 bytes of data memory (locations 0x00 through 0x1F) may be addressed as four banks of general-purpose registers. Each bank consists of eight byte-wide registers designated R0 through R7. Only one of these banks may be enabled at a time. Two bits in the program status word, RS0 (PSW.3) and RS1 (PSW.4), select the active register bank (see description of the PSW in SFR Definition 9.4. PSW: Program Status Word). This allows fast context switching when entering subroutines and interrupt service routines. Indirect addressing modes use registers R0 and R1 as index registers.

## 10.4. Bit Addressable Locations

In addition to direct access to data memory organized as bytes, the sixteen data memory locations at 0x20 through 0x2F are also accessible as 128 individually addressable bits. Each bit has a bit address from 0x00 to 0x7F. Bit 0 of the byte at 0x20 has bit address 0x00 while bit 7 of the byte at 0x20 has bit address 0x7F. A bit access is distinguished from a full byte access by the type of instruction used (bit source or destination operands as opposed to a byte source or destination).

The MCS-51<sup>™</sup> assembly language allows an alternate notation for bit addressing of the form XX.B where XX is the byte address and B is the bit position within the byte. For example, the instruction:

MOV C, 22.3h

moves the Boolean value at 0x13 (bit 3 of the byte at location 0x22) into the Carry flag.

#### 10.5. Stack

A programmer's stack can be located anywhere in the 256-byte data memory. The stack area is designated using the Stack Pointer (SP, 0x81) SFR. The SP will point to the last location used. The next value pushed on the stack is placed at SP+1 and then SP is incremented. A reset initializes the stack pointer to location 0x07. Therefore, the first value pushed on the stack is placed at location 0x08, which is also the first register (R0) of register bank 1. Thus, if more than one register bank is to be used, the SP should be initialized to a location in the data memory not being used for data storage. The stack depth can extend up to 256 bytes.



## **10.6.** Special Function Registers

The direct-access data memory locations from 0x80 to 0xFF constitute the special function registers (SFRs). The SFRs provide control and data exchange with the CIP-51's resources and peripherals. The CIP-51 duplicates the SFRs found in a typical 8051 implementation as well as implementing additional SFRs used to configure and access the sub-systems unique to the MCU. This allows the addition of new functionality while retaining compatibility with the MCS-51<sup>™</sup> instruction set. Table 10.1 lists the SFRs implemented in the CIP-51 System Controller.

The SFR registers are accessed anytime the direct addressing mode is used to access memory locations from 0x80 to 0xFF. SFRs with addresses ending in 0x0 or 0x8 (e.g. P0, TCON, IE, etc.) are bit-addressable as well as byte-addressable. All other SFRs are byte-addressable only. Unoccupied addresses in the SFR space are reserved for future use. Accessing these areas will have an indeterminate effect and should be avoided. Refer to the corresponding pages of the data sheet, as indicated in Table 10.2, for a detailed description of each register.

F8	SPI0CN	PCA0L	PCA0H	PCA0CPL0	PCA0CPH0			VDDMON
F0	В	P0MDIN	P1MDIN				EIP1	
E8	ADC0CN	PCA0CPL1	PCA0CPH1	PCA0CPL2	PCA0CPH2			RSTSRC
E0	ACC	XBR0	XBR1		IT01CF		EIE1	
D8	PCA0CN	PCA0MD	PCA0CPM0	PCA0CPM1	PCA0CPM2			
D0	PSW	REF0CN			P0SKIP	P1SKIP		P0MAT
C8	TMR2CN	REG0CN	TMR2RLL	TMR2RLH	TMR2L	TMR2H		P1MAT
C0				ADC0GTL	ADC0GTH	ADC0LTL	ADC0LTH	P0MASK
B8	IP		ADC0TK	ADC0MX	ADC0CF	ADC0L	ADC0	P1MASK
B0	OSCIFIN	OSCXCN	OSCICN	OSCICL				FLKEY
A8	IE	CLKSEL						
A0		SPI0CFG	SPI0CKR	SPI0DAT	POMDOUT	P1MDOUT		
98	SCON0	SBUF0		CPT0CN		CPT0MD		CPT0MX
90	P1		LINADDR	LINDATA		LINCF		
88	TCON	TMOD	TL0	TL1	TH0	TH1	CKCON	PSCTL
80	P0	SP	DPL	DPH				PCON
	0(8)	1(9)	2(A)	3(B)	4(C)	5(D)	6(E)	7(F)
	(bit addressable)							

#### Table 10.1. Special Function Register (SFR) Memory Map



## Table 10.2. Special Function Registers

Register	Address	Description	Page
ACC	0xE0	Accumulator	86
ADC0CF	0xBC	ADC0 Configuration	59
ADC0CN	0xE8	ADC0 Control	61
ADC0H	0xBE	ADC0	60
ADC0L	0xBD	ADC0	60
ADC0GTH	0xC4	ADC0 Greater-Than Data High Byte	63
ADC0GTL	0xC3	ADC0 Greater-Than Data Low Byte	63
ADC0LTH	0xC6	ADC0 Less-Than Data High Byte	64
ADC0LTL	0xC5	ADC0 Less-Than Data Low Byte	64
ADC0MX	0xBB	ADC0 Channel Select	58
ADC0TK	0xBA	ADC0 Tracking Mode Select	62
В	0xF0	B Register	86
CKCON	0x8E	Clock Control	190
CLKSEL	0xA9	Clock Select	144
CPT0CN	0x9B	Comparator0 Control	74
CPT0MD	0x9D	Comparator0 Mode Selection	76
CPT0MX	0x9F	Comparator0 MUX Selection	75
DPH	0x83	Data Pointer High	84
DPL	0x82	Data Pointer Low	84
EIE1	0xE6	Extended Interrupt Enable 1	99
EIP1	0xF6	Extended Interrupt Priority 1	100
FLKEY	0xB7	Flash Lock and Key	116
IE	0xA8	Interrupt Enable	97
IP	0xB8	Interrupt Priority	98
IT01CF	0xE4	INT0/INT1 Configuration	102
LINADDR	0x92	LIN indirect address pointer	161
LINCF	0x95	LIN master-slave and automatic baud rate selection	162
LINDATA	0x93	LIN indirect data buffer	162
OSCICL	0xB3	Internal Oscillator Calibration	138
OSCICN	0xB2	Internal Oscillator Control	137
OSCXCN	0xB1	External Oscillator Control	143
P0	0x80	Port 0 Latch	128
POMASK	0xC7	Port 0 Mask	130
POMAT	0xD7	Port 0 Match	130
POMDIN	0xF1	Port 0 Input Mode Configuration	128
POMDOUT	0xA4	Port 0 Output Mode Configuration	129
P0SKIP	0xD4	Port 0 Skip	129
P1	0x90	Port 1 Latch	131

SFRs are listed in alphabetical order. All undefined SFR locations are reserved



## Table 10.2. Special Function Registers (Continued)

Register	Address	Description	Page
P1MASK	0xBF	Port 1 Mask	133
P1MAT	0xCF	Port 1 Match	133
P1MDIN	0xF2	Port 1 Input Mode Configuration	131
P1MDOUT	0xA5	Port 1 Output Mode Configuration	132
P1SKIP	0xD5	Port 1 Skip	132
PCA0CN	0xD8	PCA Control	209
PCA0CPH0	0xFC	PCA Capture 0 High	212
PCA0CPH1	0xEA	PCA Capture 1 High	212
PCA0CPH2	0xEC	PCA Capture 2 High	212
PCA0CPL0	0xFB	PCA Capture 0 Low	212
PCA0CPL1	0xE9	PCA Capture 1 Low	212
PCA0CPL2	0xEB	PCA Capture 2 Low	212
PCA0CPM0	0xDA	PCA Module 0 Mode	211
PCA0CPM1	0xDB	PCA Module 1 Mode	211
PCA0CPM2	0xDC	PCA Module 2 Mode	211
PCA0H	0xFA	PCA Counter High	212
PCA0L	0xF9	PCA Counter Low	212
PCA0MD	0xD9	PCA Mode	210
PCON	0x87	Power Control	88
PSCTL	0x8F	Program Store R/W Control	116
PSW	0xD0	Program Status Word	85
REF0CN	0xD1	Voltage Reference Control	68
REG0CN	0xC9	Voltage Regulator Control	71
RSTSRC	0xEF	Reset Source Configuration/Status	108
SBUF0	0x99	UART0 Data Buffer	152
SCON0	0x98	UART0 Control	151
SP	0x81	Stack Pointer	83
SPI0CFG	0xA1	SPI Configuration	177
SPI0CKR	0xA2	SPI Clock Rate Control	179
SPI0CN	0xF8	SPI Control	178
SPI0DAT	0xA3	SPI Data	180
TCON	0x88	Timer/Counter Control	188
TH0	0x8C	Timer/Counter 0 High	191
TH1	0x8D	Timer/Counter 1 High	191
TL0	0x8A	Timer/Counter 0 Low	191
TL1	0x8B	Timer/Counter 1 Low	191
TMOD	0x89	Timer/Counter Mode	189
TMR2CN	0xC8	Timer/Counter 2 Control	195

SFRs are listed in alphabetical order. All undefined SFR locations are reserved



## Table 10.2. Special Function Registers (Continued)

SFRs are listed in alphabetical order. All undefined SFR locations are reserved

Register	Address	Description	Page
TMR2H	0xCD	Timer/Counter 2 High	196
TMR2L	0xCC	Timer/Counter 2 Low	196
TMR2RLH	0xCB	Timer/Counter 2 Reload High	196
TMR2RLL	0xCA	Timer/Counter 2 Reload Low	196
VDDMON	0xFF	V <sub>DD</sub> Monitor Control	106
XBR0	0xE1	Port I/O Crossbar Control 0	126
XBR1	0xE2	Port I/O Crossbar Control 1	127



## 11. Interrupt Handler

The C8051F52x/52xA/53x/53xA family includes an extended interrupt system with two selectable priority levels. The allocation of interrupt sources between on-chip peripherals and external input pins varies according to the specific version of the device. Each interrupt source has one or more associated interrupt-pending flag(s) located in an SFR. When a peripheral or external source meets a valid interrupt condition, the associated interrupt-pending flag is set to logic 1.

If interrupts are enabled for the source, an interrupt request is generated when the interrupt-pending flag is set. As soon as execution of the current instruction is complete, the CPU generates an LCALL to a predetermined address to begin execution of an interrupt service routine (ISR). Each ISR must end with an RETI instruction, which returns program execution to the next instruction that would have been executed if the interrupt request had not occurred. If interrupts are not enabled, the interrupt-pending flag is ignored by the hardware and program execution continues as normal. (The interrupt-pending flag is set to logic 1 regardless of the interrupt's enable/disable state.)

Each interrupt source can be individually enabled or disabled through the use of an associated interrupt enable bit in the Interrupt Enable and Extended Interrupt Enable SFRs. However, interrupts must first be globally enabled by setting the EA bit (IE.7) to logic 1 before the individual interrupt enables are recognized. Setting the EA bit to logic 0 disables all interrupt sources regardless of the individual interrupt-enable settings. Note that interrupts which occur when the EA bit is set to logic 0 will be held in a pending state, and will not be serviced until the EA bit is set back to logic 1.

Some interrupt-pending flags are automatically cleared by the hardware when the CPU vectors to the ISR. However, most are not cleared by the hardware and must be cleared by software before returning from the ISR. If an interrupt-pending flag remains set after the CPU completes the return-from-interrupt (RETI) instruction, a new interrupt request will be generated immediately and the CPU will re-enter the ISR after the completion of the next instruction.

## 11.1. MCU Interrupt Sources and Vectors

The C8051F52x/52xA/53x/53xA MCUs support 15 interrupt sources. Software can simulate an interrupt by setting any interrupt-pending flag to logic 1. If interrupts are enabled for the flag, an interrupt request will be generated and the CPU will vector to the ISR address associated with the interrupt-pending flag. MCU interrupt sources, associated vector addresses, priority order, and control bits are summarized in Table 11.1 on page 96. Refer to the data sheet section associated with a particular on-chip peripheral for information regarding valid interrupt conditions for the peripheral and the behavior of its interrupt-pending flag(s).

## **11.2.** Interrupt Priorities

Each interrupt source can be individually programmed to one of two priority levels: low or high. A low priority interrupt service routine can be preempted by a high priority interrupt. A high priority interrupt cannot be preempted. Each interrupt has an associated interrupt priority bit in an SFR (IP or EIP1) used to configure its priority level. Low priority is the default. If two interrupts are recognized simultaneously, the interrupt with the higher priority is serviced first. If both interrupts have the same priority level, a fixed priority order is used to arbitrate, given in Table 11.1.

## 11.3. Interrupt Latency

Interrupt response time depends on the state of the CPU when the interrupt occurs. Pending interrupts are sampled and priority decoded each system clock cycle. Therefore, the fastest possible response time is 5 system clock cycles: 1 clock cycle to detect the interrupt and 4 clock cycles to complete the LCALL to the ISR. If an interrupt is pending when a RETI is executed, a single instruction is executed before an LCALL is made to service the pending interrupt. Therefore, the maximum response time for an interrupt (when no other interrupt is currently being serviced or the new interrupt is of greater priority) occurs when the CPU is



performing an RETI instruction followed by a DIV as the next instruction. In this case, the response time is 18 system clock cycles: 1 clock cycle to detect the interrupt, 5 clock cycles to execute the RETI, 8 clock cycles to complete the DIV instruction, and 4 clock cycles to execute the LCALL to the ISR. If the CPU is executing an ISR for an interrupt with equal or higher priority, the new interrupt will not be serviced until the current ISR completes, including the RETI and following instruction.

Interrupt Source Interrupt Prior Vector Orde		Priority Order Pending Flag			Cleared by HW?	Enable Flag	Priority Control
Reset	0x0000	Тор	None	N/A	N/A	Always Enabled	Always Highest
External Interrupt 0(/INT0)	0x0003	0	IE0 (TCON.1)	Y	Y	EX0 (IE.0)	PX0 (IP.0)
Timer 0 Overflow	0x000B	1	TF0 (TCON.5)	Y	Y	ET0 (IE.1)	PT0 (IP.1)
External Interrupt 1(/INT1)	0x0013	2	IE1 (TCON.3)	Y	Y	EX1 (IE.2)	PX1 (IP.2)
Timer 1 Overflow	0x001B	3	TF1 (TCON.7)	Y	Y	ET1 (IE.3)	PT1 (IP.3)
UART	0x0023	4	RI0 (SCON0.0) TI0 (SCON0.1)	Y	N	ES0 (IE.4)	PS0 (IP.4)
Timer 2 Overflow	0x002B	5	TF2H (TMR2CN.7) TF2L (TMR2CN.6)	Y	Ν	ET2 (IE.5)	PT2 (IP.5)
SPI0	0x0033	6	SPIF (SPI0CN.7) WCOL (SPI0CN.6) MODF (SPI0CN.5) RXOVRN (SPI0CN.4)	Y	N	ESPI0 (IE.6)	PSPI0 (IP.6)
ADC0 Window Comparator	0x003B	7	AD0WINT (ADC0CN.3)	Y	Ν	EWADC0 (EIE1.0)	PWADC0 (EIP1.0)
ADC0 End of Conversion	0x0043	8	AD0INT (ADC0CN.5)	Y	N	EADC0 (EIE1.1)	PADC0 (EIP1.1)
Programmable Counter Array	0x004B	9	CF (PCA0CN.7) CCFn (PCA0CN.n)	Y	Ν	EPCA0 (EIE1.2)	PPCA0 (EIP1.2)
Comparator Falling Edge	0x0053	10	CP0FIF (CPT0CN.4)	N	N	ECPF (EIE1.3)	PCPF (EIP1.3)
Comparator Rising Edge	0x005B	11	CP0RIF (CPT0CN.5)	Ν	Ν	ECPR (EIE1.4)	PCPR (EIP1.4)
LIN Interrupt	0x0063	12	LININT (LINST.3)	Ν	N*	ELIN (EIE1.5)	PLIN (EIP1.5)
Voltage Regulator Dropout	0x006B	13	N/A	N/A	N/A	EREG0 (EIE1.6)	PREG0 (EIP1.6)
Port Match	0x0073	14	N/A	N/A	N/A	EMAT (EIE1.7)	PMAT (EIP1.7)
*Note: Software must set the	RSTINT bit	(LINCTRL	3) to clear the LININT flag	g.			

## Table 11.1. Interrupt Summary



## 11.4. Interrupt Register Descriptions

The SFRs used to enable the interrupt sources and set their priority level are described below. Refer to the data sheet section associated with a particular on-chip peripheral for information regarding valid interrupt conditions for the peripheral and the behavior of its interrupt-pending flag(s).

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
EA	ESPI0	ET2	ES0	ET1	EX1	ET0	EX0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressable
							SFR Addres	s: 0xA8
Bit7:	EA: Global II	nterrupt En	able.					
	This bit globa	ally enables	s/disables a	II interrupts	. It override	s the individ	lual interru	pt mask set-
	tings.							
	0: Disable al			(				
Bit6:	1: Enable ea ESPI0: Enab							
ыю.	This bit sets							
	0: Disable al		•	io interiupt	5.			
	1: Enable int			ated by SPI	0.			
Bit5:	ET2: Enable		•		•••			
	This bit sets		•	ner 2 interru	upt.			
	0: Disable Ti	mer 2 interi	rupt.		•			
	1: Enable int	errupt requ	ests genera	ated by the	TF2L or TF	2H flags.		
Bit4:	ES0: Enable							
	This bit sets		•	RT0 interru	ipt.			
	0: Disable U							
<b>D</b>	1: Enable UA		•					
Bit3:	ET1: Enable							
	This bit sets 0: Disable al			ier i interru	ipt.			
	1: Enable int		•	tod by the	TE1 flog			
Bit2:	EX1: Enable		•		n nay.			
DRE.	This bit sets			ernal interr	upt 1			
	0: Disable ex				aptin			
	1: Enable ex		•	ts.				
Bit1:	ET0: Enable							
	This bit sets	the maskin	g of the Tim	ner 0 interru	ipt.			
	0: Disable al	I Timer 0 in	terrupt.					
	1: Enable int		•	ated by the	TF0 flag.			
Bit0:	EX0: Enable				_			
	This bit sets		•	ernal interr	upt 0.			
	0: Disable ex			1				
	1: Enable ex	tern interru	pt 0 reques	ts.				

## SFR Definition 11.1. IE: Interrupt Enable



R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	PSPI0	PT2	PS0	PT1	PX1	PT0	PX0	1000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressable
							SFR Addres	
							OF IT Address	3. 0700
Bit7:	UNUSED. Re	ead = 1b; \	Nrite = don'i	care.				
Bit6:	PSPI0: Seria				rupt Priority	Control.		
	This bit sets	the priority	of the SPI0	interrupt.				
	0: SPI0 interi	upt set to	low priority	evel.				
	1: SPI0 interi							
Bit5:	PT2: Timer 2							
	This bit sets				t.			
	0: Timer 2 int	•						
	1: Timer 2 int	•	• •					
Bit4:	<b>PS0</b> : UART0							
	This bit sets				t.			
	0: UART0 int	•						
Bit3:	1: UART0 int PT1: Timer 1	•	• •					
DILJ.	This bit sets				+			
	0: Timer 1 inf				ι.			
	1: Timer 1 int	•	•					
Bit2:	PX1: Externa	•	• •					
	This bit sets				ot 1.			
	0: INT1 interi							
	1: INT1 interi							
Bit1:	PT0: Timer 0							
	This bit sets	the priority	of the Time	r 0 interrup	t.			
	0: Timer 0 int	errupt set	to low priori	ty level.				
	1: Timer 0 int	errupt set	to high prior	ity level.				
Bit0:	PX0: Externa							
	This bit sets				ot 0.			
	0: INT0 interi							
	1: INT0 interi	upt set to	high priority	level.				

## SFR Definition 11.2. IP: Interrupt Priority



SFR Definition 11.3	3. EIE1: Extended	Interrupt Enable 1
---------------------	-------------------	--------------------

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
EMAT	EREG0	ELIN	ECPR	ECPF	EPCA0	EADC0	EWADC0	00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
							SFR Address:	0xE6			
D'/7			.1.1.7								
Bit7:	EMAT: Enab				orrupt						
	This bit sets 0: Disable th		•		enupt.						
	1: Enable the										
Bit6:	EREGO: Ena			Interrunt							
Sito.	This bit sets	•	•	•	ator Dropou	it interrunt					
	0: Disable th		•	• •	•	it interrupt.					
	1: Enable the	•	•	•	•						
Bit5:	ELIN: Enable										
	This bit sets			l interrupt.							
	0: Disable LI	N interrupt	S.								
	1: Enable LI	N interrupt	requests.								
Bit4:	ECPR: Enab	le Compar	ator 0 Risin	g Edge Inte	errupt						
	This bit sets the masking of the CP0 Rising Edge interrupt.										
	0: Disable CP0 Rising Edge Interrupt.										
	1: Enable CF										
Bit3:	ECPF: Enab				•						
	This bit sets		•	•	dge interrup	t.					
	0: Disable Cl										
<b>D</b> ''0	1: Enable CF										
Bit2:	EPCA0: Ena	•			· · ·	errupt.					
	This bit sets			AU Interrup	us.						
	0: Disable all 1: Enable int			tod by DC	<b>^</b>						
Bit1:	EADCO: Ena										
51(1.	This bit sets				•	ata interrun	+				
	0: Disable Al		•			ste interrup	·				
	1: Enable int					r					
Bit0:	EWADCO: E					y.					
Sito.	This bit sets					on interrupt	_				
	0: Disable Al										



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value					
PMAT	PREG0	PLIN	PCPR	PCPF	PPAC0	PREG0	PWADC0	0000000					
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_					
		SFR Address: 0xF6											
Bit7:	PMAT. Port												
	This bit sets the priority of the Port Match interrupt. 0: Port Match interrupt set to low priority level.												
Bit6:	1: Port Matcl PREG0: Volt		• •										
DILO.	This bit sets	0 0											
	0: Voltage R			• •	•								
	1: Voltage R	•	•	•									
Bit5:	PLIN: LIN In	•		• •	ty lot on								
	This bit sets												
	0: LIN interru			•									
	1: LIN interru												
Bit4:	PCPR: Com	oarator Ris	ing Edge In	terrupt Prio	rity Control.								
	This bit sets	the priority	of the Risir	ng Edge Co	mparator int	terrupt.							
	0: Comparate												
	1: Comparate		•										
Bit3:	PCPF: Comp		0 0	•									
	This bit sets					terrupt.							
	0: Comparat												
-	1: Comparat		•										
Bit2:	PPAC0: Prog				Interrupt P	riority Cont	rol.						
	This bit sets												
	<ul><li>0: PCA0 interrupt set to low priority level.</li><li>1: PCA0 interrupt set to high priority level.</li></ul>												
Bit1:	PREGO: AD	•	• •	•		ntrol							
DILI.	This bit sets		•										
	0: ADC0 Cor												
	1: ADC0 Cor												
Bit0:	PWADC0: A												
	This bit sets												
			parison inter										

## SFR Definition 11.4. EIP1: Extended Interrupt Priority 1



## 11.5. External Interrupts

The /INT0 and /INT1 external interrupt sources are configurable as active high or low, edge or level sensitive. The IN0PL (/INT0 Polarity) and IN1PL (/INT1 Polarity) bits in the IT01CF register select active high or active low; the IT0 and IT1 bits in TCON (Section "19.1. Timer 0 and Timer 1" on page 184) select level or edge sensitive. The table below lists the possible configurations.

IT0	IN0PL	/INT0 Interrupt				
1	0	Active low, edge sensitive				
1	1	Active high, edge sensitive				
0	0	Active low, level sensitive				
0	1	Active high, level sensitive				

IT1	IN1PL	/INT1 Interrupt				
1	0	Active low, edge sensitive				
1	1	Active high, edge sensitive				
0	0	Active low, level sensitive				
0	1	Active high, level sensitive				

/INT0 and /INT1 are assigned to Port pins as defined in the IT01CF register (see SFR Definition 11.5). Note that /INT0 and /INT0 Port pin assignments are independent of any Crossbar assignments. /INT0 and /INT1 will monitor their assigned Port pins without disturbing the peripheral that was assigned the Port pin via the Crossbar. To assign a Port pin only to /INT0 and/or /INT1, configure the Crossbar to skip the selected pin(s). This is accomplished by setting the associated bit in register XBR0 (see Section "14.1. Priority Crossbar Decoder" on page 120 for complete details on configuring the Crossbar).

In the typical configuration, the external interrupt pins should be skipped in the crossbar and configured as open-drain with the pin latch set to '1'. See Section "14. Port Input/Output" on page 118 for more information.

IE0 (TCON.1) and IE1 (TCON.3) serve as the interrupt-pending flags for the /INT0 and /INT1 external interrupts, respectively. If an /INT0 or /INT1 external interrupt is configured as edge-sensitive, the corresponding interrupt-pending flag is automatically cleared by the hardware when the CPU vectors to the ISR. When configured as level sensitive, the interrupt-pending flag remains logic 1 while the input is active as defined by the corresponding polarity bit (IN0PL or IN1PL); the flag remains logic 0 while the input is inactive. The external interrupt source must hold the input active until the interrupt request is recognized. It must then deactivate the interrupt request before execution of the ISR completes or another interrupt request will be generated.



## SFR Definition 11.5. IT01CF: INT0/INT1 Configuration

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
IN1PL	IN1SL2	IN1SL1	IN1SL0	INOPL	INOSL		INOSLO	00000001
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
							SFR Address	: 0xE4
Note: Refer t	to SFR Definitio	n 19.1. "TCC	N: Timer Cont	rol" on page 1	38 for INT	)/1 edge- or level-	sensitive inter	rupt selection.
						-		
	IN1PL: /INT1							
	0: /INT1 inpu							
	1: /INT1 inpu			Dite				
	IN1SL2-0: /I					Note that this p	in accianm	ont is indo
						ed Port pin wit		
						Crossbar. The		
						kip the selecte		
	setting to '1'	•		-		•		. ,
	-			-	-			
	IN1SL2			Port Pin				
	000			P0.0				
	001			P0.1				
	010			P0.2				
	011			P0.3				
	100			P0.4				
	101 110		P0.5 P0.6*					
	110		P0.6 P0.7*					
			e C80151F53x/C8051F53xA parts.					
	*Note: Availa	able in the C	280151F53x/0	J8051F53xA	parts.			
Bit 3:		Delerity						
	INOPL: /INT( 0: /INT0 inter		ive low					
	1: /INT0 inte	•						
	INT0SL2-0:		•	on Bits				
	These bits se	elect which	Port pin is	assigned to	/INTO. N	Note that this p	oin assignm	ent is inde-
	pendent of th	ne Crossba	ar. /INT0 will	monitor the	e assigne	ed Port pin wit	hout disturb	ing the
						Crossbar. The		
						kip the selecte	d pin (accor	nplished by
	setting to '1'	the corres	ponding bit i	n register F	'USKIP).			
	INOSL	2-0	/INT(	Port Pin				
	000			P0.0				
	001			P0.1				
	010			P0.2				
	011			P0.3				
	100			P0.4				
	101			P0.5				
	110			P0.6*				
	111			P0.7*				
	*Note: Availa	able in the C	C80151F53x/0	C8051F53xA	parts.			



## 12. Reset Sources

Reset circuitry allows the controller to be easily placed in a predefined default condition. On entry to this reset state, the following occur:

- CIP-51 halts program execution
- Special Function Registers (SFRs) are initialized to their defined reset values
- External Port pins are forced to a known state
- Interrupts and timers are disabled.

All SFRs are reset to the predefined values noted in the SFR detailed descriptions. The contents of internal data memory are unaffected during a reset; any previously stored data is preserved. However, since the stack pointer SFR is reset, the stack is effectively lost, even though the data on the stack is not altered.

The Port I/O latches are reset to 0xFF (all logic ones) in open-drain mode. Weak pullups are enabled during and after the reset. For V<sub>DD</sub> Monitor and power-on resets, the  $\overrightarrow{RST}$  pin is driven low until the device exits the reset state.

On exit from the reset state, the program counter (PC) is reset, and the system clock defaults to the internal oscillator. Refer to Section "15. Oscillators" on page 135 for information on selecting and configuring the system clock source. The Watchdog Timer is enabled with the system clock divided by 12 as its clock source (Section "20.3. Watchdog Timer Mode" on page 205 details the use of the Watchdog Timer). Program execution begins at location 0x0000.

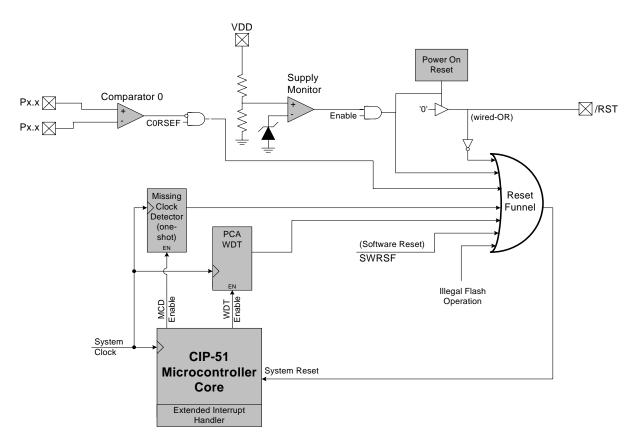


Figure 12.1. Reset Sources



## 12.1. Power-On Reset

During power-up, the device is held in a reset state and the  $\overline{RST}$  pin is driven low until V<sub>DD</sub> settles above V<sub>RST</sub>. An additional delay occurs before the device is released from reset; the delay decreases as the V<sub>DD</sub> ramp time increases (V<sub>DD</sub> ramp time is defined as how fast V<sub>DD</sub> ramps from 0 V to V<sub>RST</sub>). Figure 12.2 plots the power-on and V<sub>DD</sub> monitor reset timing. For valid ramp times (less than 1 ms), the power-on reset delay (T<sub>PORDelav</sub>) is typically less than 0.3 ms.

**Note:** The maximum  $V_{DD}$  ramp time is 1 ms; slower ramp times may cause the device to be released from reset before  $V_{DD}$  reaches the  $V_{RST}$  level.

On exit from a power-on reset, the PORSF flag (RSTSRC.1) is set by hardware to logic 1. When PORSF is set, all of the other reset flags in the RSTSRC Register are indeterminate (PORSF is cleared by all other resets). Since all resets cause program execution to begin at the same location (0x0000), software can read the PORSF flag to determine if a power-up was the cause of reset. The contents of internal data memory should be assumed to be undefined after a power-on reset. The V<sub>DD</sub> monitor is enabled following a power-on reset.

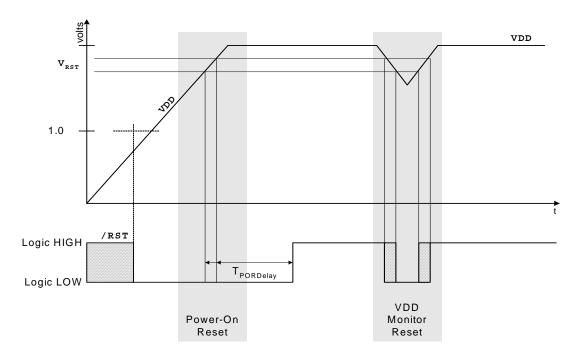


Figure 12.2. Power-On and V<sub>DD</sub> Monitor Reset Timing



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## 12.2. Power-Fail Reset / V<sub>DD</sub> Monitor

When a power-down transition or power irregularity causes  $V_{DD}$  to drop below  $V_{RST}$ , the power supply monitor will drive the  $\overline{RST}$  pin low and hold the CIP-51 in a reset state (see Figure 12.2). When  $V_{DD}$  returns to a level above  $V_{RST}$ , the CIP-51 will be released from the reset state. Note that even though internal data memory contents are not altered by the power-fail reset, it is impossible to determine if  $V_{DD}$  dropped below the level required for data retention. If the PORSF flag reads '1', the data may no longer be valid. The  $V_{DD}$  monitor is enabled and is not selected as a reset source after power-on resets; however its defined state (enabled/disabled) is not altered by any other reset source. For example, if the  $V_{DD}$  monitor is disabled by software, and a software reset is performed, the  $V_{DD}$  monitor must be enabled to the higher setting (VDMLVL = '1') and selected as a reset source if software contains routines which erase or write Flash memory. If the  $V_{DD}$  monitor is not enabled, any erase or write performed on Flash memory will cause a Flash Error device reset.

The V<sub>DD</sub> monitor must be enabled before it is selected as a reset source. Selecting the V<sub>DD</sub> monitor as a reset source before it is enabled and stabilized may cause a system reset. The procedure for reenabling the V<sub>DD</sub> monitor and configuring the V<sub>DD</sub> monitor as a reset source is shown below:

- Step 1. Enable the  $V_{DD}$  monitor (VDMEN bit in VDDMON = '1').
- Step 2. Wait for the V<sub>DD</sub> monitor to stabilize (see Table 12.1 for the V<sub>DD</sub> Monitor turn-on time).
   Note: This delay should be omitted if software contains routines which write or erase Flash memory.
- Step 3. Select the V<sub>DD</sub> monitor as a reset source (PORSF bit in RSTSRC = '1').

See Figure 12.2 for  $V_{DD}$  monitor timing; note that the reset delay is not incurred after a  $V_{DD}$  monitor reset. See Table 12.1 for complete electrical characteristics of the  $V_{DD}$  monitor.

Note: Software should take care not to inadvertently disable the  $V_{DD}$  Monitor as a reset source when writing to RSTSRC to enable other reset sources or to trigger a software reset. All writes to RSTSRC should explicitly set PORSF to '1' to keep the  $V_{DD}$  Monitor enabled as a reset source.



R	R/W	R	R	R	R	R	Reset Value		
VDDSTAT	VDMLVL	Reserved	Reserved	Reserved	Reserved	Reserved	1v000000		
Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	-		
						SFR Address:	0xFF		
VDMEN: V <sub>DI</sub>	<sub>D</sub> Monitor E	nable.							
This bit turns	s the V <sub>DD</sub> m	onitor circu	it on/off. Th	e V <sub>DD</sub> Mon	itor cannot o	generate sy	stem		
resets until it	is also sel	ected as a r	eset source	in register	RSTSRC (	SFR Definiti	on 12.2).		
The $V_{DD}$ Mo	nitor can be	e allowed to	stabilize be	efore it is se	elected as a	reset sourc	e. Select-		
ing the $\rm V_{\rm DD}$	monitor as	s a reset so	ource befor	e it has sta	bilized ma	y generate	a system		
reset. See Table 12.1 for the minimum V <sub>DD</sub> Monitor turn-on time.									
0: V <sub>DD</sub> Monitor Disabled.									
This bit indicates the current power supply status (V <sub>DD</sub> Monitor output).									
		•							
-				lefault)					
1. V[)]) WOIN		10 13 301 10	▼RST-HIGH・	ring setting	is required	i loi ariy Sys	storn that		
			oração Elas	h					
includes cod	e that write	s to and/or							
	e that write	s to and/or							
	I       VDDSTAT         Bit6         VDMEN: $V_{DI}$ This bit turns       resets until it         The V <sub>DD</sub> Mo       ing the V <sub>DD</sub> ing the V <sub>DD</sub> Monit       1:         VDD Is at 0       1:         VDD is at 0       1:         VDD is about       1:         VDMLVL:       V <sub>I</sub> 0:       V <sub>DD</sub> Monit	IVDDSTATVDMLVLBit6Bit5VDMEN: $V_{DD}$ Monitor EThis bit turns the $V_{DD}$ monitor EThis bit turns the $V_{DD}$ monitor can being the $V_{DD}$ Monitor can being the $V_{DD}$ monitor asreset. See Table 12.1 fc0: $V_{DD}$ Monitor Disabled1: $V_{DD}$ Monitor EnabledVDDSTAT: $V_{DD}$ Status.This bit indicates the cu0: $V_{DD}$ is at or below the1: $V_{DD}$ is above the $V_{DD}$ VDMLVL: $V_{DD}$ Level See0: $V_{DD}$ Monitor Thresho	IVDDSTATVDMLVLReservedBit6Bit5Bit4VDMEN: $V_{DD}$ Monitor Enable.This bit turns the $V_{DD}$ monitor circularesets until it is also selected as a random the V_{DD} Monitor can be allowed to ing the V_{DD} monitor can be allowed to ing the V_{DD} monitor as a reset set reset. See Table 12.1 for the minim0: $V_{DD}$ Monitor Disabled.1: $V_{DD}$ Monitor Enabled (default).VDDSTAT: $V_{DD}$ Status.This bit indicates the current power0: $V_{DD}$ is at or below the $V_{DD}$ Monitor The VDMLVL: $V_{DD}$ Level Select.0: $V_{DD}$ Monitor Threshold is set to Y	IVDDSTATVDMLVLReservedReservedBit6Bit5Bit4Bit3VDMEN: $V_{DD}$ Monitor Enable.This bit turns the $V_{DD}$ monitor circuit on/off. The resets until it is also selected as a reset source to the $V_{DD}$ Monitor can be allowed to stabilize be ing the $V_{DD}$ monitor as a reset source befor reset. See Table 12.1 for the minimum $V_{DD}$ Models0: $V_{DD}$ Monitor Disabled.1: $V_{DD}$ Monitor Enabled (default).VDDSTAT: $V_{DD}$ Status.This bit indicates the current power supply state 0: $V_{DD}$ is at or below the $V_{DD}$ Monitor Threshold.VDMLVL: $V_{DD}$ Level Select.0: $V_{DD}$ Monitor Threshold is set to $V_{RST-LOW}$ (contexpendence)	IVDDSTATVDMLVLReservedReservedReservedReservedBit6Bit5Bit4Bit3Bit2VDMEN: $V_{DD}$ Monitor Enable.This bit turns the $V_{DD}$ monitor circuit on/off. The $V_{DD}$ Monitor esets until it is also selected as a reset source in registerThe $V_{DD}$ Monitor can be allowed to stabilize before it is seting the $V_{DD}$ monitor as a reset source before it has statereset. See Table 12.1 for the minimum $V_{DD}$ Monitor turn-turned0: $V_{DD}$ Monitor Enabled.1: $V_{DD}$ Monitor Enabled (default).VDDSTAT: $V_{DD}$ Status.This bit indicates the current power supply status ( $V_{DD}$ Motion0: $V_{DD}$ is at or below the $V_{DD}$ Monitor Threshold.1: $V_{DD}$ is above the $V_{DD}$ Monitor Threshold.0: $V_{DD}$ Monitor Threshold is set to $V_{RST-LOW}$ (default).	IVDDSTATVDMLVLReservedReservedReservedReservedReservedBit6Bit5Bit4Bit3Bit2Bit1VDMEN: $V_{DD}$ Monitor Enable.This bit turns the $V_{DD}$ monitor circuit on/off. The $V_{DD}$ Monitor cannot generate the value of the val	IVDDSTATVDMLVLReservedReservedReservedReservedReservedReservedBit6Bit5Bit4Bit3Bit2Bit1Bit0SFR Address:VDMEN: $V_{DD}$ Monitor Enable.This bit turns the $V_{DD}$ monitor circuit on/off. The $V_{DD}$ Monitor cannot generate sy resets until it is also selected as a reset source in register RSTSRC (SFR Definiti The $V_{DD}$ Monitor can be allowed to stabilize before it is selected as a reset source <b>ing the <math>V_{DD}</math> monitor as a reset source before it has stabilized may generate</b> <b>reset.</b> See Table 12.1 for the minimum $V_{DD}$ Monitor turn-on time.0: $V_{DD}$ Monitor Enabled.1: $V_{DD}$ Monitor Enabled (default).VDDSTAT: $V_{DD}$ Status.This bit indicates the current power supply status ( $V_{DD}$ Monitor output).0: $V_{DD}$ is at or below the $V_{DD}$ Monitor Threshold.1: $V_{DD}$ is above the $V_{DD}$ Monitor Threshold.VDMLVL: $V_{DD}$ Level Select.		

## SFR Definition 12.1. VDDMON: V<sub>DD</sub> Monitor Control

## 12.3. External Reset

The external RST pin provides a means for external circuitry to force the device into a reset state. As<u>serting</u> an active-low signal on the RST pin generates a reset; an external pullup and/or decoupling of the RST pin may be necessary to avoid erroneous noise-induced resets. See Table 12.1 for complete RST pin specifications. The PINRSF flag (RSTSRC.0) is set on exit from an external reset.

## 12.4. Missing Clock Detector Reset

The Missing Clock Detector (MCD) is a one-shot circuit that is triggered by the system clock. If the system clock remains high or low for more than 100  $\mu$ s, the one-shot will time out and generate a reset. After a MCD reset, the MCDRSF flag (RSTSRC.2) will read '1', signifying the MCD as the reset source; otherwise, this bit reads '0'. Writing a '1' to the MCDRSF bit enables the Missing Clock Detector; writing a '0' disables it. The state of the RST pin is unaffected by this reset.

## 12.5. Comparator Reset

Comparator0 can be configured as a reset source by writing a '1' to the CORSEF flag (RSTSRC.5). Comparator0 should be enabled and allowed to settle prior to writing to CORSEF to prevent any turn-on chatter on the output from generating an unwanted reset. The Comparator0 reset is active-low: if the non-



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inverting input voltage (on CP0+) is less than the inverting input voltage (on CP0-), the device is put into the reset state. After a Comparator0 reset, the C0RSEF flag (RSTSRC.5) will read '1' signifying Comparator0 as the reset source; otherwise, this bit reads '0'. The state of the RST pin is unaffected by this reset.

## 12.6. PCA Watchdog Timer Reset

The programmable Watchdog Timer (WDT) function of the Programmable Counter Array (PCA) can be used to prevent software from running out of control during a system malfunction. The PCA WDT function can be enabled or disabled by software as described in Section "20.3. Watchdog Timer Mode" on page 205; the WDT is enabled and clocked by SYSCLK / 12 following any reset. If a system malfunction prevents user software from updating the WDT, a reset is generated and the WDTRSF bit (RSTSRC.5) is set to '1'. The state of the RST pin is unaffected by this reset.

## 12.7. Flash Error Reset

If a Flash read/write/erase or program read targets an illegal address, a system reset is generated. This may occur due to any of the following:

- A Flash write or erase is attempted above user code space. This occurs when PSWE is set to '1' and a MOVX write operation targets an address above the Lock Byte address.
- A Flash read is attempted above user code space. This occurs when a MOVC operation targets an address above the Lock Byte address.
- A program read is attempted above user code space. This occurs when user code attempts to branch to an address above the Lock Byte address.
- A Flash read, write or erase attempt is restricted due to a Flash security setting (see Section "13.4. Security Options" on page 114).
- A Flash write or erase is attempted while the V<sub>DD</sub> Monitor is disabled.

The FERROR bit (RSTSRC.6) is set following a Flash error reset. The state of the  $\overline{RST}$  pin is unaffected by this reset.

## 12.8. Software Reset

Software may force a reset by writing a '1' to the SWRSF bit (RSTSRC.4). The SWRSF bit will read '1' following a software forced reset. The state of the RST pin is unaffected by this reset.



## SFR Definition 12.2. RSTSRC: Reset Source

R/W	R	R/W	R/W	R	R/W	R/W	R	Reset Value						
—	FERROR	CORSEF	SWRSF	WDTRSF	MCDRSF	PORSF	PINRSF	Variable						
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	<b>_</b>						
							SFR Address	: 0xEF						
Note: Sc	Note: Software should avoid read modify write instructions when writing values to RSTSRC.													
Bit7:	UNUSED. R	ead = 1, W	rite = don't	care.										
Bit6:	FERROR: Flash Error Indicator.													
	0: Source of	last reset w	vas not a F	lash read/w	rite/erase er	ror.								
	1: Source of													
Bit5:	CORSEF: Co													
	0: Read: So				ator0.									
		mparator0 i			<u> </u>									
	<ol> <li>Read: Source of last reset was Comparator0.</li> <li>Write: Comparator0 is a reset source (active-low).</li> </ol>													
Bit4:	SWRSF: So				e-10w).									
DIL4.	0: <b>Read:</b> So			0	the SWRS	E bit								
	Write: No		16361 Was			n bit.								
	1: <b>Read:</b> So		reset was	a write to th	e SWRSF b	it.								
		rces a syste												
Bit3:	WDTRSF: W			Flag.										
	0: Source of last reset was not a WDT timeout.													
	1: Source of	last reset w	as a WDT	timeout.										
Bit2:	MCDRSF: M	lissing Cloc	k Detector	Flag.										
	0: Read: So				g Clock Det	ector timed	out.							
		ssing Clock				_								
	1: Read: So			-										
		Vrite: Missing Clock Detector enabled; triggers a reset if a missing clock condition is												
D:44	detected.	war On Daa	ot Force of											
Bit1:	PORSF: Po			-	Writing thi	e hit onahl	ac/disables	tho V						
	This bit is set anytime a power-on reset occurs. Writing this bit enables/disables the $V_{DD}$ monitor as a reset source. Note: writing '1' to this bit before the $V_{DD}$ monitor is enabled													
	and stabilized may cause a system reset. See register VDDMON (SFR Definition 12.1) 0: Read: Last reset was not a power-on or V <sub>DD</sub> monitor reset.													
			•			301.								
	Write: V <sub>DD</sub> monitor is not a reset source. 1: Read: Last reset was a power-on or V <sub>DD</sub> monitor reset; all other reset flags indetermi-													
		st reset was	a power-c	on or v <sub>DD</sub> me	onitor reset;	all other re	eset flags in	determi-						
	nate. Write: Vp	<sub>D</sub> monitor is	a reset so	urce										
Bit0:	PINRSF: HV	-												
Bito.			· ·	 T pin										
	0: Source of last reset was <u>not R</u> ST pin. 1: Source of last reset was <del>RST</del> pin.													



#### **Table 12.1. Reset Electrical Characteristics**

-40 to +125 °C unless otherwise specified.

Parameter	Conditions	Min	Тур	Max	Units
RST Output Low Voltage	I <sub>OL</sub> = 8.5 mA, V <sub>DD</sub> = 2.1 V	_		0.8	V
RST Input High Voltage		0.7 x V <sub>REGIN</sub>		_	V
RST Input Low Voltage				0.3 x V <sub>REGIN</sub>	V
RST Input Pullup Impedance	V <sub>REGIN</sub> = 3.3 V		126	_	kΩ
RST Input Pullup V <sub>REGIN</sub> Sensitivity <sup>1</sup>			-34.8	_	kΩ/V
V Monitor Throshold (V )	C8051F52x/53x	1.8	1.9	2.0	V
$V_{DD}$ Monitor Threshold ( $V_{RST-LOW}$ )	C8051F52xA/53xA	1.7	1.75	1.8	V
V <sub>DD</sub> Monitor Threshold (V <sub>RST-HIGH</sub> )	C8051F52x/53x	2.1	2.2	2.3	V
ADD Monitor Threshold (AKSI-HIGH)	C8051F52xA/53xA	2.25	2.3	2.4	V
Missing Clock Detector Timeout	Time from last system clock rising edge to reset initiation	TBD	350	650	μs
Reset Time Delay <sup>2</sup>	Delay between release of any reset source and code execution at loca- tion 0x0000	_	_	350	μs
Minimum RST Low Time to Generate a System Reset		TBD	_	—	μs
V <sub>DD</sub> Monitor Turn-on Time			TBD	—	μs
V <sub>DD</sub> Monitor Supply Current	V <sub>DD</sub> = 2.1 V	_	23	TBD	μA
Notes:		-		•	

Notes:

1. The  $\overline{\text{RST}}$  Input Pullup Impedance can be estimated by taking the impendance at a V<sub>REGIN</sub> of 3.3 V minus the difference in impendance indicated by the sensitivity number. For example: V<sub>REGIN</sub> = 5 V; Impedance = 126 k  $\Omega$  - (3.3 V - 5 V) \* -34.8 k $\Omega$ /V = 60 k $\Omega$ .

2. Refer to Section "21. Device Specific Behavior" on page 213.



### 13. Flash Memory

On-chip, re-programmable Flash memory is included for program code and non-volatile data storage. The Flash memory can be programmed in-system through the C2 interface or by software using the MOVX write instruction. Once cleared to logic 0, a Flash bit must be erased to set it back to logic 1. Flash bytes would typically be erased (set to 0xFF) before being reprogrammed. The write and erase operations are automatically timed by hardware for proper execution; data polling to determine the end of the write/erase operations is not required. Code execution is stalled during Flash write/erase operations. Refer to Table 13.2 for complete Flash memory electrical characteristics.

#### 13.1. Programming The Flash Memory

The simplest means of programming the Flash memory is through the C2 interface using programming tools provided by Silicon Laboratories or a third party vendor. This is the only means for programming a non-initialized device. For details on the C2 commands to program Flash memory, see Section "22. C2 Interface" on page 216.

To protect the integrity of Flash contents, the  $V_{DD}$  monitor must be enabled to the higher setting (VDMLVL = '1') and selected as a reset source if software contains routines which erase or write Flash memory. If the  $V_{DD}$  monitor is not enabled, any erase or write performed on Flash memory will cause a Flash Error device reset.

The V<sub>DD</sub> monitor must be enabled before it is selected as a reset source. Selecting the V<sub>DD</sub> monitor as a reset source before it is enabled and stabilized may cause a system reset. The procedure for reenabling the V<sub>DD</sub> monitor and configuring the V<sub>DD</sub> monitor as a reset source is shown below:

- Step 1. Enable the  $V_{DD}$  monitor (VDMEN bit in VDDMON = '1').
- Step 2. Wait for the V<sub>DD</sub> monitor to stabilize (see Table 12.1 for the V<sub>DD</sub> Monitor turn-on time).
   Note: This delay should be omitted if software contains routines which write or erase Flash memory.
- Step 3. Select the  $V_{DD}$  monitor as a reset source (PORSF bit in RSTSRC = '1').

#### 13.1.1. Flash Lock and Key Functions

Flash writes and erases by user software are protected with a lock and key function. The Flash Lock and Key Register (FLKEY) must be written with the correct key codes, in sequence, before Flash operations may be performed. The key codes are: 0xA5, 0xF1. The timing does not matter, but the codes must be written in order. If the key codes are written out of order, or the wrong codes are written, Flash writes and erases will be disabled until the next system reset. Flash writes and erases will also be disabled if a Flash write or erase is attempted before the key codes have been written properly. The Flash lock resets after each write or erase; the key codes must be written again before a following Flash operation can be performed. The FLKEY register is detailed in SFR Definition 13.2.



#### 13.1.2. Flash Erase Procedure

The Flash memory can be programmed by software using the MOVX write instruction with the address and data byte to be programmed provided as normal operands. Before writing to Flash memory using MOVX, Flash write operations must be enabled by: (1) setting the PSWE Program Store Write Enable bit (PSCTL.0) to logic 1 (this directs the MOVX writes to target Flash memory); and (2) Writing the Flash key codes in sequence to the Flash Lock register (FLKEY). The PSWE bit remains set until cleared by software.

A write to Flash memory can clear bits to logic 0 but cannot set them; only an erase operation can set bits to logic 1 in Flash. A byte location to be programmed should be erased before a new value is written. The Flash memory is organized in 512-byte pages. The erase operation applies to an entire page (setting all bytes in the page to 0xFF). To erase an entire 512-byte page, perform the following steps:

- Step 1. Disable interrupts (recommended).
- Step 2. Write the first key code to FLKEY: 0xA5.
- Step 3. Write the second key code to FLKEY: 0xF1.
- Step 4. Set the PSEE bit (register PSCTL).
- Step 5. Set the PSWE bit (register PSCTL).
- Step 6. Using the MOVX instruction, write a data byte to any location within the 512-byte page to be erased.
- Step 7. Clear the PSWE and PSEE bits.
- Step 8. Re-enable interrupts.

#### 13.1.3. Flash Write Procedure

Flash bytes are programmed by software with the following sequence:

- Step 1. Disable interrupts.
- Step 2. Write the first key code to FLKEY: 0xA5.
- Step 3. Write the second key code to FLKEY: 0xF1.
- Step 4. Set the PSWE bit (register PSCTL).
- Step 5. Clear the PSEE bit (register PSCTL).
- Step 6. Using the MOVX instruction, write a single data byte to the desired location within the 512byte sector.
- Step 7. Clear the PSWE bit.
- Step 8. Re-enable interrupts.

Steps 2–7 must be repeated for each byte to be written. After Flash writes are complete, PSWE should be cleared so that MOVX instructions do not target program memory.



#### 13.2. Flash Write and Erase Guidelines

Any system which contains routines which write or erase Flash memory from software involves some risk that the write or erase routines will execute unintentionally if the CPU is operating outside its specified operating range of  $V_{DD}$ , system clock frequency, or temperature. This accidental execution of Flash modifying code can result in alteration of Flash memory contents causing a system failure that is only recoverable by re-Flashing the code in the device.

The following guidelines are recommended for any system which contains routines which write or erase Flash from code.

#### 13.2.1. $V_{DD}$ Maintenance and the $V_{DD}$ monitor

- 1. If the system power supply is subject to voltage or current "spikes," add sufficient transient protection devices to the power supply to ensure that the supply voltages listed in the Absolute Maximum Ratings table are not exceeded.
- 2. Make certain that the minimum  $V_{DD}$  rise time specification of 1 ms is met. If the system cannot meet this rise time specification, then add an external  $V_{DD}$  brownout circuit to the  $\overline{RST}$  pin of the device that holds the device in reset until  $V_{DD}$  reaches 1.8 V and re-asserts  $\overline{RST}$  if  $V_{DD}$  drops below 1.8 V.
- 3. Enable the on-chip V<sub>DD</sub> monitor and enable the V<sub>DD</sub> monitor as a reset source as early in code as possible. This should be the first set of instructions executed after the Reset Vector. For 'C'-based systems, this will involve modifying the startup code added by the 'C' compiler. See your compiler documentation for more details. Make certain that there are no delays in software between enabling the V<sub>DD</sub> monitor and enabling the V<sub>DD</sub> monitor as a reset source. Code examples showing this can be found in "AN201: Writing to Flash from Firmware", available from the Silicon Laboratories web site.
- 4. As an added precaution, explicitly enable the V<sub>DD</sub> monitor and enable the V<sub>DD</sub> monitor as a reset source inside the functions that write and erase Flash memory. The V<sub>DD</sub> monitor enable instructions should be placed just after the instruction to set PSWE to a '1', but before the Flash write or erase operation instruction.
- 5. Make certain that all writes to the RSTSRC (Reset Sources) register use direct assignment operators and explicitly DO NOT use the bit-wise operators (such as AND or OR). For example, "RSTSRC = 0x02" is correct. "RSTSRC |= 0x02" is incorrect.
- 6. Make certain that all writes to the RSTSRC register explicitly set the PORSF bit to a '1'. Areas to check are initialization code which enables other reset sources, such as the Missing Clock Detector or Comparator, for example, and instructions which force a Software Reset. A global search on "RSTSRC" can quickly verify this.

#### 13.2.2. PSWE Maintenance

- 7. Reduce the number of places in code where the PSWE bit (PSCTL.0) is set to a '1'. There should be exactly one routine in code that sets PSWE to a '1' to write Flash bytes and one routine in code that sets PSWE and PSEE both to a '1' to erase Flash pages.
- 8. Minimize the number of variable accesses while PSWE is set to a '1'. Handle pointer address updates and loop variable maintenance outside the "PSWE = 1; ... PSWE = 0;" area. Code examples showing this can be found in "AN201: Writing to Flash from Firmware," available from the Silicon Laboratories web site.
- 9. Disable interrupts prior to setting PSWE to a '1' and leave them disabled until after PSWE has been reset to '0'. Any interrupts posted during the Flash write or erase operation will be serviced in priority order after the Flash operation has been completed and interrupts have been re-enabled by software.



- 10. Make certain that the Flash write and erase pointer variables are not located in XRAM. See your compiler documentation for instructions regarding how to explicitly locate variables in different memory areas.
- 11. Add address bounds checking to the routines that write or erase Flash memory to ensure that a routine called with an illegal address does not result in modification of the Flash.

#### 13.2.3. System Clock

- 12. If operating from an external crystal, be advised that crystal performance is susceptible to electrical interference and is sensitive to layout and to changes in temperature. If the system is operating in an electrically noisy environment, use the internal oscillator or use an external CMOS clock.
- 13. If operating from the external oscillator, switch to the internal oscillator during Flash write or erase operations. The external oscillator can continue to run, and the CPU can switch back to the external oscillator after the Flash operation has completed.

Additional Flash recommendations and example code can be found in "AN201: Writing to Flash from Firmware," available from the Silicon Laboratories web site.



#### 13.3. Non-volatile Data Storage

The Flash memory can be used for non-volatile data storage as well as program code. This allows data such as calibration coefficients to be calculated and stored at run time. Data is written using the MOVX write instruction and read using the MOVC instruction. Note: MOVX read instructions always target XRAM.

#### 13.4. Security Options

The CIP-51 provides security options to protect the Flash memory from inadvertent modification by software as well as to prevent the viewing of proprietary program code and constants. The Program Store Write Enable (bit PSWE in register PSCTL) and the Program Store Erase Enable (bit PSEE in register PSCTL) bits protect the Flash memory from accidental modification by software. PSWE must be explicitly set to '1' before software can modify the Flash memory; both PSWE and PSEE must be set to '1' before software can erase Flash memory. Additional security features prevent proprietary program code and data constants from being read or altered across the C2 interface.

A Security Lock Byte located at the last byte of Flash user space offers protection of the Flash program memory from access (reads, writes, or erases) by unprotected code or the C2 interface. The Flash security mechanism allows the user to lock n 512-byte Flash pages, starting at page 0 (addresses 0x0000 to 0x01FF), where n is the 1's complement number represented by the Security Lock Byte. Note that the page containing the Flash Security Lock Byte is unlocked when no other Flash pages are locked (all bits of the Lock Byte are '1') and locked when any other Flash pages are locked (any bit of the Lock Byte is '0'). See example below.

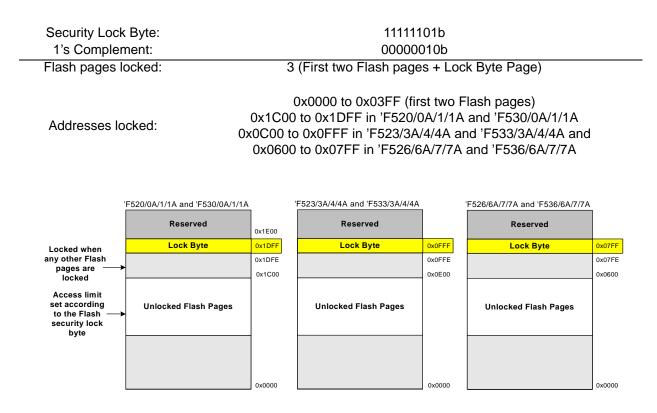


Figure 13.1. Flash Program Memory Map



The level of Flash security depends on the Flash access method. The three Flash access methods that can be restricted are reads, writes, and erases from the C2 debug interface, user firmware executing on unlocked pages, and user firmware executing on locked pages. Table 13.1 summarizes the Flash security features of the 'F52x/'F52xA/'F53xA devices.

Action	C2 Debug	User Firmware e	executing from:
	Interface	an unlocked page	a locked page
Read, Write or Erase unlocked pages (except page with Lock Byte)	Permitted	Permitted	Permitted
Read, Write or Erase locked pages (except page with Lock Byte)	Not Permitted	Flash Error Reset	Permitted
Read or Write page containing Lock Byte (if no pages are locked)	Permitted	Permitted	Permitted
Read or Write page containing Lock Byte (if any page is locked)	Not Permitted	Flash Error Reset	Permitted
Read contents of Lock Byte (if no pages are locked)	Permitted	Permitted	Permitted
Read contents of Lock Byte (if any page is locked)	Not Permitted	Flash Error Reset	Permitted
Erase page containing Lock Byte (if no pages are locked)	Permitted	Flash Error Reset	Flash Error Reset
Erase page containing Lock Byte - Unlock all pages (if any page is locked)	C2 Device Erase Only	Flash Error Reset	Flash Error Reset
Lock additional pages (change '1's to '0's in the Lock Byte)	Not Permitted	Flash Error Reset	Flash Error Reset
Unlock individual pages (change '0's to '1's in the Lock Byte)	Not Permitted	Flash Error Reset	Flash Error Reset
Read, Write or Erase Reserved Area	Not Permitted	Flash Error Reset	Flash Error Reset

Table	13.1. F	lash	Security	Summary
10010		10011	oooanty	<b>o</b> anna y

C2 Device Erase - Erases all Flash pages including the page containing the Lock Byte.

Flash Error Reset - Not permitted; Causes Flash Error Device Reset (FERROR bit in RSTSRC is '1' after reset).

- All prohibited operations that are performed via the C2 interface are ignored (do not cause device reset).

- Locking any Flash page also locks the page containing the Lock Byte.

- Once written to, the Lock Byte cannot be modified except by performing a C2 Device Erase.

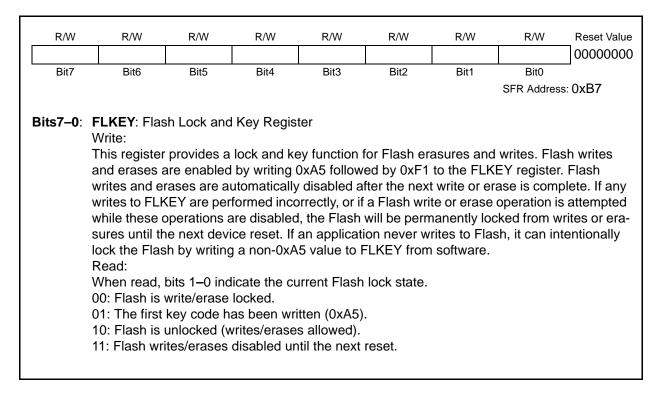
- If user code writes to the Lock Byte, the Lock does not take effect until the next device reset.



#### SFR Definition 13.1. PSCTL: Program Store R/W Control

R	R	R	R	R	R	R/W	R/W	Reset Value
-	-	-	-	-	-	PSEE	PSWE	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
							SFR Addres	s: 0x8F
Bits7–2: Bit1: Bit0:	UNUSED: R PSEE: Progr Setting this b to be erased Flash memo tion addresse 0: Flash prog PSWE: Prog Setting this b write instruct 0: Writes to F 1: Writes to F memory.	ram Store E bit (in combi . If this bit is ry using the ed by the N gram memo gram memo gram Store N bit allows we tion. The Fla Flash program	rase Enable nation with s logic 1 and MOVX instru- ory erasure Write Enable iting a byte ash location am memory	e PSWE) allo d Flash writ truction will ction. The v disabled. e of data to t n should be v disabled.	ws an entir es are enab erase the e alue of the he Flash pr erased befo	oled (PSWE entire page data byte w ogram men ore writing o	is logic 1) that contain written does nory using data.	, a write to ns the loca- s not matter. the MOVX

#### SFR Definition 13.2. FLKEY: Flash Lock and Key





### Table 13.2. Flash Electrical Characteristics

 $V_{DD}$  = 1.8 to 2.75 V; –40 to +125 °C unless otherwise specified

Parameter	Conditions	Min	Тур	Мах	Units
	'F520/0A/1/1A and 'F530/0A/1/1A	7680			
Flash Size	'F523/3A/4/4A and 'F533/3A/4/4A	4096	—	—	bytes
	'F526/6A/7/7A and 'F536/6A/7/7A	2048			
Endurance	V <sub>DD</sub> is 2.25 V or greater	40 k	150 k	_	Erase/Write
Erase Cycle Time		32	40	48	ms
Write Cycle Time		76	92	114	μs
V <sub>DD</sub>	Write/Erase Operations	2.25	_		V

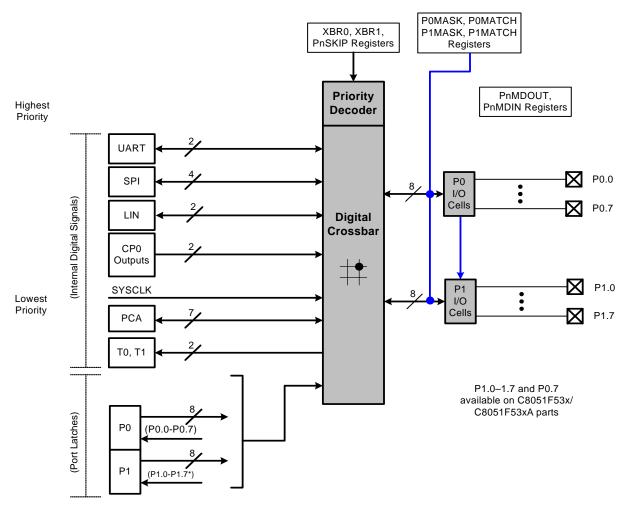


## 14. Port Input/Output

Digital and analog resources are available through up to 16 I/O pins. Port pins are organized as two or one byte-wide Ports. Each of the Port pins can be defined as general-purpose I/O (GPIO) or analog input/out-put; Port pins P0.0 - P1.7 can be assigned to one of the internal digital resources as shown in Figure 14.3. The designer has complete control over which functions are assigned, limited only by the number of physical I/O pins. This resource assignment flexibility is achieved through the use of a Priority Crossbar Decoder. Note that the state of a Port I/O pin can always be read in the corresponding Port latch, regardless of the Crossbar settings.

The Crossbar assigns the selected internal digital resources to the I/O pins based on the peripheral priority order of the Priority Decoder (Figure 14.3 and Figure 14.4). The registers XBR0 and XBR1, defined in SFR Definition 14.1 and SFR Definition 14.2, are used to select internal digital functions.

Port I/O pins are 5.25 V tolerant over the operating range of  $V_{REGIN}$ . Figure 14.2 shows the Port cell circuit. The Port I/O cells are configured as either push-pull or open-drain in the Port Output Mode registers (PnMDOUT, where n = 0,1). Complete Electrical Specifications for Port I/O are given in Table 14.1 on page 134.







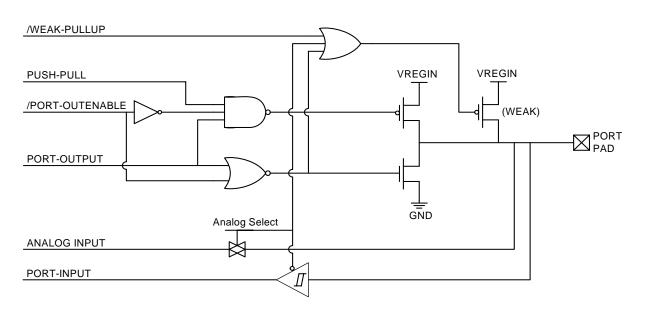
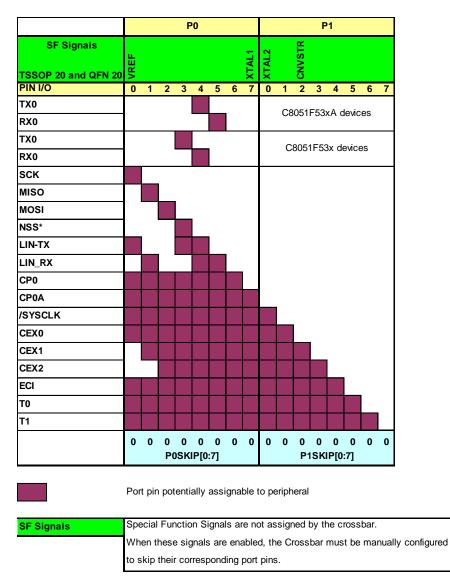


Figure 14.2. Port I/O Cell Block Diagram



#### 14.1. Priority Crossbar Decoder

The Priority Crossbar Decoder (Figure 14.3) assigns a priority to each I/O function, starting at the top with UART0. When a digital resource is selected, the least-significant unassigned Port pin is assigned to that resource (excluding UART0, which will be assigned to pins P0.4 and P0.5). If a Port pin is assigned, the Crossbar skips that pin when assigning the next selected resource. Additionally, the Crossbar will skip Port pins whose associated bits in the PnSKIP registers are set. The PnSKIP registers allow software to skip Port pins that are to be used for analog input, dedicated functions, or GPIO.



\*Note: 4-Wire SPI Only.

#### Figure 14.3. Crossbar Priority Decoder with No Pins Skipped (TSSOP 20 and QFN 20)

**Important Note on Crossbar Configuration**: If a Port pin is claimed by a peripheral without use of the Crossbar, its corresponding PnSKIP bit should be set. This applies to P1.0 and/or P0.7 ('F53x/'F53xA) or



P0.2 and/or P0.3 ('F52x/'F52xA) for the external oscillator, P0.0 for  $V_{REF}$ , P1.2 ('F53x/'F53xA) or P0.5 ('F52x/'F52xA) for the external CNVSTR signal, and any selected ADC or comparator inputs. The Crossbar skips selected pins as if they were already assigned, and moves to the next unassigned pin. Figure 14.3 shows the Crossbar Decoder priority with no Port pins skipped (P0SKIP, P1SKIP); Figure 14.4 shows the Crossbar Decoder priority with the XTAL1 (P1.0) and XTAL2 (P1.1) pins skipped (P1SKIP = 0x03).

**Important Note on UART Pins**: On C8051F52xA/53xA devices, the UART pins must be skipped if the UART is enabled in order for peripherals to appear on port pins beyond the UART on the crossbar. For example, with the SPI and UART enabled on the crossbar with the SPI on P1.0-P1.3, the UART pins must be skipped using P0SKIP for the SPI pins to appear correctly.



				F	0							F	י1			
SF Signals ISSOP 20 and QFN 20	VREF							XTAL1	XTAL2		CNVSTR					
PIN I/O	0	1	2	3	4	5	6	7	0	1	2	3	4	5	6	7
rxo											C80	51F4	53x/	A de	vices	
RXO											000	0113	5577	1 uc	vices	,
-X0													52	dev	icoc	
X0											00	5511	558	uev	1065	
SCK								1								
MISO																
MOSI																
ISS*																
IN-TX																
IN-RX																
P0																
POA																
SYSCLK																
EX0																
EX1																
EX2																
CI																
0																
1																
	0	0 P(	0 DSK	0 IP[0	0 :7] =	0 = 0x	0 80	1	1	0 P	0 1SK	0 1P[0	0 :7] :	0 = 0x	0 01	0
	Por	t pir	n pot	enti	ally	assi	gna	ble t	to pe	ərip	heral					
SF Signals	Spe	ecial	Fur	nctic	n S	ignal	s a	re no	ot as	ssig	ned	by tl	he c	ross	bar.	
											ross					nual
						bond										

\*Note: 4-Wire SPI Only.

### Figure 14.4. Crossbar Priority Decoder with Crystal Pins Skipped (TSSOP 20 and QFN 20)



SF Signals DFN10	VREF		XTAL1	XTAL2		CNVSTR	
PIN I/O	0	1	2	3	4	5	
ТХО							C8051F52xA devices
RX0							COUSTF32XA devices
ТХО							C8051F52x devices
RX0							COUSTF 52X devices
SCK					•		
MISO							
MOSI							
NSS*							
LIN-TX							
LIN_RX							
CP0							
CP0A							
/SYSCLK							
CEX0							
CEX1							
CEX2							
ECI							
ТО							
T1							
	0	0 P(	0 DSK	0 IP[0	0 :5]	0	
	Por	t pir	n poi	tenti	ally	ass	ignable to peripheral
SF Signals	Spe	ecial	Fu	nctio	on S	igna	Is are not assigned by the crossbar.
	Wh	en t	hes	e się	gnals	s are	e enabled, the Crossbar must be manually config
	to s	kip	thei	r co	rres	ponc	ling port pins.

\*Note: 4-Wire SPI Only.

### Figure 14.5. Crossbar Priority Decoder with No Pins Skipped (DFN 10)



			F	<b>0</b>		
SF Signals DFN 10	VREF		XTAL1	XTAL2	CNVSTR	
PIN I/O	0	1	2	3	45	
ТХО						C8051F52xA devices
RX0					_	
ТХО						C8051F52x devices
RX0						
SCK					_	
MISO						
MOSI						
NSS*						
LIN-TX						
LIN-RX						
CP0						
CP0A						
/SYSCLK						
CEX0						
CEX1						
CEX2						
ECI						
ТО						
T1						
	0 P(	1 0SK	1 IP[0	0 ):5] :	0 0 = 0x06	
	Poi	rt pin	i pot	tenti	ially ass	ignable to peripheral
SF Signals	Spe	ecial	Fur	nctio	on Signa	Is are not assigned by the crossbar.
	Wh	nen tl	hes	e się	gnals are	e enabled, the Crossbar must be manually configu
	to s	skip	thei	r co	rrespond	ling port pins.

\*Note: 4-Wire SPI Only.

#### Figure 14.6. Crossbar Priority Decoder with Some Pins Skipped (DFN 10)

Registers XBR0 and XBR1 are used to assign the digital I/O resources to the physical I/O Port pins. Note that when the SMBus is selected, the Crossbar assigns both pins associated with the SMBus (SDA and SCL); when the UART is selected, the Crossbar assigns both pins associated with the UART (TX and RX). UART0 pin assignments are fixed for bootloading purposes: UART TX0 is always assigned to P0.3 or P0.4\*; UART RX0 is always assigned to P0.4 or P0.5\*. Standard Port I/Os appear contiguously starting at P0.0 after prioritized functions and skipped pins are assigned.

\*Note: Refer to Section "21. Device Specific Behavior" on page 213.



**Important Note:** The SPI can be operated in either 3-wire or 4-wire modes, depending on the state of the NSSMD1–NSSMD0 bits in register SPI0CN. According to the SPI mode, the NSS signal may or may not be routed to a Port pin.

#### 14.2. Port I/O Initialization

Port I/O initialization consists of the following steps:

- Step 1. Select the input mode (analog or digital) for all Port pins, using the Port Input Mode register (PnMDIN).
- Step 2. Select the output mode (open-drain or push-pull) for all Port pins, using the Port Output Mode register (PnMDOUT).
- Step 3. Select any pins to be skipped by the I/O Crossbar using the Port Skip registers (PnSKIP).
- Step 4. Assign Port pins to desired peripherals using the XBRn registers.
- Step 5. Enable the Crossbar (XBARE = (1)).

All Port pins must be configured as either analog or digital inputs. Any pins to be used as Comparator or ADC inputs should be configured as an analog inputs. When a pin is configured as an analog input, its weak pullup, digital driver, and digital receiver are disabled. This process saves power and reduces noise on the analog input. Pins configured as digital inputs may still be used by analog peripherals; however, this practice is not recommended.

Additionally, all analog input pins should be configured to be skipped by the Crossbar (accomplished by setting the associated bits in PnSKIP). Port input mode is set in the PnMDIN register, where a '1' indicates a digital input, and a '0' indicates an analog input. All pins default to digital inputs on reset. See SFR Definition 14.4 for the PnMDIN register details.

Important Note: Port 0 and Port 1 pins are 5.25 V tolerant across the operating range of V<sub>REGIN</sub>.

The output driver characteristics of the I/O pins are defined using the Port Output Mode registers (PnMD-OUT). Each Port Output driver can be configured as either open drain or push-pull. This selection is required even for the digital resources selected in the XBRn registers, and is not automatic. When the WEAKPUD bit in XBR1 is '0', a weak pullup is enabled for all Port I/O configured as open-drain. WEAK-PUD does not affect the push-pull Port I/O. Furthermore, the weak pullup is turned off on an output that is driving a '0' and for pins configured for analog input mode to avoid unnecessary power dissipation.

Registers XBR0 and XBR1 must be loaded with the appropriate values to select the digital I/O functions required by the design. Setting the XBARE bit in XBR1 to '1' enables the Crossbar. Until the Crossbar is enabled, the external pins remain as standard Port I/O (in input mode), regardless of the XBRn Register settings. For given XBRn Register settings, one can determine the I/O pin-out using the Priority Decode Table.

The Crossbar must be enabled to use Port pins as standard Port I/O in output mode. **Port output drivers** are disabled while the Crossbar is disabled.



#### SFR Definition 14.1. XBR0: Port I/O Crossbar Register 0

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	CP0AE	CP0E	SYSCKE	LINE	SPI0E	URT0E	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
							SFR Address	s: 0xE1
Bit7-6:	RESERVED	. Read = 00	)b; Must wr	ite 00b.				
Bit5:	CP0AE: Cor	•	•	•	nable			
	0: Asynchro							
	1: Asynchro			•				
Bit4:	CP0E: Com		•	e				
	0: CP0 unav							
	1: CP0 route							
Bit3:	SYSCKE: /S		•					
	0: /SYSCLK		•					
	1: /SYSCLK			oin.				
Bit2:	LINE. Lin Ou		e					
Bit1:	SPIOE: SPI I							
	0: SPI I/O ur		•					
	1: SPI I/O ro			e that the SP	I can be as	signed eith	er 3 or 4 Gl	PIO pins.
Bit0:	URTOE: UA	•						
	0: UART I/O					/ <b>-</b>		
	1: UART TX	0, RX0 rout	ed to Port p	oins (P0.3 ai	nd P0.4) or	(P0.4 and F	-0.5).*	
* <b>Note:</b> Re	fer to Section "	21. Device S	pecific Beha	vior" on page	213.			



#### SFR Definition 14.2. XBR1: Port I/O Crossbar Register 1

R/W		R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
WEAKP		BARE	T1E	TOE	ECIE	Reserved			00000000
Bit7		Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
		2.110	2.10	2	2.10	2.12	2	SFR Addres	s: 0xF2
								0	
Bit7:	WEAK	KPUD: P	ort I/O We	ak Pullup	Disable.				
						ose I/O are o	configured	as analog	input).
			os disableo				U		• •
Bit6:	XBAR	RE: Cross	sbar Enabl	e.					
	0: Cro	ssbar dis	sabled.						
	1: Cro	ssbar en	abled.						
Bit5:	<b>T1E</b> : ]	T1 Enabl	е						
			ble at Port	pin.					
			Port pin.						
Bit4:	-	T0 Enabl	-						
			ble at Port	pin.					
			Port pin.						
Bit3:				unter Inpu	it Enable				
			able at Po						
Bit2:			o Port pin st Write 0						
				). /O Enable	Rite				
BIIST-U.				ble at Port					
			ed to Port		pins.				
				to Port pin	s				
				routed to F					
			, •=						
1									

#### 14.3. General Purpose Port I/O

Port pins that remain unassigned by the Crossbar and are not used by analog peripherals can be used for general purpose I/O. Ports P0–P1 are accessed through corresponding special function registers (SFRs) that are both byte addressable and bit addressable. When writing to a Port, the value written to the SFR is latched to maintain the output data value at each pin. When reading, the logic levels of the Port's input pins are returned regardless of the XBRn settings (i.e., even when the pin is assigned to another signal by the Crossbar, the Port register can always read its corresponding Port I/O pin). The exception to this is the execution of the read-modify-write instructions that target a Port Latch register as the destination. The read-modify-write instructions when operating on a Port SFR are the following: ANL, ORL, XRL, JBC, CPL, INC, DEC, DJNZ and MOV, CLR or SETB, when the destination is an individual bit in a Port SFR. For these instructions, the value of the latch register (not the pin) is read, modified, and written back to the SFR.

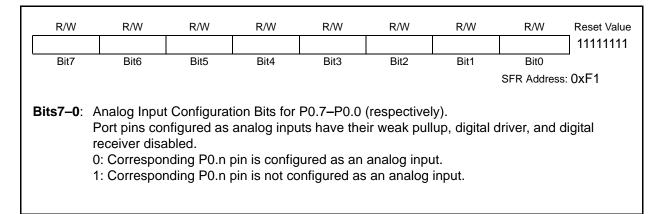


In addition to performing general purpose I/O, P0 and P1 can generate a port match event if the logic levels of the Port's input pins match a software controlled value. A port match event is generated if (P0 & P0MASK) does not equal (P0MATCH & P0MASK) or if (P1 & P1MASK) does not equal (P1MATCH & P1MASK). This allows Software to be notified if a certain change or pattern occurs on P0 or P1 input pins regardless of the XBRn settings. A port match event can cause an interrupt if EMAT (EIE2.1) is set to '1' or cause the internal oscillator to awaken from SUSPEND mode. See Section "15.1.1. Internal Oscillator Suspend Mode" on page 136 for more information.

### SFR Definition 14.3. P0: Port0

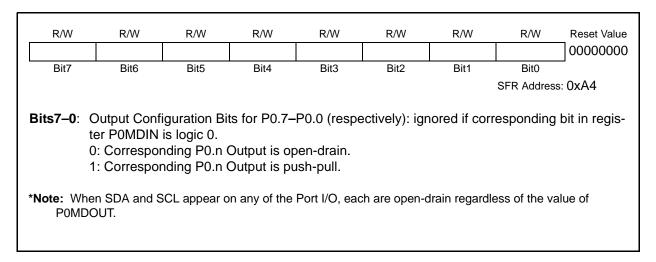
R/W P0.7	R/W P0.6	R/W P0.5	R/W P0.4	R/W P0.3	R/W P0.2	R/W P0.1	R/W P0.0	Reset Value
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressable
							SFR Address	s: 0x80
Bits7–0:	P0.[7:0] Write - Outpu 0: Logic Low 1: Logic High Read - Alway pin when cor 0: P0.n pin is 1: P0.n pin is	Output. Output (hi ys reads '0' ofigured as logic low.	gh impedar if selected digital input	nce if corres as analog i	ponding PC	)MDOUT.n	,	reads Port

### SFR Definition 14.4. P0MDIN: Port0 Input Mode

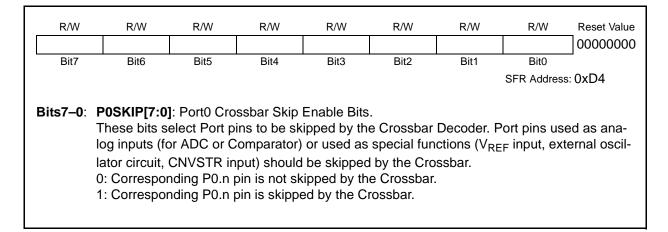




#### SFR Definition 14.5. P0MDOUT: Port0 Output Mode

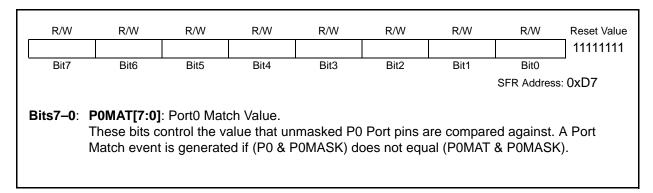


#### SFR Definition 14.6. P0SKIP: Port0 Skip

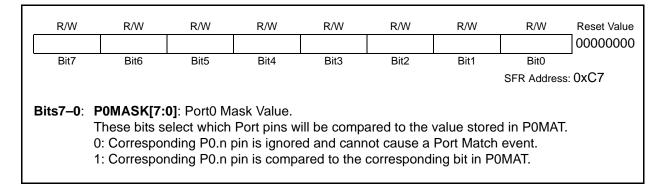




### SFR Definition 14.7. P0MAT: Port0 Match



### SFR Definition 14.8. P0MASK: Port0 Mask

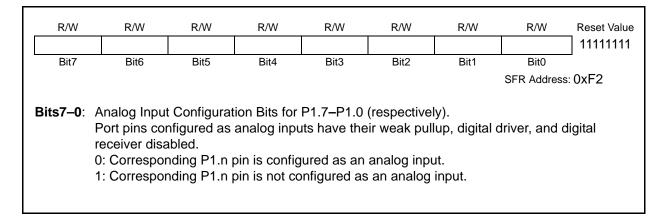




#### SFR Definition 14.9. P1: Port1

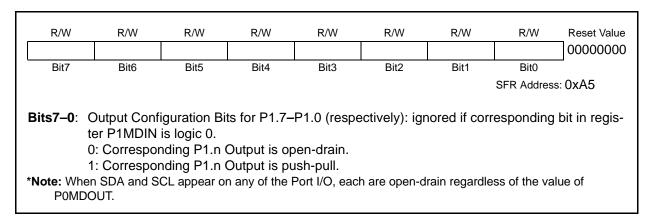
R/W P1.7	R/W P1.6	R/W P1.5	R/W P1.4	R/W P1.3	R/W P1.2	R/W P1.1	R/W P1.0	Reset Value
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressable
							SFR Address	s: 0x90
	Write - Outpu 0: Logic Low 1: Logic High Read - Alway pin when cor 0: P1.n pin is 1: P1.n pin is	Output. Output (h /s reads '0' nfigured as logic low.	igh impedar ' if selected digital input	nce if corres as analog i	sponding P1	1MDOUT.n	,	reads Port

#### SFR Definition 14.10. P1MDIN: Port1 Input Mode

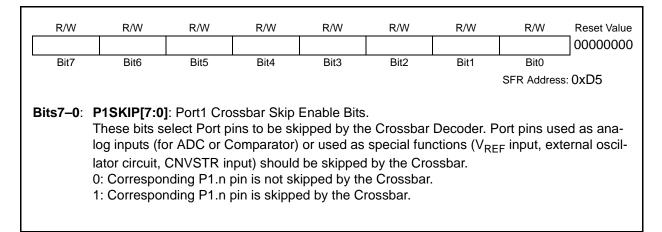




#### SFR Definition 14.11. P1MDOUT: Port1 Output Mode



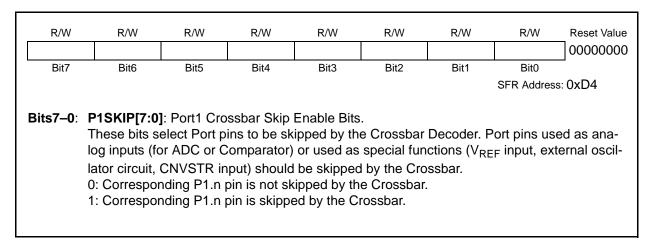
SFR Definition 14.12. P1SKIP: Port1 Skip



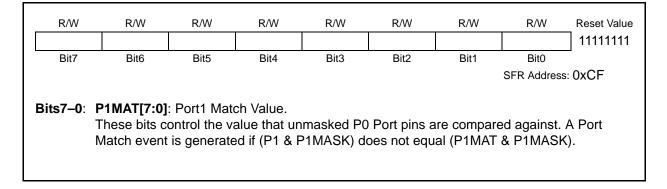
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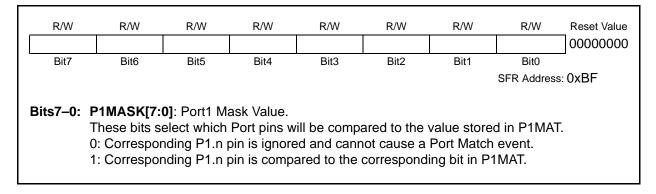
### SFR Definition 14.13. P0SKIP: Port0 Skip



### SFR Definition 14.14. P1MAT: Port1 Match



#### SFR Definition 14.15. P1MASK: Port1 Mask





### Table 14.1. Port I/O DC Electrical Characteristics

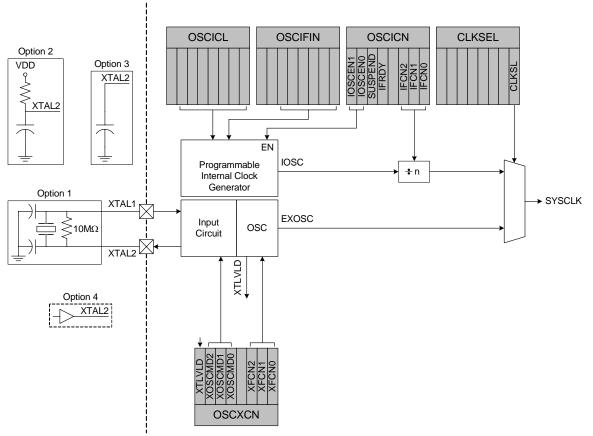
 $V_{REGIN}$  = 2.7 to 5.25 V, –40 to +125 °C unless otherwise specified

Parameters	Conditions	Min	Тур	Max	Units
	I <sub>OH</sub> = –3 mA, Port I/O push-pull	V <sub>REGIN</sub> – 0.4	_	_	
Output High Voltage	I <sub>OH</sub> = −10 μA, Port I/O push-pull	V <sub>REGIN</sub> – 0.02	—	_	V
voltage	I <sub>OH</sub> = –10 mA, Port I/O push-pull	—	V <sub>REGIN</sub> -0.7	—	
	V <sub>REGIN</sub> = 1.8 V:				
	I <sub>OL</sub> = 70 μA	—	—	50	
	I <sub>OL</sub> = 8.5 mA	—	—	750	
Output Low	V <sub>REGIN</sub> = 2.7 V:				
Voltage	I <sub>OL</sub> = 70 μA	—	—	45	mV
vollago	I <sub>OL</sub> = 8.5 mA	—	—	550	
	V <sub>REGIN</sub> = 5.25 V:				
	I <sub>OL</sub> = 70 μA	—	—	40	
	I <sub>OL</sub> = 8.5 mA	—	—	400	
Input High Voltage		V <sub>REGIN</sub> x 0.65	_	_	V
Input Low Voltage			_	V <sub>REGIN</sub> x 0.3	V
	Weak Pullup Off	—	—	±2	
	C8051F52xA/53xA:		. 6	TDD	
Input Leakage Current	Weak Pullup On, V <sub>IN</sub> = 0 V; V <sub>REGIN</sub> = 1.8 V	_	< 5	TBD	μA
	C8051F52x/52xA/53x/53xA:				
	Weak Pullup On, V <sub>IN</sub> = 0 V; V <sub>REGIN</sub> = 2.7 V	—	< 20	50	
	Weak Pullup On, $V_{IN} = 0$ V; $V_{REGIN} = 5.25$ V	—	< 65	115	



### 15. Oscillators

C8051F52x/F52xA/F53x/F53xA devices include a programmable internal oscillator, an external oscillator drive circuit. The internal oscillator can be enabled/disabled and calibrated using the OSCICN and OSCICL registers, as shown in Figure 15.1. The system clock (SYSCLK) can be derived from the internal oscillator, external oscillator circuit. Oscillator electrical specifications are given in Table 15.1 on page 145.





#### 15.1. Programmable Internal Oscillator

All C8051F52x/53x devices include a programmable internal oscillator that defaults as the system clock after a system reset. The internal oscillator period can be programmed via the OSCICL and OSCIFIN registers, shown in SFR Definition 15.2 and SFR Definition 15.3. On C8051F52x/53x devices, OSCICL and OSCIFIN are factory calibrated to obtain a 24.5 MHz frequency.

Electrical specifications for the precision internal oscillator are given in Table 15.1 on page 145. Note that the system clock may be derived from the programmed internal oscillator divided by 1, 2, 4, 8, 16, 32, 64, or 128 as defined by the IFCN bits in register OSCICN. The divide value defaults to 128 following a reset.



#### 15.1.1. Internal Oscillator Suspend Mode

When software writes a logic 1 to SUSPEND (OSCICN.5), the internal oscillator is suspended. If the system clock is derived from the internal oscillator, the input clock to the peripheral or CIP-51 will be stopped until one of the following events occur:

- Port 0 Match Event.
- Port 1 Match Event.
- Comparator 0 enabled and output is logic 0.

When one of the internal oscillator awakening events occur, the internal oscillator, CIP-51, and affected peripherals resume normal operation, regardless of whether the event also causes an interrupt. The CPU resumes execution at the instruction following the write to SUSPEND.

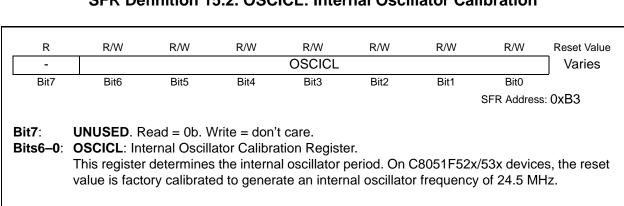


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### SFR Definition 15.1. OSCICN: Internal Oscillator Control

R/W	R/W	R/W	R	R	R/W	R/W	R/W	Reset Value	
IOSCEN	1 IOSCEN0	SUSPEND	IFRDY	-	IFCN2	IFCN1	IFCN0	11000000	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	1	
	SFR Address: 0xB2								
Bits7–6:	IOSCEN[1:0	-	scillator Er	nable Bits.					
	00: Oscillator								
	01: Reserved								
	10: Reserved			a da la val Di	abladia O		-l		
Bit5:	11: Oscillator SUSPEND: I					uspena ivio	de.		
DILJ.	Setting this b						noda Thair	ternal oscil-	
	lator resume	• •							
Bit4:	IFRDY: Interi					o awartonii	ig overne et	Jour.	
	0: Internal Os					ncy.			
	1: Internal Os								
Bit3:	UNUSED. R	ead = 0b, Wi	ite = don't	care.					
Bits2–0:	IFCN2-0: Int								
	000: SYSCL					``	lt).		
	001: SYSCL				•				
	010: SYSCL								
	011: SYSCL								
	100: SYSCL								
	101: SYSCLK derived from Internal Oscillator divided by 4. 110: SYSCLK derived from Internal Oscillator divided by 2.								
	111: SYSCLK derived from Internal Oscillator divided by 2.								





#### SFR Definition 15.2. OSCICL: Internal Oscillator Calibration

#### SFR Definition 15.3. OSCIFIN: Internal Fine Oscillator Calibration

R/W	R/W	R/W	R	R	R/W	R/W	R/W	Reset Value			
-	-		OSCIFIN undetermin								
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressable			
	SFR Address: 0xB0										
Bits7–6: UNUSED. Read = 00b, Write = don't care. Bits5–0: OSCIFIN. Internal oscillator fine adjustment bits.											
The valid range is between 0x00 and 0x27.											
This register is a fine adjustment for the internal oscillator period. On C8051F52x/52xA/53x/53xA devices, the reset value is factory calibrated to generate an											

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### 15.2. External Oscillator Drive Circuit

The external oscillator circuit may drive an external crystal, ceramic resonator, capacitor, or RC network. A CMOS clock may also provide a clock input. For a crystal or ceramic resonator configuration, the crystal/resonator must be wired across the XTAL1 and XTAL2 pins as shown in Option 1 of Figure 15.1. A 10 M $\Omega$  resistor also must be wired across the XTAL1 and XTAL2 pins for the crystal/resonator configuration. In RC, capacitor, or CMOS clock configuration, the clock source should be wired to the XTAL2 pin as shown in Option 2, 3, or 4 of Figure 15.1. The type of external oscillator must be selected in the OSCXCN register, and the frequency control bits (XFCN) must be selected appropriately (see SFR Definition 15.4. OSCXCN: External Oscillator Control).

**Important Note on External Oscillator Usage:** Port pins must be configured when using the external oscillator circuit. When the external oscillator drive circuit is enabled in crystal/resonator mode, Port pins P0.7 and P1.0 ('F53x/'F53xA) or P0.2 and P0.3 ('F52x/'F52xA) are used as XTAL1 and XTAL2 respectively. When the external oscillator drive circuit is enabled in capacitor, RC, or CMOS clock mode, Port pin P1.0 ('F53x/'F53xA) or P0.3 ('F52x/'F52xA) is used as XTAL2. The Port I/O Crossbar should be configured to skip the Port pins used by the oscillator circuit; see Section "14.1. Priority Crossbar Decoder" on page 120 for Crossbar configuration. Additionally, when using the external oscillator circuit in crystal/resonator, capacitor, or RC mode, the associated Port pins should be configured as **analog inputs**. In CMOS clock mode, the associated pin should be configured as a **digital input**. See Section "14.2. Port I/O Initialization" on page 125 for details on Port input mode selection.

#### 15.2.1. Clocking Timers Directly Through the External Oscillator

The external oscillator source divided by eight is a clock option for the timers (Section "19. Timers" on page 184) and the Programmable Counter Array (PCA) (Section "20. Programmable Counter Array (PCA0)" on page 197). When the external oscillator is used to clock these peripherals, but is not used as the system clock, the external oscillator frequency must be less than or equal to the system clock frequency. In this configuration, the clock supplied to the peripheral (external oscillator / 8) is synchronized with the system clock; the jitter associated with this synchronization is limited to  $\pm 0.5$  system clock cycles.

#### 15.2.2. External Crystal Example

If a crystal or ceramic resonator is used as an external oscillator source for the MCU, the circuit should be configured as shown in Figure 15.1, Option 1. The External Oscillator Frequency Control value (XFCN) should be chosen from the Crystal column of the table in SFR Definition 15.4. For example, a 12 MHz crystal requires an XFCN setting of 111b.



When the crystal oscillator is first enabled, the oscillator amplitude detection circuit requires a settling time to achieve proper bias. Introducing a delay of 1 ms between enabling the oscillator and checking the XTLVLD bit will prevent a premature switch to the external oscillator as the system clock. Switching to the external oscillator before the crystal oscillator has stabilized can result in unpredictable behavior. The recommended procedure is:

- Step 1. Configure XTAL1 and XTAL2 pins by writing '1' to the port latch.
- Step 2. Configure XTAL1 and XTAL2 as analog inputs.
- Step 3. Enable the external oscillator.
- Step 4. Wait at least 1 ms.
- Step 5. Poll for XTLVLD => '1'.
- Step 6. Switch the system clock to the external oscillator.

Note: Tuning-fork crystals may require additional settling time before XTLVLD returns a valid result.

The capacitors shown in the external crystal configuration provide the load capacitance required by the crystal for correct oscillation. These capacitors are "in series" as seen by the crystal and "in parallel" with the stray capacitance of the XTAL1 and XTAL2 pins.

**Note:** The load capacitance depends upon the crystal and the manufacturer. Please refer to the crystal data sheet when completing these calculations.

The equation for determining the load capacitance for two capacitors is:

$$C_L = \frac{C_A \times C_B}{C_A + C_B} + C_S$$

Where:

 $C_A$  and  $C_B$  are the capacitors connected to the crystal leads.

 $C_S$  is the total stray capacitance of the PCB.

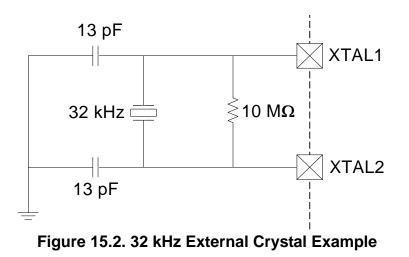
The stray capacitance for a typical layout where the crystal is as close as possible to the pins is 2-5 pF per pin.

If  $C_A$  and  $C_B$  are the same (C), then the equation becomes:

$$C_L = \frac{C}{2} + C_S$$

For example, a tuning-fork crystal of 32 kHz with a recommended load capacitance of 12.5 pF should use the configuration shown in Figure 15.1, Option 1. With a stray capacitance of 3 pF per pin (6 pF total), the 13 pF capacitors yield an equivalent capacitance of 12.5 pF across the crystal, as shown in Figure 15.2.





**Important Note on External Crystals:** Crystal oscillator circuits are quite sensitive to PCB layout. The crystal should be placed as close as possible to the XTAL pins on the device. The traces should be as short as possible and shielded with ground plane from any other traces which could introduce noise or interference.



#### 15.2.3. External RC Example

If an RC network is used as an external oscillator source for the MCU, the circuit should be configured as shown in Figure 15.1, Option 2. The capacitor should be no greater than 100 pF; however for very small capacitors, the total capacitance may be dominated by parasitic capacitance in the PCB layout. To determine the required External Oscillator Frequency Control value (XFCN) in the OSCXCN Register, first select the RC network value to produce the desired frequency of oscillation. If the frequency desired is 100 kHz, let R = 246 k $\Omega$  and C = 50 pF:

f = 1.23(10<sup>3</sup>) / RC = 1.23(10<sup>3</sup>) / [246 x 50] = 0.1 MHz = 100 kHz

Referring to the table in SFR Definition 15.4, the required XFCN setting is 010b. Programming XFCN to a higher setting in RC mode will improve frequency accuracy at a slightly increased external oscillator supply current.

#### 15.2.4. External Capacitor Example

If a capacitor is used as an external oscillator for the MCU, the circuit should be configured as shown in Figure 15.1, Option 3. The capacitor should be no greater than 100 pF; however for very small capacitors, the total capacitance may be dominated by parasitic capacitance in the PCB layout. To determine the required External Oscillator Frequency Control value (XFCN) in the OSCXCN Register, select the frequency of oscillation and calculate the capacitance to be used from the equations below. Assume  $V_{DD} = 2.1 \text{ V}$  and f = 75 kHz:

f = KF / (C x V<sub>DD</sub>) 0.075 MHz = KF / (C x 2.1)

Since the frequency of roughly 75 kHz is desired, select the K Factor from the table in SFR Definition 15.4 as KF = 7.7:

0.075 MHz = 7.7 / (C x 2.1)

C x 2.1 = 7.7 / 0.075 MHz

C = 102.6 / 2.0 pF = 51.3 pF

Therefore, the XFCN value to use in this example is 010b.



#### SFR Definition 15.4. OSCXCN: External Oscillator Control

R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
XTLVLD	XOSCMD2	XOSCMD1	(OSCMD0	Reserved	XFCN2	XFCN1	XFCN0	0000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
							SFR Address	:: 0xB1			
Bit7:	XTLVLD: Cr	ystal Oscilla	tor Valid Fl	ag. (Read o	nly when 3	KOSCMD =	= 11x.)				
	0: Crystal Os	scillator is ur	nused or no	ot yet stable			,				
Ritch A.	1: Crystal Oscillator is running and stable.										
DI130-4.	<b>XOSCMD2–0</b> : External Oscillator Mode Bits. 00x: External Oscillator circuit off.										
	010: Externa										
	011: Externa			vith divide by	2 stage						
	100: RC Osc				2 olago.						
	101: Capacit										
	110: Crystal										
	111: Crystal			vide by 2 st	age.						
Bit3:	RESERVED			•	-						
Bits2–0:	XFCN2-0: E				ol Bits.						
	000-111: See	e table belov	v:								
	XFCN	Crystal (X	DSCMD =	11x) RC	(XOSCME	0 = 10x)	C (XOSCN	/ID = 10x)			
	000	•	20 kHz	, -	, f ≤ 25 kH	,	K Factor	,			
	001		<f≤58 kh<="" td=""><td>z 25</td><td>kHz &lt; f ≤ s</td><td></td><td colspan="3">K Factor = 2.6</td></f≤58>	z 25	kHz < f ≤ s		K Factor = 2.6				
	010	58 kHz <	: f ≤ 155 kH	lz 50	$Hz < f \le 1$	00 kHz	K Facto	or = 7.7			
	011	155 kHz	< f ≤ 415 k	Hz 100	$kHz < f \le 2$	200 kHz	K Facto	or = 22			
	100	415 kHz	< f ≤ 1.1 M	Hz 200	kHz < f ≤ 4	400 kHz	K Facto	or = 65			
	101	1.1 MHz	< f ≤ 3.1 M	Hz 400	$kHz < f \le 8$	300 kHz	K Facto	r = 180			
	110	3.1 MHz	< f ≤ 8.2 M	Hz 800	$kHz < f \le T$	1.6 MHz	K Facto	or = 664			
	111		< f ≤ 25 MI		$MHz < f \le 3$		K Factor = 1590				
0											
Crystal W	lode (Circuit Choose XFC										
PC Mode	(Circuit from					ncy.					
	Choose XFC	•			,						
	$f = 1.23(10^3)$		•	cincy range	•						
	f = frequency										
	C = capacito										
	R = Pullup re	•									
C Mode (	Circuit from F			(OSCMD =	10x)						
	Choose K Fa	-	•		,	d.					
	f = KF / (C x			adon noquo		ч.					
	f = frequency										
	C = capacito			in nF							
	$V_{DD} = Powe$		•	•							
	· DD - 1 0 WC										



#### 15.3. System Clock Selection

The internal oscillator requires little start-up time and may be selected as the system clock immediately following the OSCICN write that enables the internal oscillator. External crystals and ceramic resonators typically require a start-up time before they are settled and ready for use. The Crystal Valid Flag (XTLVLD in register OSCXCN) is set to '1' by hardware when the external oscillator is settled. **To avoid reading a false XTLVLD in crystal mode, the software should delay at least 1 ms between enabling the external oscillator and checking XTLVLD.** RC and C modes typically require no startup time.

The CLKSL bit in register CLKSEL selects which oscillator source is used as the system clock. CLKSL must be set to '1' for the system clock to run from the external oscillator; however the external oscillator may still clock certain peripherals (timers, PCA) when another oscillator is selected as the system clock. The system clock may be switched on-the-fly between the internal oscillator and external oscillator, as long as the selected clock source is enabled and has settled.

R	R	R/W	R/W	R	R/W	R/W	R/W	Reset Value
-	-	Reserved	Reserved	-	Reserved	Reserved	CLKSL	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
							SFR Address:	0xA9
Bits5–4: Bit3:	Unused. Rea Reserved. R Unused. Rea Reserved. R <b>CLKSL</b> : Sys 0: Internal O 1: External O	ead = 00b; ad = 0b; Wr ead = 00b; stem Clock s scillator (as	Must write ite = don't c Must write Select	00b. care. 00b.	CN bits in re	gister OSCI	CN).	

### SFR Definition 15.5. CLKSEL: Clock Select



## Table 15.1. Oscillator Electrical Characteristics

 $V_{DD}$  = 1.8 to 2.75 V, -40 to +125 °C unless otherwise specified. Use factory-calibrated settings.

Parameter	Conditions	Min	Тур	Max	Units	
Oscillator Frequency	IFCN = 11b	24.5 - 0.5%	24.5*	24.5 + 0.5%	MHz	
Oscillator Supply Current (from V <sub>DD</sub> )	Internal Oscillator On OSCICN[7:6] = 11b	_	800	TBD		
	Internal Oscillator Suspend OSCICN[7:6] = 00b ZTCEN = 1	_	50	TBD	μA	
Wake-Up Time From	OSCICN[7:6] = 00b ZTCEN = 0	_	1	_	μs	
Suspend	OSCICN[7:6] = 00b ZTCEN = 1	_	5	_	Instruction Cycles	
*Note: This is the average freq	uency across the operating te	emperature range	Э.			

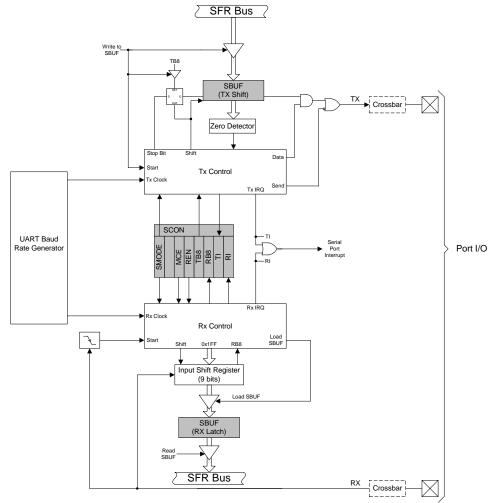


## 16. UART0

UART0 is an asynchronous, full duplex serial port offering modes 1 and 3 of the standard 8051 UART. Enhanced baud rate support allows a wide range of clock sources to generate standard baud rates (details in Section "16.1. Enhanced Baud Rate Generation" on page 147). Received data buffering allows UART0 to start reception of a second incoming data byte before software has finished reading the previous data byte. (Please refer to Section "21. Device Specific Behavior" on page 213 for more information on the pins associated with the UART interface.)

UART0 has two associated SFRs: Serial Control Register 0 (SCON0) and Serial Data Buffer 0 (SBUF0). The single SBUF0 location provides access to both transmit and receive registers. Writes to SBUF0 always access the Transmit register. Reads of SBUF0 always access the buffered Receive register; it is not possible to read data from the Transmit register.

With UART0 interrupts enabled, an interrupt is generated each time a transmit is completed (TI0 is set in SCON0), or a data byte has been received (RI0 is set in SCON0). The UART0 interrupt flags are not cleared by hardware when the CPU vectors to the interrupt service routine. They must be cleared manually by software, allowing software to determine the cause of the UART0 interrupt (transmit complete or receive complete).

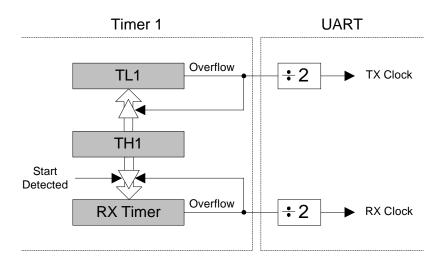






#### 16.1. Enhanced Baud Rate Generation

The UART0 baud rate is generated by Timer 1 in 8-bit auto-reload mode. The TX clock is generated by TL1; the RX clock is generated by a copy of TL1 (shown as RX Timer in Figure 16.2), which is not useraccessible. Both TX and RX Timer overflows are divided by two to generate the TX and RX baud rates. The RX Timer runs when Timer 1 is enabled, and uses the same reload value (TH1). However, an RX Timer reload is forced when a START condition is detected on the RX pin. This allows a receive to begin any time a START is detected, independent of the TX Timer state.





Timer 1 should be configured for Mode 2, 8-bit auto-reload (see Section "19.1.3. Mode 2: 8-bit Counter/Timer with Auto-Reload" on page 186). The Timer 1 reload value should be set so that overflows will occur at two times the desired UART baud rate frequency. Note that Timer 1 may be clocked by one of six sources: SYSCLK, SYSCLK / 4, SYSCLK / 12, SYSCLK / 48, the external oscillator clock / 8, or an external input T1. The UART0 baud rate is determined by Equation 16.1-A and Equation 16.1-B.

A) UartBaudRate = 
$$\frac{1}{2} \times T1_Overflow_Rate$$
  
B) T1\_Overflow\_Rate =  $\frac{T1_{CLK}}{256 - TH1}$ 

#### Equation 16.1. UART0 Baud Rate

Where  $T1_{CLK}$  is the frequency of the clock supplied to Timer 1, and T1H is the high byte of Timer 1 (8-bit auto-reload mode reload value). Timer 1 clock frequency is selected as described in Section "19. Timers" on page 184. A quick reference for typical baud rates and system clock frequencies is given in Table 16.1. Note that the internal oscillator may still generate the system clock when the external oscillator is driving Timer 1.



#### 16.2. Operational Modes

UART0 provides standard asynchronous, full duplex communication. The UART mode (8-bit or 9-bit) is selected by the S0MODE bit (SCON0.7). Typical UART connection options are shown below.

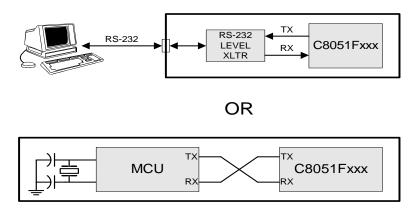


Figure 16.3. UART Interconnect Diagram

#### 16.2.1. 8-Bit UART

8-Bit UART mode uses a total of 10 bits per data byte: one start bit, eight data bits (LSB first), and one stop bit. Data are transmitted LSB first from the TX0 pin and received at the RX0 pin. On receive, the eight data bits are stored in SBUF0 and the stop bit goes into RB80 (SCON0.2).

Data transmission begins when software writes a data byte to the SBUF0 register. The TI0 Transmit Interrupt Flag (SCON0.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN0 Receive Enable bit (SCON0.4) is set to logic 1. After the stop bit is received, the data byte will be loaded into the SBUF0 receive register if the following conditions are met: RI0 must be logic 0, and if MCE0 is logic 1, the stop bit must be logic 1. In the event of a receive data overrun, the first received 8 bits are latched into the SBUF0 receive register and the following overrun data bits are lost.

If these conditions are met, the eight bits of data is stored in SBUF0, the stop bit is stored in RB80 and the RI0 flag is set. If these conditions are not met, SBUF0 and RB80 will not be loaded and the RI0 flag will not be set. An interrupt will occur if enabled when either TI0 or RI0 is set.

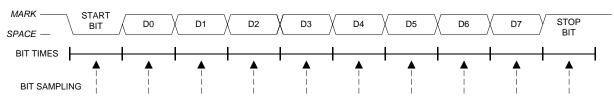


Figure 16.4. 8-Bit UART Timing Diagram



#### 16.2.2. 9-Bit UART

9-bit UART mode uses a total of eleven bits per data byte: a start bit, 8 data bits (LSB first), a programmable ninth data bit, and a stop bit. The state of the ninth transmit data bit is determined by the value in TB80 (SCON0.3), which is assigned by user software. It can be assigned the value of the parity flag (bit P in register PSW) for error detection, or used in multiprocessor communications. On receive, the ninth data bit goes into RB80 (SCON0.2) and the stop bit is ignored.

Data transmission begins when an instruction writes a data byte to the SBUF0 register. The TI0 Transmit Interrupt Flag (SCON0.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN0 Receive Enable bit (SCON0.4) is set to '1'. After the stop bit is received, the data byte will be loaded into the SBUF0 receive register if the following conditions are met: (1) RI0 must be logic 0, and (2) if MCE0 is logic 1, the 9th bit must be logic 1 (when MCE0 is logic 0, the state of the ninth data bit is unimportant). If these conditions are met, the eight bits of data are stored in SBUF0, the ninth bit is stored in RB80, and the RI0 flag is set to '1'. A UART0 interrupt will occur if enabled when either TI0 or RI0 is set to '1'.

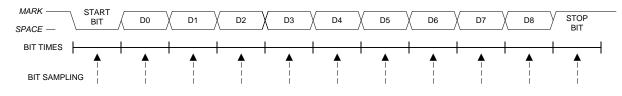


Figure 16.5. 9-Bit UART Timing Diagram

## 16.3. Multiprocessor Communications

9-Bit UART mode supports multiprocessor communication between a master processor and one or more slave processors by special use of the ninth data bit. When a master processor wants to transmit to one or more slaves, it first sends an address byte to select the target(s). An address byte differs from a data byte in that its ninth bit is logic 1; in a data byte, the ninth bit is always set to logic 0.

Setting the MCE0 bit (SCON0.5) of a slave processor configures its UART such that when a stop bit is received, the UART will generate an interrupt only if the ninth bit is logic 1 (RB80 = 1) signifying an address byte has been received. In the UART interrupt handler, software will compare the received address with the slave's own assigned 8-bit address. If the addresses match, the slave will clear its MCE0 bit to enable interrupts on the reception of the following data byte(s). Slaves that weren't addressed leave their MCE0 bits set and do not generate interrupts on the reception of the following data byte(s) addressed slave resets its MCE0 bit to ignore all transmissions until it receives the next address byte.

Multiple addresses can be assigned to a single slave and/or a single address can be assigned to multiple slaves, thereby enabling "broadcast" transmissions to more than one slave simultaneously. The master processor can be configured to receive all transmissions or a protocol can be implemented such that the master/slave role is temporarily reversed to enable half-duplex transmission between the original master and slave(s).



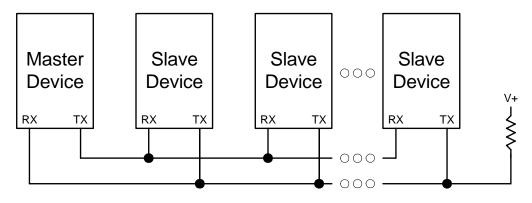


Figure 16.6. UART Multi-Processor Mode Interconnect Diagram



SFR Definition	16.1.	SCON0:	Serial	Port 0	Control
----------------	-------	--------	--------	--------	---------

R/W	R - 1	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
SOMOD	= -	MCE0	REN0	TB80	RB80	TIO	RI0	0100000 Bit
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Addressab
							SFR Addres	ss: 0x98
			<b>•</b>					
Bit7:	SOMODE: S		•					
	This bit sele 0: 8-bit UAR		•					
	1: 9-bit UAR							
Bit6:	UNUSED. R							
Bit5:	MCE0: Multi							
	The function					peration M	lode.	
	S0MODE =					p 01 0 1 0 1 1		
			f stop bit is i					
		•	•	•	s logic level	1.		
	S0MODE =			•	•			
	0: Lo	ogic level of	f ninth bit is	ignored.				
	1: R	10 is set and	d an interru	ot is genera	ted only wh	en the nint	h bit is logi	c 1.
Bit4:	REN0: Rece							
	This bit enab	oles/disable	s the UART	receiver.				
	0: UART0 re							
	1: UART0 re							
Bit3:	TB80: Ninth							
	The logic lev							RT Mode. I
	is not used in			Set or cleare	ed by softwa	ire as requ	ired.	
Bit2:	RB80: Ninth							
	RB80 is assi		alue of the S	STOP bit in	Mode 0; it is	s assigned	the value	of the 9th
D:14 .	data bit in M							
Bit1:	TIO: Transmi			ta haa haar	tranamitta		0 (aftar the	Oth hit in O
	Set by hardw bit UART Mo							
	interrupt is e							
	routine. This		•					Tupt Service
Bit0:	RIO: Receive			anually by s	sonware.			
Bitto.	Set to '1' by		•	of data has	been receiv	ed by UAR	T0 (set at t	he STOP bi
	sampling tim							
	to vector to t							
			initentubli se	I VICE I OULIII	e. This dit m	iusi de ciea	areu manu	ally by solt-



## C8051F52x/F52xA/F53x/F53xA

#### SFR Definition 16.2. SBUF0: Serial (UART0) Port Data Buffer

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	00000000
Diti	Бло	Bito	DILT	Bito	DILZ	Ditt	SFR Addres	s: 0x99
۲ c s	SBUF0[7:0]: This SFR act lata is writte sion. Writing ents of the r	cesses two n to SBUF( a byte to S	registers; a 0, it goes to BUF0 initia	transmit sh the transmi	ift register a t shift regis	ter and is h	eld for seri	



Rev. 0.5

_			5				
			Free	quency: 24.5 M	lHz		
	Target Baud Rate (bps)	Baud Rate % Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select)*	T1M*	Timer 1 Reload Value (hex)
	230400	-0.32%	106	SYSCLK	XX	1	0xCB
	115200	-0.32%	212	SYSCLK	XX	1	0x96
	57600	0.15%	426	SYSCLK	XX	1	0x2B
from Jsc.	28800	-0.32%	848	SYSCLK/4	01	0	0x96
< fror Osc.	14400	0.15%	1704	SYSCLK / 12	00	0	0xB9
	9600	-0.32%	2544	SYSCLK / 12	00	0	0x96
SYSCL	2400	-0.32%	10176	SYSCLK / 48	10	0	0x96
SY Int	1200	0.15%	20448	SYSCLK / 48	10	0	0x2B
				V Den	14		

# Table 16.1. Timer Settings for Standard Baud RatesUsing the Internal Oscillator

X = Don't care

\*Note: SCA1–SCA0 and T1M bit definitions can be found in Section 19.1.



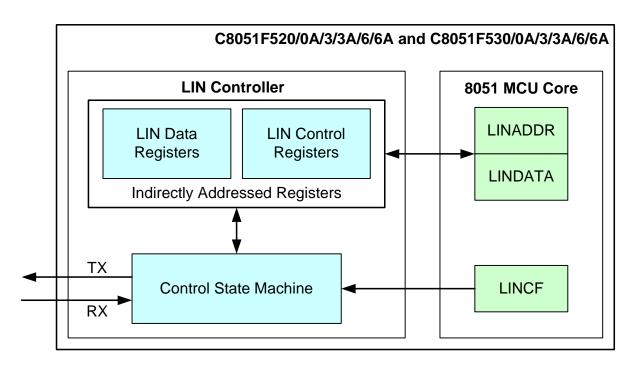
## 17. LIN (C8051F520/0A/3/3A/6/6A and C8051F530/0A/3/3A/6/6A)

**Important Note:** This chapter assumes an understanding of the Local Interconnect Network (LIN) protocol. For more information about the LIN protocol, including specifications, please refer to the LIN consortium (http://www.lin-subbus.org/).

LIN is an asynchronous, serial communications interface used primarily in automotive networks. The Silicon Laboratories LIN controller is compilant to the 2.0 Specification, implements a complete hardware LIN interface, and includes the following features:

- Selectable Master and Slave modes.
- Automatic baud rate option in slave mode
- The internal oscillator is accurate to within 0.5% of 24.5 MHz across the entire supply voltage and temperature range, and so external oscillator is not necessary for master mode operation.

Note: The minimum system clock (SYSCLK) required when using the LIN peripheral is 8 MHz.





The LIN peripheral has four main components:

- 1. LIN Access Registers Provide the interface between the MCU core and the LIN peripheral.
- 2. LIN Data Registers Where transmitted and received message data bytes are stored.
- 3. LIN Control Registers Control the functionality of the LIN interface.
- 4. Control State Machine and Bit Streaming Logic Contains the hardware that serializes messages and controls the bus timing of the controller.



#### 17.1. Software Interface with the LIN Peripheral

The selection of the mode (Master or Slave) and the automatic baud rate feature are done though the LIN0 Control Mode (LIN0CF) register. The other LIN registers are accessed indirectly through the two SFRs LIN0 Address (LINADDR) and LIN0 Data (LINDATA). The LINADDR register selects which LIN register is targeted by reads/writes of the LINDATA register. The full list of indirectly-accessible LIN register is given in Table 17.4 on page 163.

#### 17.2. LIN Interface Setup and Operation

The hardware based LIN peripheral allows for the implementation of both Master and Slave nodes with minimal firmware overhead and complete control of the interface status while allowing for interrupt and polled mode operation.

The first step to use the peripheral is to define the basic characteristics of the node:

- Mode Master or Slave
- Baud Rate Either defined manually or using the autobaud feature (slave mode only).
- Checksum Type Select between classic or enhanced checksum, both of which are implemented in hardware.

#### 17.2.1. Mode Definition

Following the LIN specification, the peripheral implements both the Slave and Master operating modes in hardware. The mode is configured using the MODE bit (LIN0CF.6).

#### 17.2.2. Baud Rate Options: Manual or Autobaud

The LIN peripheral can be selected to have its baud rate calculated manually or automatically. A master node must always have its baud rate set manually, but slave nodes can choose between a manual or automatic setup. The configuration is selected using the ABAUD bit (LINOCF.5).

Both the manual and automatic baud rate configurations require additional setup. The following sections explain the different options available and their relation with the baud rate, along with the steps necessary to achieve the required baud rate.

#### 17.2.3. Baud Rate Calculations - Manual Mode

The baud rate used by the peripheral is a function of the System Clock (SYSCLK) and the bit-timing Registers according to the following equation:

$$baud\_rate = \frac{SYSCLK}{2^{(prescaler + 1)} \times divider \times (multiplier + 1)}}$$

The prescaler, divider and multiplier factors are part of the LIN0DIV and LIN0MUL registers and can assume values in the following range:



Factor	Range
prescaler	03
multiplier	031
divider	200511

#### Table 17.1. Baud-Rate Calculation Variable Ranges

Important: The minimum system clock (SYSCLK) to operate the LIN peripheral is 8 MHz.

Use the following equations to calculate the values for the variables for the baud-rate equation:

 $multiplier = \frac{20000}{baud\_rate} - 1$ 

$$prescaler = ln \left[ \frac{SYSCLK}{(multiplier + 1) \times baud_rate \times 200} \right] \times \frac{1}{ln2} - 1$$

$$divider = \frac{SYSCLK}{(2^{(prescaler + 1)} \times multiplier \times baud_rate)}$$

It is important to note that in all these equations, the results must be rounded down to the nearest integer.

The following example shows the steps for calculating the baud rate values for a Master node running at 24.5 MHz and communicating at 19200 bits/sec. First, calculate the multiplier:

$$multiplier = \frac{20000}{19200} - 1 = 0.0417 \cong 0$$

Next, calculate the prescaler:

$$prescaler = ln \frac{24500000}{(0+1) \times 19200 \times 200} \times \frac{1}{ln2} - 1 = 1.674 \cong 1$$

Finally, calculate the divider:

$$divider = \frac{24500000}{2^{(1+1)} \times (0+1) \times 19200} = 319.010 \cong 319$$

These values lead to the following baud rate:



$$baud\_rate = \frac{24500000}{2^{(1+1)} \times (0+1) \times 319} \cong 19200.63$$

The following code programs the interface in Master mode, using the Enhanced Checksum and enables the interface to operate at 19200 bits/sec using a 24 MHz system clock.

```
LINOCF = 0x80;// Activate the interface
LINOCF |= 0x40;// Set the node as a Master
LINADDR = 0x0D;// Point to the LINOMUL register
// Initialize the register (prescaler, multiplier and bit 8 of divider)
LINDATA = ( 0x01 << 6 ) + ( 0x00 << 1 ) + ( ( 0x13F & 0x0100 ) >> 8 );
LINADDR = 0x0C;// Point to the LINODIV register
LINDATA = (unsigned char)_0x13F;// Initialize LINODIV
LINADDR = 0x0B;// Point to the LINOSIZE register
LINDATA |= 0x80;// Initialize the checksum as Enhanced
LINADDR = 0x08;// Point to LINOCTRL register
LINDATA = 0xC0; // Reset any error and the interrupt
```

Table 17.2 includes the configuration values required for the typical system clocks and baud rates:

		Baud (bits / sec)													
		20 k	(	19.2 K 9.6 K			4.8 K			1 K					
SYSCLK (MHz)	Mult.	Pres.	Div.	Mult.	Pres.	Div.	Mult.	Pres.	Div.	Mult.	Pres.	Div.	Mult.	Pres.	Div.
25	0	1	312	0	1	325	1	1	325	3	1	325	19	1	312
24.5	0	1	306	0	1	319	1	1	319	3	1	319	19	1	306
24	0	1	300	0	1	312	1	1	312	3	1	312	19	1	300
22.1184	0	1	276	0	1	288	1	1	288	3	1	288	19	1	276
16	0	1	200	0	1	208	1	1	208	3	1	208	19	1	200
12.25	0	0	306	0	0	319	1	0	319	3	0	319	19	0	306
12	0	0	300	0	0	312	1	0	312	3	0	312	19	0	300
11.0592	0	0	276	0	0	288	1	0	288	3	0	288	19	0	276
8	0	0	200	0	0	208	1	0	208	3	0	208	19	0	200

Table 17.2. Manual Baud Rate Parameters Examples

#### 17.2.4. Baud Rate Calculations - Automatic Mode

If the LIN peripheral is configured for slave mode, only the prescaler and divider need to be calculated:



$$prescaler = ln \left[\frac{SYSCLK}{4000000}\right] \times \frac{1}{ln2} - 1$$

$$divider = \frac{SYSCLK}{2^{(prescaler+1)} \times 20000}$$

The following example calculates the values of these variables for a 24 MHz system clock:

$$prescaler = ln \left[\frac{24500000}{4000000}\right] \times \frac{1}{ln2} - 1 = 1.615 \cong 1$$

$$divider = \frac{24500000}{2^{(1+1)} \times 20000} = 306.25 \cong 306$$

Table 17.3 presents some typical values of system clock and baud rate along with their factors.

System Clock (MHz)	Prescaler	Divider
25	1	312
24.5	1	306
24	1	300
22.1184	1	276
16	1	200
12.25	0	306
12	0	300
11.0592	0	276
8	0	200

#### Table 17.3. Autobaud Parameters Examples

#### 17.3. LIN Master Mode Operation

The master node is responsible for the scheduling of messages and sends the header of each frame, containing the SYNCH BREAK FIELD, SYNCH FIELD and IDENTIFIER FIELD. The steps to schedule a message transmission or reception are listed below.

- 1. Load the 6-bit Identifier into the LIN0ID register.
- Load the data length into the LINOSIZE register. Set the value to the number of data bytes or "1111b" if the data length should be decoded from the identifier. Also, set the checksum type, classic or enhanced, in the same LINOSIZE register.



- 3. Set the data direction by setting the TXRX bit (LIN0CTRL.5). Set the bit to 1 to perform a master transmit operation, or set the bit to 0 to perform a master receive operation.
- 4. If performing a master transmit operation, load the data bytes to transmit into the data buffer (LIN0DT1 to LIN0DT8).
- 5. Set the STREQ bit (LINOCTRL.0) to start the message transfer. The LIN peripheral will schedule the message frame and request an interrupt if the message transfer is successfully completed or if an error has occurred.

This code segment shows the procedure to schedule a message in a transmission operation:

```
LINADDR = 0x08;// Point to LIN0CTRL
LINDATA |= 0x20;// Select to transmit data
LINADDR = 0x0E;// Point to LIN0ID
LINDATA = 0x11;// Load the ID, in this example 0x11
LINADDR = 0x0B;// Point to LIN0SIZE
LINDATA = ( LINDATA & 0xF0 ) | 0x08; // Load the size with 8
LINADDR = 0x00;// Point to Data buffer first byte
for (i=0; i<8; i++)
{
    LINDATA = i + 0x41;// Load the buffer with `A', `B', ...
    LINADDR++;// Increment the address to the next buffer
}
LINADDR = 0x08;// Point to LIN0CTRL
LINADATA = 0x01;// Start Request
```

The application should perform the following steps when an interrupt is requested.

- 1. Check the DONE bit (LIN0ST.0) and the ERROR bit (LIN0ST.2).
- 2. If performing a master receive operation and the transfer was successful, read the received data from the data buffer.
- 3. If the transfer was not successful, check the error register to determine the kind of error. Further error handling has to be done by the application.
- 4. Set the RSTINT (LIN0CTRL.3) and RSTERR bits (LIN0CTRL.2) to reset the interrupt request and the error flags.

#### 17.4. LIN Slave Mode Operation

When the device is configured for slave mode operation, it must wait for a command from a master node. Access from the firmware to data buffer and ID registers of the LIN peripheral is only possible when a data request is pending (DTREQ bit (LINOST.4) is '1') and also when the LIN bus is not active (ACTIVE bit (LINOST.7) is set to '0').

The LIN peripheral in slave mode detects the header of the message frame sent by the LIN master. If slave synchronization is enabled (autobaud), the slave synchronizes its internal bit time to the master bit time.

The LIN peripheral configured for slave mode will generated an interrupt in one of three situations:

- 1. After the reception of the IDENTIFIER FIELD.
- 2. When an error is detected.
- 3. When the message transfer is completed.



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The application should perform the following steps when an interrupt is detected:

- 1. Check the status of the DTREQ bit (LIN0ST.4). This bit is set when the IDENTIFIER FIELD has been received.
- 2. If DTREQ (LIN0ST.4) is set, read the identifier from LIN0ID and process it. If DTREQ (LIN0ST.4) is not set, continue to step 7.
- 3. Set the TXRX bit (LIN0CTRL.5) to '1' if the current frame is a transmit operation for the slave and set to '0' if the current frame is a receive operation for the slave.
- 4. Load the data length into LINOSIZE.
- 5. For a slave transmit operation, load the data to transmit into the data buffer.
- 6. Set the DTACK bit (LIN0CTRL.4). Continue to step 10.
- 7. If DTREQ (LIN0ST.4) is not set, check the DONE bit (LIN0ST.0). The transmission was successful if the DONE bit is set.
- 8. If the transmission was successful and the current frame was a receive operation for the slave, load the received data bytes from the data buffer.
- 9. If the transmission was not successful, check LIN0ERR to determine the nature of the error. Further error handling has to be done by the application.
- 10. Set the RSTINT (LIN0CTRL.3) and RSTERR bits (LIN0CTRL.2) to reset the interrupt request and the error flags.

In addition to these steps, the application should be aware of the following:

- 1. If the current frame is a transmit operation for the slave, steps 1 through 5 must be completed during the IN-FRAME RESPONSE SPACE. If it is not completed in time, a timeout will be detected by the master.
- If the current frame is a receive operation for the slave, steps 1 through 5 have to be finished until the reception of the first byte after the IDENTIFIER FIELD. Otherwise, the internal receive buffer of the LIN peripheral will be overwritten and a timeout error will be detected in the LIN peripheral.
- 3. The LIN module does not directly support LIN Version 1.3 Extended Frames. If the application detects an unknown identifier (e.g. extended identifier), it has to write a '1' to the STOP bit (LIN0CTRL.7) instead of setting the DTACK (LIN0CTRL.4) bit. At that time, steps 2 through 5 can then be skipped. In this situation, the LIN peripheral stops the processing of the LIN communication until the next SYNC BREAK is received.
- 4. Changing the configuration of the checksum during a transaction will cause the interface to reset and the transaction to be lost. To prevent this, the checksum should not be configured while a transaction is in progress. The same applies to changes in the LIN interface mode from slave mode to master mode and from master mode to slave mode.

#### 17.5. Sleep Mode and Wake-Up

To reduce the system's power consumption, the LIN Protocol Specification defines a Sleep Mode. The message used to broadcast a Sleep Mode request must be transmitted by the LIN master application in the same way as a normal transmit message. The LIN slave application must decode the Sleep Mode Frame from the Identifier and data bytes. After that, the LIN slave node must be put into the Sleep Mode by setting the SLEEP bit (LINOCTRL.6).

If the SLEEP bit (LINOCTRL.6) of the LIN slave application is not set and there is no bus activity for four seconds (specified bus idle timeout), the IDLTOUT bit (LINOST.6) is set and an interrupt request is generated. After that the application may assume that the LIN bus is in Sleep Mode and set the SLEEP bit (LINOCTRL.6).



Sending a Wakeup signal from the master or any slave node terminates the Sleep Mode of the LIN bus. To send a Wakeup signal, the application has to set the WUPREQ bit (LIN0CTRL.1). After successful transmission of the wakeup signal, the DONE bit (LIN0ST.0) of the master node is set and an interrupt request is generated. The LIN slave does not generate an interrupt request after successful transmission of the Wakeup signal but it generates an interrupt request if the master does not respond to the Wakeup signal within 150 milliseconds. In that case, the ERROR bit (LIN0ST.2) and TOUT bit (LIN0ERR.2) are set. The application then has to decide whether or not to transmit another Wakeup signal.

All LIN nodes that detect a wakeup signal will set the WAKEUP (LIN0ST.1) and DONE bits (LIN0ST.0) and generate an interrupt request. After that, the application has to clear the SLEEP bit (LIN0CTRL.6) in the LIN slave.

## 17.6. Error Detection and Handling

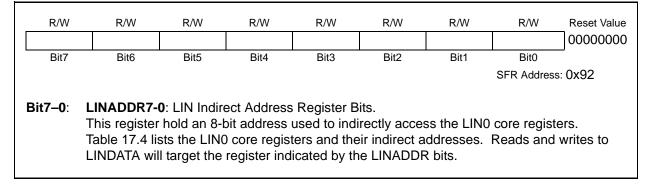
The LIN peripheral generates an interrupt request and stops the processing of the current frame if it detects an error. The application has to check the type of error by processing LIN0ERR. After that, it has to reset the error register and the ERROR bit (LIN0ST.2) by writing a '1' to the RSTERR bit (LIN0CTRL.2). Starting a new message with the LIN peripheral selected as master or sending a Wakeup signal with the LIN peripheral selected as a master or slave is possible only if ERROR bit (LIN0ST.2) is set to '0'.

#### 17.7. LIN Registers

The following Special Function Registers (SFRs) are available:

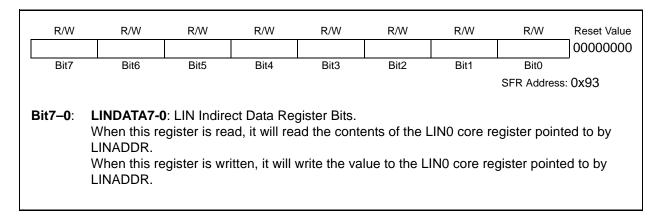
#### 17.7.1. LIN Direct Access SFR Registers Definition







## SFR Definition 17.2. LINDATA: LIN Data Register



## SFR Definition 17.3. LINCF Control Mode Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
LINEN	MODE	ABAUD						00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
							SFR Addres	s: 0x95
Bit7:	LINEN: LIN 0: LIN0 is dis 1: LIN0 is er	sabled.	able bit					
Bit6:	MODE: LIN 0: LIN0 oper 1: LIN0 oper	ates in Slav	e mode.					
Bit5:	<b>ABAUD</b> : LIN 0: Manual ba 1: Automatic	aud rate sel	ection is en	abled.	ction ( <b>slave</b>	e mode on	ly).	



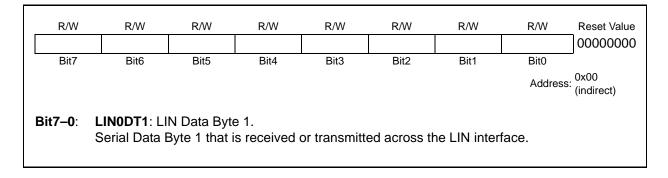
#### 17.7.2. LIN Indirect Access SFR Registers Definition

Name	Addres s	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
LIN0DT1	0x00				DATA1[	7:0]							
LIN0DT2	0x01		DATA2[7:0]										
LIN0DT3	0x02		DATA3[7:0]										
LIN0DT4	0x03		DATA4[7:0]										
LIN0DT5	0x04		DATA5[7:0]										
LIN0DT6	0x05		DATA6[7:0]										
LIN0DT7	0x06		DATA7[7:0]										
LIN0DT8	0x07				DATA8[	[7:0]							
LIN0CTRL	0x08	STOP(s)	SLEEP(s)	TXRX	DTACK(s)	RSTINT	RSTERR	WUPREQ	STREQ(m)				
LIN0ST	0x09	ACTIVE	IDLTOUT	ABORT(s)	DTREQ(s)	LININT	ERROR	WAKEUP	DONE				
LIN0ERR	0x0A				SYNCH(s)	PRTY(s)	TOUT	СНК	BITERR				
LIN0SIZE	0x0B	ENHCHK					LINS	IZE[3:0]					
LIN0DIV	0x0C				DIVLSB	[7:0]							
LINOMUL	0x0D	PRES	CL[1:0]		LI	NMUL[4:0]			DIV9				
LIN0ID	0x0E					ID[	5:0]						

Table 17.4. LIN Registers\* (Indirectly Addressable)

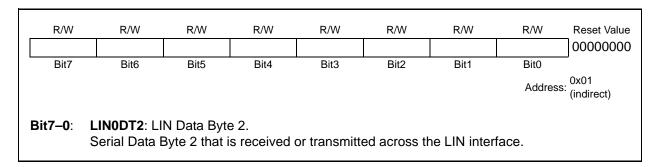
\*These registers are used in both master and slave mode. The register bits marked with (m) are accessible only in Master mode while the register bits marked with (s) are accessible only in slave mode. All other registers are accessible in both modes.

## SFR Definition 17.4. LIN0DT1: LIN0 Data Byte 1

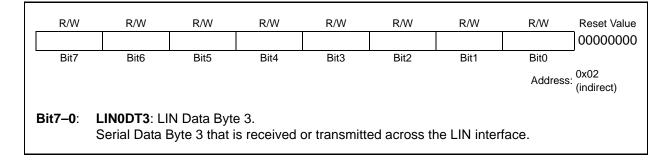




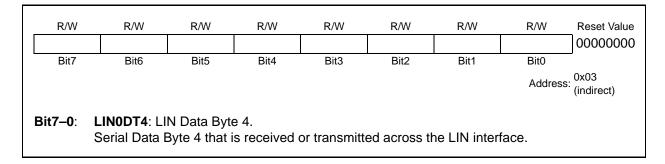
## SFR Definition 17.5. LIN0DT2: LIN0 Data Byte 2



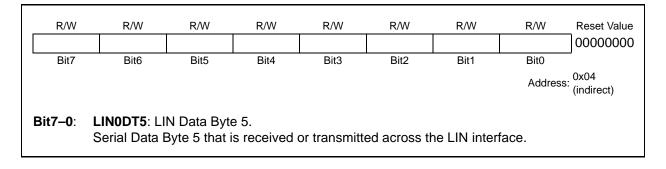
## SFR Definition 17.6. LIN0DT3: LIN0 Data Byte 3



## SFR Definition 17.7. LIN0DT4: LIN0 Data Byte 4



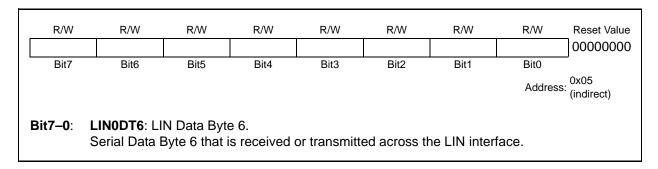
## SFR Definition 17.8. LIN0DT5: LIN0 Data Byte 5



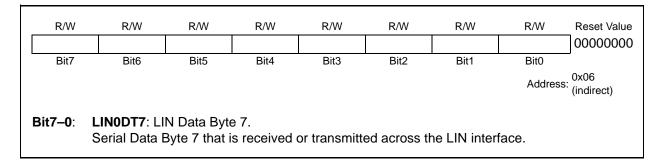


## C8051F50x

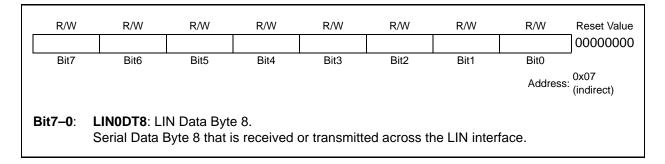
## SFR Definition 17.9. LIN0DT6: LIN0 Data Byte 6



## SFR Definition 17.10. LIN0DT7: LIN0 Data Byte 7



## SFR Definition 17.11. LIN0DT8: LIN0 Data Byte 8





W	W	W	R/W	R/W	R/W	R/W	R/W	Reset Value
STOP	SLEEP	TXRX	DTACK	RSTINT	RSTERR		STREQ	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
							Address	0x08 (indirect)
Bit7:	<b>STOP</b> : Stop This bit is to until the next request inter '0').	be set by tl t SYNCH B	ne applicati REAK signa	on to block al. It is used	the process I when the a	sing of the LI application is	s handling a	a data
Bit6:	SLEEP: Slee This bit is to received and The application	be set by the that the B	ne applicati us is in slee	p mode or	if a Bus Idle	e timeout inte		
Bit5:	TXRX: Trans This bit dete 0: Current fra 1: Current fra	smit/Receiv rmines if the ame is a ree	e Selection e current fra ceive opera	Bit. ame is a tra tion.		·	e frame.	
Bit4:	DTACK: Dat Set to '1' after automatically	er handling	a data requ	lest interrup	ot to acknow	vledge the tra	ansfer. Th	e bit will
Bit3:	<b>RSTINT</b> : Inte This bit alwa 0: No effect. 1: Reset the	errupt Rese ys reads as	t bit. s '0'.					
Bit2:	RSTERR: En This bit alwa 0: No effect. 1: Reset the	rror Reset E ys reads as	Bit. s 'O'.		۶.			
Bit1:	WUPREQ: V Set to '1' to t cleared to '0'	Vake-Up Re erminate sl ' by the LIN	equest Bit. eep mode k controller.	by sending a	a wakeup si	gnal. The b	it will auton	natically be
Bit0:	STREQ: Sta 1: Start a LIN and data buf The bit is res	l transmiss fer if neces	ion. This sl sary.	hould be se	t only after	-	dentifier, d	ata length



## SFR Definition 17.13. LIN0ST: LIN0 STATUS Register

R	R	R	R	R/W	R	R	R	Reset Value			
ACTIVE	E IDLTOUT	ABORT	DTREQ	LININT	ERROR	WAKEUP	DONE	00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
							Addres	s: 0x09 (indirect)			
Bit7:	ACTIVE: LIN	Bus Activi	ty Bit.								
	0: No transm	hission activ	vity detected	d on the LIN	bus.						
	1: Transmiss	ion activity	detected of	n the LIN bu	IS.						
Bit6:	IDLTOUT: BU	us Idle Time	eout Bit ( <b>sla</b>	ive mode o	nly).						
	0: The bus h	as not beei	n idle for fou	ur seconds.							
	1: No bus ac	tivity has b	een detecte	ed for four se	econds, but	t the bus is r	not yet in S	leep mode.			
Bit5:	ABORT: Abo		•	•	• /						
					•			bit is reset to '0' after			
	receiving a S										
	1: New SYNCH BREAK detected before the end of the last transmission or the STOP bit										
<b>D</b> '(4	(LINOCTRL.)										
Bit4:	DTREQ: Data 0: Data ident										
	1: Data ident										
Bit3:	LININT: Inter			J.							
Dito.				bit is clear	ed by settin	a RSTINT (		3)			
	<ul> <li>0: An interrupt is not pending. This bit is cleared by setting RSTINT (LIN0CTRL.3)</li> <li>1: There is a pending LIN0 interrupt.</li> </ul>										
Bit2:	ERROR: Co										
	0: No error has been detected. This bit is cleared by setting RSTERR (LIN0CTRL.2)										
	1: An error has been detected.										
Bit1:	WAKEUP: Wakeup Bit.										
	0: A wakeup				d.						
	1: A wakeup				been recei	ved.					
Bit0:	DONE: Tran										
	0: A transmis		in progress	or has not l	peen starte	d. This bit is	s cleared a	t the start of			
	a transmissio										
1	1: The curre	nt transmis	sion is com	plete.							



## SFR Definition 17.14. LIN0ERR: LIN0 ERROR Register

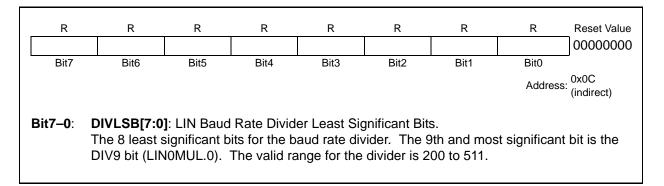
R	R	R	R	R	R	R	R	Reset Value			
			SYNCH	PRTY	TOUT	CHK	BITERR	00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	J			
							Address	0x0A (indirect)			
Bits7–5:	UNUSED. R	ead = 000b	. Write = do	on't care.							
Bit4:	SYNCH: Syr	nchronizatio	on Error Bit	(slave mod	le only).						
	0: No error v	vith the SYI	NCH FIELD	has been o	detected.						
	1: Edges of	the SYNC⊢	I FIELD are	outside of t	the maximu	m tolerance	э.				
Bit3:	PRTY: Parity	/ Error Bit (	slave mode	e only).							
	0: No parity										
	1: A parity e	rror has be	en detected								
Bit2:	TOUT: Time	out Error Bi	t.								
	0: A timeout										
	1: A timeout		een detecte	ed. This err	or is detect	ed wheneve	er one of the	e following			
	conditions is										
	•The master is expecting data from a slave and the slave does not respond.										
	•The slave is expecting data but no data is transmitted on the bus.										
	•A frame is not finished within the maximum frame length.										
	<ul> <li>The application does not set the DTACK bit (LIN0CTRL.4) or STOP bit (LIN0CTRL.7) until the end of the reception of the first byte after the identifier.</li> </ul>										
Bit1:	CHK: Check	•		byte alter t	ne identilier						
DILI.	0: Checksun			stactad							
	1: Checksun										
Bit0:	BITERR: Bit										
	0: No error in			-							
	1: The bit va					than the hi	t value sent				
	1. 110 51 74										



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value	
ENHCH	K -	-	-		LINSIZ	LINSIZE[3:0]			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0		
							Address	s: (indirect)	
Bit7: Bit6–4: Bit3–0:	ENHCHK: C 0: Use the cl 1: Use the el and protecte UNUSED. R LINSIZE3-0 0000: 0 data 0001: 1 data 0010: 2 data 0010: 2 data 0100: 4 data 0100: 4 data 0110: 6 data 0111: 7 data 1000: 8 data 1001-1110: F 1111: Use th	assic, spec nhanced, sp d identifier. ead = 000b : <b>Data Field</b> bytes bytes bytes bytes bytes bytes bytes bytes bytes bytes bytes bytes bytes bytes bytes	ification 1.3 becification . Write = do	2.0 compliant 2.0 complia on't care.	ant checksu	n. Checksu		•	

## SFR Definition 17.15. LIN0SIZE: LIN0 Message Size Register

## SFR Definition 17.16. LIN0DIV: LIN0 Divider Register

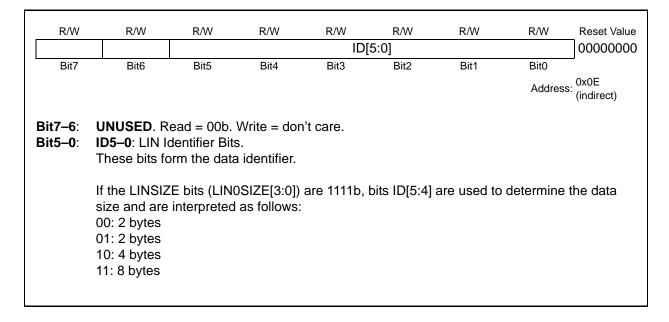




## SFR Definition 17.17. LIN0MUL: LIN0 Multiplier Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
PRESCL[1:0]				_INMUL[4:0	]		DIV9	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
							Addres	s: 0x0D (indirect)
Bit7–6: Bit5–1 <sup>.</sup>	PRESCL1–0 These bits ar LINMUL4–0:	e the bauc	I rate presc	aler bits.				
2.10	These bits ar				ese bits are	e not used i	n slave mo	de.
Bit0:	<b>DIV9</b> : LIN Ba The most sig The valid ran	ud Rate D nificant bit	ivider Most of the baud	Significant rate divide	Bit.			

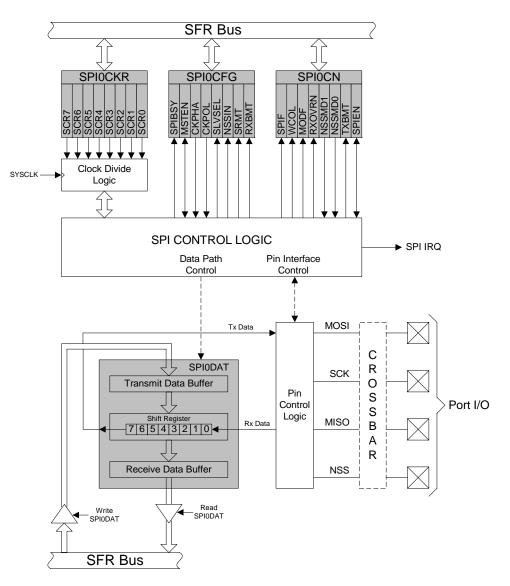
## SFR Definition 17.18. LIN0ID: LIN0 ID Register





## 18. Enhanced Serial Peripheral Interface (SPI0)

The Serial Peripheral Interface (SPI0) provides access to a flexible, full-duplex synchronous serial bus. SPI0 can operate as a master or slave device in both 3-wire or 4-wire modes, and supports multiple masters and slaves on a single SPI bus. The slave-select (NSS) signal can be configured as an input to select SPI0 in slave mode, or to disable Master Mode operation in a multi-master environment, avoiding contention on the SPI bus when more than one master attempts simultaneous data transfers. NSS can also be configured as a chip-select output in master mode, or disabled for 3-wire operation. Additional general purpose port I/O pins can be used to select multiple slave devices in master mode.







#### **18.1. Signal Descriptions**

The four signals used by SPI0 (MOSI, MISO, SCK, NSS) are described below.

#### 18.1.1. Master Out, Slave In (MOSI)

The master-out, slave-in (MOSI) signal is an output from a master device and an input to slave devices. It is used to serially transfer data from the master to the slave. This signal is an output when SPI0 is operating as a master and an input when SPI0 is operating as a slave. Data is transferred most-significant bit first. When configured as a master, MOSI is driven by the MSB of the shift register in both 3- and 4-wire mode.

#### 18.1.2. Master In, Slave Out (MISO)

The master-in, slave-out (MISO) signal is an output from a slave device and an input to the master device. It is used to serially transfer data from the slave to the master. This signal is an input when SPI0 is operating as a master and an output when SPI0 is operating as a slave. Data is transferred most-significant bit first. The MISO pin is placed in a high-impedance state when the SPI module is disabled and when the SPI operates in 4-wire mode as a slave that is not selected. When acting as a slave in 3-wire mode, MISO is always driven by the MSB of the shift register.

#### 18.1.3. Serial Clock (SCK)

The serial clock (SCK) signal is an output from the master device and an input to slave devices. It is used to synchronize the transfer of data between the master and slave on the MOSI and MISO lines. SPI0 generates this signal when operating as a master. The SCK signal is ignored by a SPI slave when the slave is not selected (NSS = 1) in 4-wire slave mode.

#### 18.1.4. Slave Select (NSS)

The function of the slave-select (NSS) signal is dependent on the setting of the NSSMD1 and NSSMD0 bits in the SPI0CN register. There are three possible modes that can be selected with these bits:

- NSSMD[1:0] = 00: 3-Wire Master or 3-Wire Slave Mode: SPI0 operates in 3-wire mode, and NSS is disabled. When operating as a slave device, SPI0 is always selected in 3-wire mode. Since no select signal is present, SPI0 must be the only slave on the bus in 3-wire mode. This is intended for point-to-point communication between a master and one slave.
- 2. NSSMD[1:0] = 01: 4-Wire Slave or Multi-Master Mode: SPI0 operates in 4-wire mode, and NSS is enabled as an input. When operating as a slave, NSS selects the SPI0 device. When operating as a master, a 1-to-0 transition of the NSS signal disables the master function of SPI0 so that multiple master devices can be used on the same SPI bus.
- NSSMD[1:0] = 1x: 4-Wire Master Mode: SPI0 operates in 4-wire mode, and NSS is enabled as an output. The setting of NSSMD0 determines what logic level the NSS pin will output. This configuration should only be used when operating SPI0 as a master device.

See Figure 18.2, Figure 18.3, and Figure 18.4 for typical connection diagrams of the various operational modes. **Note that the setting of NSSMD bits affects the pinout of the device.** When in 3-wire master or 3-wire slave mode, the NSS pin will not be mapped by the crossbar. In all other modes, the NSS signal will be mapped to a pin on the device. See Section "14. Port Input/Output" on page 118 for general purpose port I/O and crossbar information.



## 18.2. SPI0 Master Mode Operation

A SPI master device initiates all data transfers on a SPI bus. SPI0 is placed in master mode by setting the Master Enable flag (MSTEN, SPI0CN.6). Writing a byte of data to the SPI0 data register (SPI0DAT) when in master mode writes to the transmit buffer. If the SPI shift register is empty, the byte in the transmit buffer is moved to the shift register, and a data transfer begins. The SPI0 master immediately shifts out the data serially on the MOSI line while providing the serial clock on SCK. The SPIF (SPI0CN.7) flag is set to logic 1 at the end of the transfer. If interrupts are enabled, an interrupt request is generated when the SPIF flag is set. While the SPI0 master transfers data to a slave on the MOSI line, the addressed SPI slave device simultaneously transfers data to the SPI master on the MISO line in a full-duplex operation. Therefore, the SPIF flag serves as both a transmit-complete and receive-data-ready flag. The data byte received from the slave is transferred MSB-first into the master's shift register. When a byte is fully shifted into the register, it is moved to the receive buffer where it can be read by the processor by reading SPI0DAT.

When configured as a master, SPI0 can operate in one of three different modes: multi-master mode, 3-wire single-master mode, and 4-wire single-master mode. The default, multi-master mode is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 1. In this mode, NSS is an input to the device, and is used to disable the master SPI0 when another master is accessing the bus. When NSS is pulled low in this mode, MSTEN (SPI0CN.6) and SPIEN (SPI0CN.0) are set to 0 to disable the SPI master device, and a Mode Fault is generated (MODF, SPI0CN.5 = 1). Mode Fault will generate an interrupt if enabled. SPI0 must be manually re-enabled in software under these circumstances. In multi-master systems, devices will typically default to being slave devices while they are not acting as the system master device. In multi-master mode, slave devices can be addressed individually (if needed) using general-purpose I/O pins. Figure 18.2 shows a connection diagram between two master devices in multiple-master mode.

3-wire single-master mode is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 0. In this mode, NSS is not used and is not mapped to an external port pin through the crossbar. Any slave devices that must be addressed in this mode should be selected using general-purpose I/O pins. Figure 18.3 shows a connection diagram between a master device in 3-wire master mode and a slave device.

4-wire single-master mode is active when NSSMD1 (SPI0CN.3) = 1. In this mode, NSS is configured as an output pin and can be used as a slave-select signal for a single SPI device. In this mode, the output value of NSS is controlled (in software) with the bit NSSMD0 (SPI0CN.2). Additional slave devices can be addressed using general-purpose I/O pins. Figure 18.4 shows a connection diagram for a master device in 4-wire master mode and two slave devices.



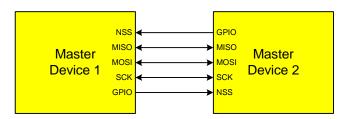


Figure 18.2. Multiple-Master Mode Connection Diagram

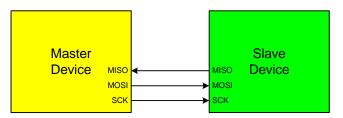
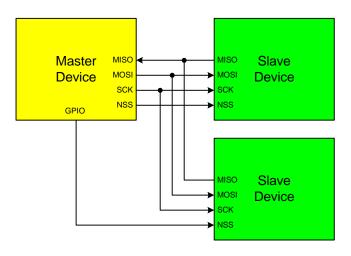


Figure 18.3. 3-Wire Single Master and Slave Mode Connection Diagram





## 18.3. SPI0 Slave Mode Operation

When SPI0 is enabled and not configured as a master, it will operate as a SPI slave. As a slave, bytes are shifted in through the MOSI pin and out through the MISO pin by a master device controlling the SCK signal. A bit counter in the SPI0 logic counts SCK edges. When 8 bits have been shifted into the shift register, the SPIF flag is set to logic 1, and the byte is copied into the receive buffer. Data is read from the receive buffer by reading SPI0DAT. A slave device cannot initiate transfers. Data to be transferred to the master device is pre-loaded into the shift register by writing to SPI0DAT. Writes to SPI0DAT are double-buffered, and are placed in the transmit buffer first. If the shift register is empty, the contents of the transmit buffer will immediately be transferred into the shift register. When the shift register already contains data, the SPI will load the shift register with the transmit buffer's contents after the last SCK edge of the next (or current) SPI transfer.



The shift register contents are locked after the slave detects the first edge of SCK. Writes to SPI0DAT that occur after the first SCK edge will be held in the TX latch until the end of the current transfer.

When configured as a slave, SPI0 can be configured for 4-wire or 3-wire operation. The default, 4-wire slave mode, is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 1. In 4-wire mode, the NSS signal is routed to a port pin and configured as a digital input. SPI0 is enabled when NSS is logic 0, and disabled when NSS is logic 1. The bit counter is reset on a falling edge of NSS. Note that the NSS signal must be driven low at least 2 system clocks before the first active edge of SCK for each byte transfer. Figure 18.4 shows a connection diagram between two slave devices in 4-wire slave mode and a master device.

3-wire slave mode is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 0. NSS is not used in this mode, and is not mapped to an external port pin through the crossbar. Since there is not a way of uniquely addressing the device in 3-wire slave mode, SPI0 must be the only slave device present on the bus. It is important to note that in 3-wire slave mode there is no external means of resetting the bit counter that determines when a full byte has been received. The bit counter can only be reset by disabling and re-enabling SPI0 with the SPIEN bit. Figure 18.3 shows a connection diagram between a slave device in 3-wire slave mode and a master device.

#### 18.4. SPI0 Interrupt Sources

When SPI0 interrupts are enabled, the following four flags will generate an interrupt when they are set to logic 1:

#### Note that all of the following interrupt bits must be cleared by software.

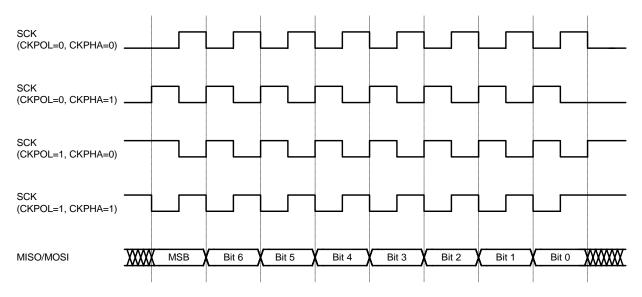
- 1. The SPI Interrupt Flag, SPIF (SPI0CN.7) is set to logic 1 at the end of each byte transfer. This flag can occur in all SPI0 modes.
- 2. The Write Collision Flag, WCOL (SPI0CN.6) is set to logic 1 if a write to SPI0DAT is attempted when the transmit buffer has not been emptied to the SPI shift register. When this occurs, the write to SPI0DAT will be ignored, and the transmit buffer will not be written. This flag can occur in all SPI0 modes.
- 3. The Mode Fault Flag MODF (SPI0CN.5) is set to logic 1 when SPI0 is configured as a master in multi-master mode and the NSS pin is pulled low. When a Mode Fault occurs, the MSTEN and SPIEN bits in SPI0CN are set to logic 0 to disable SPI0 and allow another master device to access the bus.
- 4. The Receive Overrun Flag RXOVRN (SPI0CN.4) is set to logic 1 when configured as a slave, and a transfer is completed while the receive buffer still holds an unread byte from a previous transfer. The new byte is not transferred to the receive buffer, allowing the previously received data byte to be read. The data byte which caused the overrun is lost.



#### 18.5. Serial Clock Timing

Four combinations of serial clock phase and polarity can be selected using the clock control bits in the SPI0 Configuration Register (SPI0CFG). The CKPHA bit (SPI0CFG.5) selects one of two clock phases (edge used to latch the data). The CKPOL bit (SPI0CFG.4) selects between a rising edge or a falling edge. Both master and slave devices must be configured to use the same clock phase and polarity. SPI0 should be disabled (by clearing the SPIEN bit, SPI0CN.0) when changing the clock phase or polarity. The clock and data line relationships are shown in Figure 18.5.

The SPI0 Clock Rate Register (SPI0CKR) as shown in SFR Definition 18.3 controls the master mode serial clock frequency. This register is ignored when operating in slave mode. When the SPI is configured as a master, the maximum data transfer rate (bits/sec) is one-half the system clock frequency or 12.5 MHz, whichever is slower. When the SPI is configured as a slave, the maximum data transfer rate (bits/sec) for full-duplex operation is 1/10 the system clock frequency, provided that the master issues SCK, NSS (in 4-wire slave mode), and the serial input data synchronously with the slave's system clock. If the master issues SCK, NSS, and the serial input data asynchronously, the maximum data transfer rate (bits/sec) must be less than 1/10 the system clock frequency. In the special case where the master only wants to transmit data to the slave and does not need to receive data from the slave (i.e. half-duplex operation), the SPI slave can receive data at a maximum data transfer rate (bits/sec) of 1/4 the system clock frequency. This is provided that the master issues SCK, NSS, and the serial input data transfer rate (bits/sec) of 1/4 the system clock frequency. This is provided that the master issues SCK, NSS, and the serial input data synchronously with the slave's system clock frequency.





## 18.6. SPI Special Function Registers

SPI0 is accessed and controlled through four special function registers in the system controller: SPI0CN Control Register, SPI0DAT Data Register, SPI0CFG Configuration Register, and SPI0CKR Clock Rate Register. The four special function registers related to the operation of the SPI0 Bus are described in the following figures.



## SFR Definition 18.1. SPI0CFG: SPI0 Configuration

R	R/W	R/W	R/W	R	R	R	R	Reset Valu			
SPIBSY	MSTEN	CKPHA	CKPOL	SLVSEL	NSSIN	SRMT	RXBMT	0000011			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
							SFR Address	: 0xA1			
Bit 7:	SPIBSY: SP	I Busv (rea	d onlv).								
	This bit is se		• /	l transfer is	in progress	(Master or	Slave Mode	e).			
	MSTEN: Ma	-			1 0	· ·		,			
	0: Disable m	aster mode	. Operate i	n slave mod	le.						
	1: Enable ma	aster mode	Operate a	s a master.							
Sit 5:	CKPHA: SP	I0 Clock Ph	ase.								
	This bit cont										
	0: Data cente										
	1: Data cente			of SCK perio	od.*						
	CKPOL: SPI										
	This bit cont		•	arity.							
	0: SCK line low in idle state. 1: SCK line high in idle state.										
	<b>SLVSEL</b> : Slave Selected Flag (read only). This bit is set to logic 1 whenever the NSS pin is low indicating SPI0 is the selected slave. If										
	is cleared to										
	instantaneou										
	NSSIN: NSS				•			Jui.			
						the NSS n	ort nin at the	time that			
	This bit mimics the instantaneous value that is present on the NSS port pin at the time that the register is read. This input is not de-glitched.										
	SRMT: Shift		•	•		ulv)					
							t of the shift	register			
	This bit will be set to logic 1 when all data has been transferred in/out of the shift register, and there is no new information available to read from the transmit buffer or write to the										
	receive buffer. It returns to logic 0 when a data byte is transferred to the shift register from										
	the transmit		-		,						
	NOTE: SRM										
Sit O:	RXBMT: Red	ceive Buffer	Empty (Va	lid in Slave	Mode, read	l only).					
	This bit will b	be set to log	jic 1 when t	he receive l	ouffer has b	een read a	nd contains	no new			
	information.	If there is n	ew informat	ion availabl	e in the rece	eive buffer t	hat has not	been read			
	this bit will re	eturn to logi	c 0.								
	NOTE: RXB	MT = 1 whe	en in Master	r Mode							
				moue.							
	Table 18.1 fo			i woue.							



## C8051F52x/F52xA/F53x/F53xA

544	D 444	D 444	D 444	<b>D</b> 444	DAA		DAAL				
R/W	R/W WCOL	R/W MODF	R/W RXOVRN	R/W NSSMD1	R/W NSSMD0	R TXBMT	R/W SPIEN	Reset Value			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit			
							SFR Address				
Bit7:	SPIF: SPI0 I										
	This bit is se setting this b										
	automatically					•					
Bit6:	WCOL: Write		•								
	This bit is se	•		· •		• •					
	attempted when the transmit buffer has not been emptied to the SPI shift register. When this occurs, the write to SPI0DAT will be ignored, and the transmit buffer will not be written. This										
	bit is not aut			•							
Bit5:	MODF: Mod		-	<i>,</i> ,							
	This bit is set to logic 1 by hardware (and generates a SPI0 interrupt) when a master mode collision is detected (NSS is low, MSTEN = 1, and NSSMD[1:0] = 01). This bit is not auto-										
	matically cle	•				/	. 1113 DIL 13				
Bit4:	RXOVRN: R	eceive Ove	errun Flag (	Slave Mode	only).						
	This bit is se										
	fer still holds shifted into the										
	be cleared b					any oloaroe	a by hardwe				
Bits3-2:	NSSMD1-N										
	Selects betw					- 172 and (	Castion "10	2 2010			
	(See Section "18.2. SPI0 Master Mode Operation" on page 173 and Section "18.3. SPI0 Slave Mode Operation" on page 174).										
	00: 3-Wire Slave or 3-wire Master Mode. NSS signal is not routed to a port pin.										
	01: 4-Wire Slave or Multi-Master Mode (Default). NSS is always an input to the device. 1x: 4-Wire Single-Master Mode. NSS signal is mapped as an output from the device and will										
	1x: 4-wire S assume the	-		ss signal is	mapped as a	an output fr	om the dev	lice and will			
Bit1:	TXBMT: Trai										
	This bit will b		-								
	data in the tr						it will be se	et to logic 1,			
Bit0:	indicating the SPIEN: SPIC		to write a no		ne transmit	bullel.					
	This bit enab		es the SPI.								
	0: SPI disab										
	1: SPI enabl	ed.									

## SFR Definition 18.2. SPI0CN: SPI0 Control



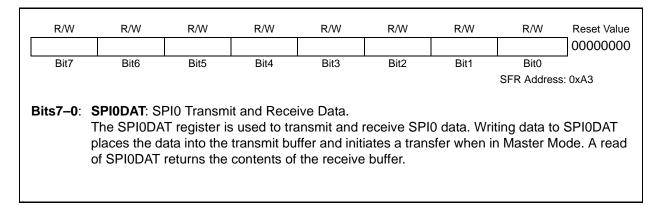
## SFR Definition 18.3. SPI0CKR: SPI0 Clock Rate

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
SCR7	SCR6	SCR5	SCR4	SCR3	SCR2	SCR1	SCR0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
							SFR Address	s: 0xA2
its7–0: \$	SCR7-SCR	0: SPI0 Clo	ck Rate.					
	These bits d				•			•
	or master m							
	clock, and is and S <i>PI0CK</i>						Stem Clock	irequency
· · · ·								
	f	S	YSCLK PIOCKR +					
	JSCK	$2 \times (SP)$	PIOCKR +	1)				
f	or 0 <= SPI	0CKR <= 2	55					
Example: I	f SYSCLK =	2 MHz and	SPI0CKR	= 0x04,				
		200000	0					
	$f_{SCK}$ =	$=\frac{200000}{2 \times (4 + 10^{-3})}$	$\frac{1}{1}$					
		2 ~ (+	1)					
	C	000111						
	$f_{SCK} =$	200kHz						



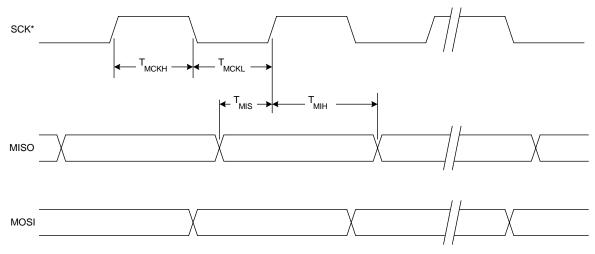
## C8051F52x/F52xA/F53x/F53xA

## SFR Definition 18.4. SPI0DAT: SPI0 Data



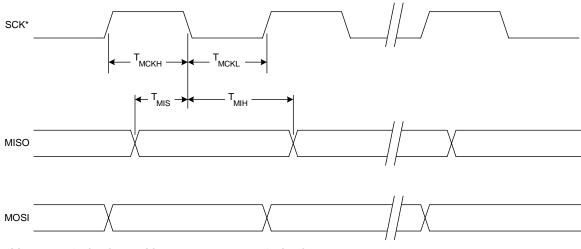


# C8051F52x/F52xA/F53x/F53xA



\* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.



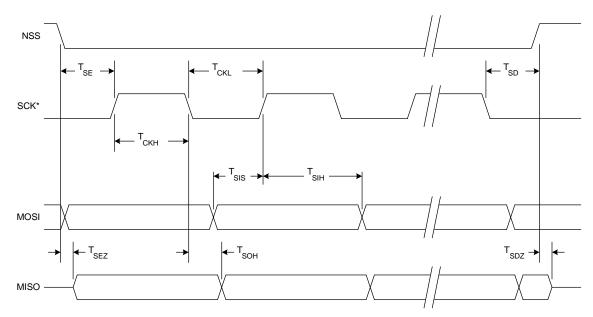


\* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.

## Figure 18.7. SPI Master Timing (CKPHA = 1)

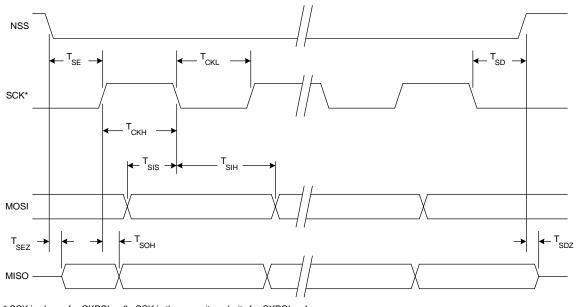


# C8051F52x/F52xA/F53x/F53xA



\* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.





\* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.

## Figure 18.9. SPI Slave Timing (CKPHA = 1)



Parameter	Description	Min	Max	Units
Master Mode	Timing* (See Figure 18.6 and Figure 18.7)	I	•	
т <sub>мскн</sub>	SCK High Time	1 x T <sub>SYSCLK</sub>	—	ns
T <sub>MCKL</sub>	SCK Low Time	1 x T <sub>SYSCLK</sub>	—	ns
T <sub>MIS</sub>	MISO Valid to SCK Sample Edge	20	—	ns
т <sub>мін</sub>	SCK Sample Edge to MISO Change	0	—	ns
Slave Mode T	iming* (See Figure 18.8 and Figure 18.9)			•
T <sub>SE</sub>	NSS Falling to First SCK Edge	2 x T <sub>SYSCLK</sub>	—	ns
T <sub>SD</sub>	Last SCK Edge to NSS Rising	2 x T <sub>SYSCLK</sub>	—	ns
T <sub>SEZ</sub>	NSS Falling to MISO Valid	—	4 x T <sub>SYSCLK</sub>	ns
T <sub>SDZ</sub>	NSS Rising to MISO High-Z		4 x T <sub>SYSCLK</sub>	ns
т <sub>скн</sub>	SCK High Time	5 x T <sub>SYSCLK</sub>	—	ns
Т <sub>СКL</sub>	SCK Low Time	5 x T <sub>SYSCLK</sub>	—	ns
T <sub>SIS</sub>	MOSI Valid to SCK Sample Edge	2 x T <sub>SYSCLK</sub>	—	ns
T <sub>SIH</sub>	SCK Sample Edge to MOSI Change	2 x T <sub>SYSCLK</sub>	—	ns
Т <sub>SOH</sub>	SCK Shift Edge to MISO Change	—	4 x T <sub>SYSCLK</sub>	ns
The ma Transm	c is equal to one period of the device system clock (SYSC ximum possible frequency of the SPI can be calculated a ssion: SYSCLK/2 on: SYSCLK/10			

## Table 18.1. SPI Slave Timing Parameters



## 19. Timers

Each MCU includes three counter/timers: two are 16-bit counter/timers compatible with those found in the standard 8051, and one is a 16-bit auto-reload timer for use with other device peripherals or for general purpose use. These timers can be used to measure time intervals, count external events and generate periodic interrupt requests. Timer 0 and Timer 1 are nearly identical and have four primary modes of operation. Timer 2 offer 16-bit and split 8-bit timer functionality with auto-reload.

Timer 0 and Timer 1 Modes:	Timer 2 Modes:
13-bit counter/timer	16-bit timer with auto-reload
16-bit counter/timer	
8-bit counter/timer with auto-reload	
Two 8-bit counter/timers	Two 8-bit timers with auto-reload
(Timer 0 only)	

Timers 0 and 1 may be clocked by one of five sources, determined by the Timer Mode Select bits (T1M–T0M) and the Clock Scale bits (SCA1–SCA0). The Clock Scale bits define a pre-scaled clock from which Timer 0 and/or Timer 1 may be clocked (See SFR Definition 19.3 for pre-scaled clock selection).

Timer 0/1 may then be configured to use this pre-scaled clock signal or the system clock. Timer 2 may be clocked by the system clock, the system clock divided by 12, or the external oscillator clock source divided by 8.

Timer 0 and Timer 1 may also be operated as counters. When functioning as a counter, a counter/timer register is incremented on each high-to-low transition at the selected input pin (T0 or T1). Events with a frequency of up to one-fourth the system clock's frequency can be counted. The input signal need not be periodic, but it must be held at a given level for at least two full system clock cycles to ensure the level is properly sampled.

#### 19.1. Timer 0 and Timer 1

Each timer is implemented as a 16-bit register accessed as two separate bytes: a low byte (TL0 or TL1) and a high byte (TH0 or TH1). The Counter/Timer Control register (TCON) is used to enable Timer 0 and Timer 1 as well as indicate status. Timer 0 interrupts can be enabled by setting the ET0 bit in the IE register (Section "11.4. Interrupt Register Descriptions" on page 97); Timer 1 interrupts can be enabled by setting the ET1 bit in the IE register (Section 11.4). Both counter/timers operate in one of four primary modes selected by setting the Mode Select bits T1M1–T0M0 in the Counter/Timer Mode register (TMOD). Each timer can be configured independently. Each operating mode is described below.

#### 19.1.1. Mode 0: 13-bit Counter/Timer

Timer 0 and Timer 1 operate as 13-bit counter/timers in Mode 0. The following describes the configuration and operation of Timer 0. However, both timers operate identically, and Timer 1 is configured in the same manner as described for Timer 0.

The TH0 register holds the eight MSBs of the 13-bit counter/timer. TL0 holds the five LSBs in bit positions TL0.4–TL0.0. The three upper bits of TL0 (TL0.7–TL0.5) are indeterminate and should be masked out or ignored when reading. As the 13-bit timer register increments and overflows from 0x1FFF (all ones) to 0x0000, the timer overflow flag TF0 (TCON.5) is set and an interrupt will occur if Timer 0 interrupts are enabled.



The C/T0 bit (TMOD.2) selects the counter/timer's clock source. When C/T0 is set to logic 1, high-to-low transitions at the selected Timer 0 input pin (T0) increment the timer register (Refer to Section "14.1. Priority Crossbar Decoder" on page 120 for information on selecting and configuring external I/O pins). Clearing C/T selects the clock defined by the T0M bit (CKCON.3). When T0M is set, Timer 0 is clocked by the system clock. When T0M is cleared, Timer 0 is clocked by the source selected by the Clock Scale bits in CKCON (see SFR Definition 19.3).

Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is logic 0 or the input signal /INT0 is active as defined by bit IN0PL in register IT01CF (see SFR Definition 11.5. IT01CF: INT0/INT1 Configuration). Setting GATE0 to '1' allows the timer to be controlled by the external input signal /INT0 (see Section "11.4. Interrupt Register Descriptions" on page 97), facilitating pulse width measurements.

TR0	GATE0	/INT0	Counter/Timer				
0	Х	Х	Disabled				
1	0	Х	Enabled				
1	1	0	Disabled				
1	1 1 1 Enabled						
X = Don't Care							

Setting TR0 does not force the timer to reset. The timer registers should be loaded with the desired initial value before the timer is enabled.

TL1 and TH1 form the 13-bit register for Timer 1 in the same manner as described above for TL0 and TH0. Timer 1 is configured and controlled using the relevant TCON and TMOD bits just as with Timer 0. The input signal /INT1 is used with Timer 1; the /INT1 polarity is defined by bit IN1PL in register IT01CF (see SFR Definition 11.5. IT01CF: INT0/INT1 Configuration).

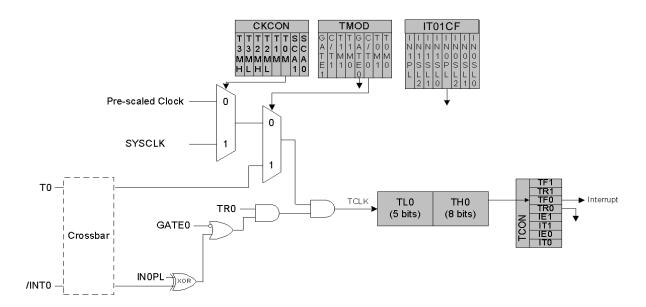


Figure 19.1. T0 Mode 0 Block Diagram



#### 19.1.2. Mode 1: 16-bit Counter/Timer

Mode 1 operation is the same as Mode 0, except that the counter/timer registers use all 16 bits. The counter/timers are enabled and configured in Mode 1 in the same manner as for Mode 0.

#### 19.1.3. Mode 2: 8-bit Counter/Timer with Auto-Reload

Mode 2 configures Timer 0 and Timer 1 to operate as 8-bit counter/timers with automatic reload of the start value. TL0 holds the count and TH0 holds the reload value. When the counter in TL0 overflows from all ones to 0x00, the timer overflow flag TF0 (TCON.5) is set and the counter in TL0 is reloaded from TH0. If Timer 0 interrupts are enabled, an interrupt will occur when the TF0 flag is set. The reload value in TH0 is not changed. TL0 must be initialized to the desired value before enabling the timer for the first count to be correct. When in Mode 2, Timer 1 operates identically to Timer 0.

Both counter/timers are enabled and configured in Mode 2 in the same manner as Mode 0. Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is logic 0 or when the input signal /INT0 is active as defined by bit IN0PL in register IT01CF (see Section "11.5. External Interrupts" on page 101 for details on the external input signals /INT0 and /INT1).

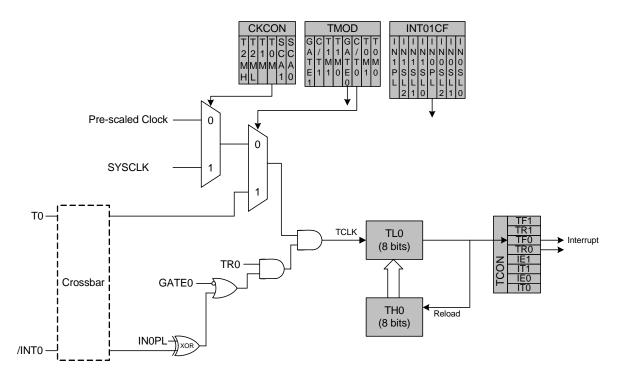


Figure 19.2. T0 Mode 2 Block Diagram



#### 19.1.4. Mode 3: Two 8-bit Counter/Timers (Timer 0 Only)

In Mode 3, Timer 0 is configured as two separate 8-bit counter/timers held in TL0 and TH0. The counter/timer in TL0 is controlled using the Timer 0 control/status bits in TCON and TMOD: TR0, C/T0, GATE0 and TF0. TL0 can use either the system clock or an external input signal as its timebase. The TH0 register is restricted to a timer function sourced by the system clock or prescaled clock. TH0 is enabled using the Timer 1 run control bit TR1. TH0 sets the Timer 1 overflow flag TF1 on overflow and thus controls the Timer 1 interrupt.

Timer 1 is inactive in Mode 3. When Timer 0 is operating in Mode 3, Timer 1 can be operated in Modes 0, 1 or 2, but cannot be clocked by external signals nor set the TF1 flag and generate an interrupt. However, the Timer 1 overflow can be used to generate baud rates for the SMBus and UART. While Timer 0 is operating in Mode 3, Timer 1 run control is handled through its mode settings. To run Timer 1 while Timer 0 is in Mode 3, set the Timer 1 Mode as 0, 1, or 2. To disable Timer 1, configure it for Mode 3.

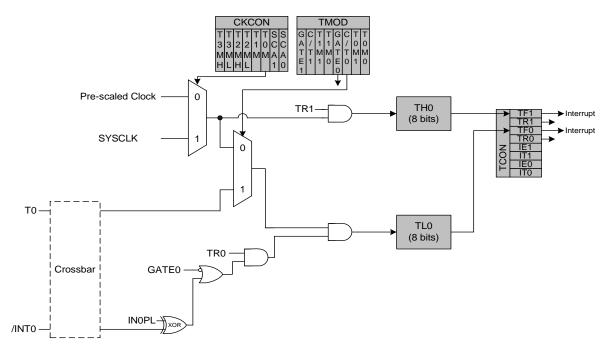


Figure 19.3. T0 Mode 3 Block Diagram



# C8051F52x/F52xA/F53x/F53xA

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit			
Diti	Dito	Dito	Ditt	Dito	DILL	Bitt		Addressable			
	SFR Address: 0x88										
Bit7:	TE1: Timer 1 Overflow Flag										
Ditr.		<b>TF1</b> : Timer 1 Overflow Flag. Set by hardware when Timer 1 overflows. This flag can be cleared by software but is auto-									
		natically cleared when the CPU vectors to the Timer 1 interrupt service routine.									
		D: No Timer 1 overflow detected.									
	1: Timer 1 ha										
Bit6:	TR1: Timer 1		ol.								
	0: Timer 1 di										
Bit5:	1: Timer 1 er <b>TF0</b> : Timer 0										
DILJ.	Set by hardw			rflows. This	s flag can be	e cleared b	v software	but is auto-			
	matically clea				•		•				
	0: No Timer					·					
	1: Timer 0 ha										
Bit4:	TRO: Timer (		ol.								
	0: Timer 0 di 1: Timer 0 er										
Bit3:	IE1: External										
Dito.	This flag is s	•		n edae/leve	el of type de	fined by IT	1 is detecte	ed. It can be			
	cleared by so										
	rupt 1 service										
	defined by bi			1CF (see S	FR Definitio	on 11.5."IT	01CF: INT	0/INT1 Con-			
D:40.	figuration" or										
Bit2:	IT1: Interrupt			urod /INIT1 i	ntorrunt will	ha adaa a	r lovol son	sitivo /INT1			
	is configured										
	Definition 11						. (				
	0: /INT1 is le	vel triggere	d.	-		- ,					
-	1: /INT1 is e										
Bit1:	IEO: Externa	•				for a diameter in	0 :!				
	This flag is so cleared by so										
	rupt 0 service										
	defined by bi										
	figuration" or			,							
Bit0:	ITO: Interrupt										
	This bit selec							sitive. /INT0			
	is configured						see SFR				
	Definition 11 0: /INT0 is le				auon on pa	ye 102).					
	1: /INT0 is e										

## SFR Definition 19.1. TCON: Timer Control



## SFR Definition 19.2. TMOD: Timer Mode

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value				
GATE1	C/T1	T1M1	T1M0	GATE0	C/T0	T0M1	T0M0	0000000				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0					
							SFR Addres	s: 0x89				
Bit7:	-		Gate Control. d when TR1 = 1 irrespective of /INT1 logic level.									
	1: Timer 1 enabled only when TR1 = 1 AND /INT1 is active as defined by bit IN1PL in reg ter IT01CF (see SFR Definition 11.5. "IT01CF: INT0/INT1 Configuration" on page 102).											
D:40.		•		5. "IT01CF	: IN I 0/IN I 1	Configurat	ion" on pag	ge 102).				
Bit6:		nter/Timer			ale dafina di							
			ner 1 increme Timer 1 incre									
	(T1).	Function.		nemed by i	ligh-to-low i		n external	input pin				
Rits5_4		MO: Timer 1	Mode Select									
B1130 4.			Timer 1 opera									
	T1M1	T1M0		Mode	9							
	0	0	Mod	e 0: 13-bit c	ounter/time	r						
	0	1	Mod	e 1: 16-bit c	ounter/time	r						
	1	0	Mode 2: 8-bit counter/timer with auto-reload									
	1	1	Mc	de 3: Timer	1 inactive							
Bit3:		imer 0 Gate										
			nen TR0 = 1 i				-1 h h :4 IN 10					
			nly when TR0 Definition 11.									
Bit2:		nter/Timer		5. HUICF	.   N   U/  N	Configurat	ion on pag	ge 102).				
DILZ.			ner 0 increme	nted by clo	ck defined k	w TOM bit (						
			Timer 0 incre				· · · · · ·					
	(T0).	r anotion.		nonted by i	light to low t			input pin				
Bits1-0:	· · ·	<b>MO</b> : Timer 0	Mode Select									
	These bits	select the	Timer 0 opera	ation mode.								
			-									
	T0M1	T0M0		Mod								
	0	0		e 0: 13-bit c								
		1	Mod									
	0	-	Mode 2: 8-bit counter/timer with auto-reload									
	0 1 1	0	Mode 2: 8-b		ner with aut							

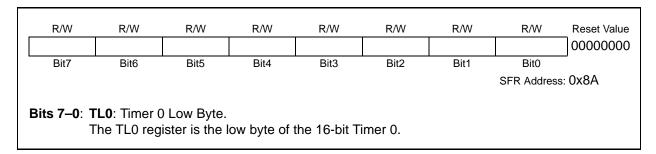


SFR Definition	19.3.	<b>CKCON:</b>	Clock	Control
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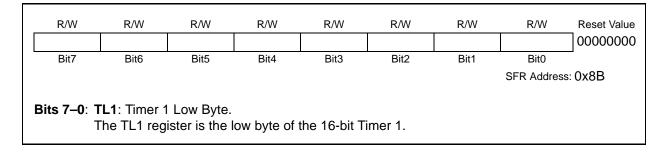
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value				
_		T2MH	T2ML	T1M	TOM	SCA1	SCA0	0000000				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0					
							SFR Addres	s: 0x8E				
Bit7–6:	RESERVED											
Bit5:		<b>2MH</b> : Timer 2 High Byte Clock Select. This bit selects the clock supplied to the Timer 2 high byte if Timer 2 is configured in split 8-										
					• •		is configure	ed in split 8-				
	bit timer mo		•									
	0: Timer 2 h 1: Timer 2 h						KZUN.					
Bit4:	T2ML: Time	• •										
BR4.	This bit sele				If Timer 2 is	configured	in split 8-b	it timer				
	mode, this b					•	op o .o.					
	0: Timer 2 lo			•			2CN.					
	1: Timer 2 lo			n clock.								
Bit3:	T1M: Timer											
	This select				•		n C/T1 is se	et to logic 1.				
	0: Timer 1 u			y the presc	ale bits, SC	CA1–SCA0.						
Bit2:	1: Timer 1 u TOM: Timer											
BITZ:	This bit sele			nnlied to Ti	mor 0 TOM	Lie ignored	when C/TO	is set to				
	logic 1.			pplied to 11		i is ignored		15 561 10				
	0: Counter/	Fimer 0 use	s the clock o	defined by t	he prescale	e bits. SCA1	-SCA0.					
	1: Counter/					,						
Bits1-0:	SCA1-SCA											
	These bits of	control the d	livision of th	e clock sup	plied to Tin	ner 0 and Ti	mer 1 if cor	nfigured to				
	use prescal	ed clock inp	outs.									
	SCA1	SCA0	Presc	aled Clock	(							
	0	0	System clo	ck divided	by 12							
	0	1	System clo	ock divided	by 4							
	1	0	System clo	ck divided	by 48							
	1	1	External cl	ock divided	by 8							
	Note: Exter	nal clock di	vided by 8 is	synchroniz	zed with							
	the system	clock.										



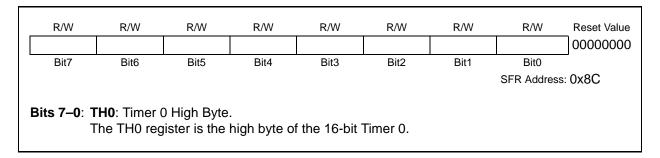
## SFR Definition 19.4. TL0: Timer 0 Low Byte



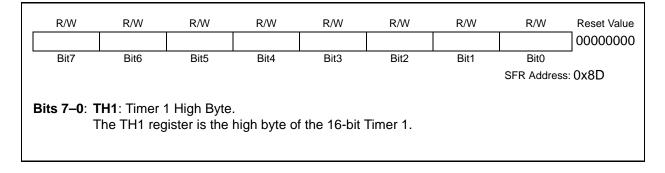
## SFR Definition 19.5. TL1: Timer 1 Low Byte



## SFR Definition 19.6. TH0: Timer 0 High Byte



## SFR Definition 19.7. TH1: Timer 1 High Byte





### 19.2. Timer 2

Timer 2 is a 16-bit timer formed by two 8-bit SFRs: TMR2L (low byte) and TMR2H (high byte). Timer 2 may operate in 16-bit auto-reload mode or (split) 8-bit auto-reload mode. The T2SPLIT bit (TMR2CN.3) defines the Timer 2 operation mode. Timer 2 can also be used in Capture Mode to measure the RTC0 clock frequency or the External Oscillator clock frequency.

Timer 2 may be clocked by the system clock, the system clock divided by 12, or the external oscillator source divided by 8. The external oscillator source divided by 8 is synchronized with the system clock.

#### 19.2.1. 16-bit Timer with Auto-Reload

When T2SPLIT (TMR2CN.3) is zero, Timer 2 operates as a 16-bit timer with auto-reload. Timer 2 can be clocked by SYSCLK, SYSCLK divided by 12, or the external oscillator clock source divided by 8. As the 16-bit timer register increments and overflows from 0xFFFF to 0x0000, the 16-bit value in the Timer 2 reload registers (TMR2RLH and TMR2RLL) is loaded into the Timer 2 register as shown in Figure 19.4, and the Timer 2 High Byte Overflow Flag (TMR2CN.7) is set. If Timer 2 interrupts are enabled (if IE.5 is set), an interrupt will be generated on each Timer 2 overflow. Additionally, if Timer 2 interrupts are enabled and the TF2LEN bit is set (TMR2CN.5), an interrupt will be generated each time the lower 8 bits (TMR2L) overflow from 0xFF to 0x00.

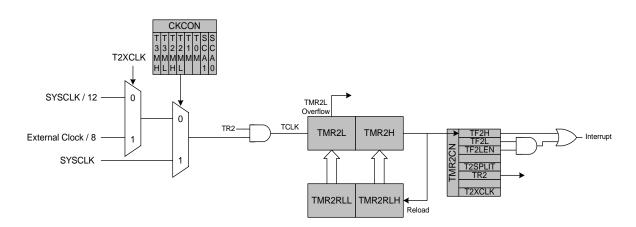


Figure 19.4. Timer 2 16-Bit Mode Block Diagram



#### 19.2.2. 8-bit Timers with Auto-Reload

When T2SPLIT is set, Timer 2 operates as two 8-bit timers (TMR2H and TMR2L). Both 8-bit timers operate in auto-reload mode as shown in Figure 19.5. TMR2RLL holds the reload value for TMR2L; TMR2RLH holds the reload value for TMR2H. The TR2 bit in TMR2CN handles the run control for TMR2H. TMR2L is always running when configured for 8-bit Mode.

Each 8-bit timer may be configured to use SYSCLK, SYSCLK divided by 12, or the external oscillator clock source divided by 8. The Timer 2 Clock Select bits (T2MH and T2ML in CKCON) select either SYSCLK or the clock defined by the Timer 2 External Clock Select bit (T2XCLK in TMR2CN), as follows:

T2MH	T2XCLK	TMR2H Clock Source
0	0	SYSCLK / 12
0	1	External Clock / 8
1	Х	SYSCLK

T2ML	T2XCLK	TMR2L Clock Source
0	0	SYSCLK / 12
0	1	External Clock / 8
1	Х	SYSCLK

The TF2H bit is set when TMR2H overflows from 0xFF to 0x00; the TF2L bit is set when TMR2L overflows from 0xFF to 0x00. When Timer 2 interrupts are enabled (IE.5), an interrupt is generated each time TMR2H overflows. If Timer 2 interrupts are enabled and TF2LEN (TMR2CN.5) is set, an interrupt is generated each time either TMR2L or TMR2H overflows. When TF2LEN is enabled, software must check the TF2H and TF2L flags to determine the source of the Timer 2 interrupt. The TF2H and TF2L interrupt flags are not cleared by hardware and must be manually cleared by software.

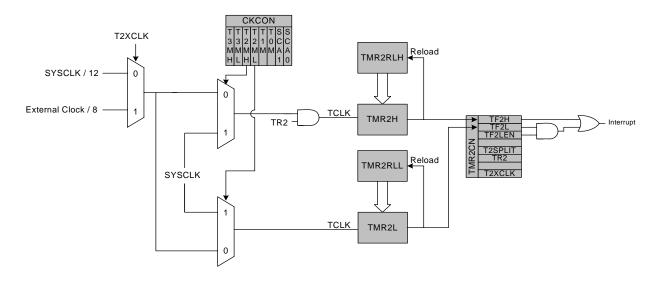


Figure 19.5. Timer 2 8-Bit Mode Block Diagram



#### 19.2.3. External Capture Mode

Capture Mode allows the external oscillator to be measured against the system clock. Timer 2 can be clocked from the system clock, or the system clock divided by 12, depending on the T2ML (CKCON.4) and T2XCLK bits. When a capture event is generated, the contents of Timer 2 (TMR2H:TMR2L) are loaded into the Timer 2 reload registers (TMR2RLH:TMR2RLL) and the TF2H flag is set. A capture event is generated by the falling edge of the clock source being measured, which is the external oscillator / 8. By recording the difference between two successive timer capture values, the external oscillator frequency can be determined with respect to the Timer 2 clock. The Timer 2 clock should be much faster than the capture clock to achieve an accurate reading. Timer 2 should be in 16-bit auto-reload mode when using Capture Mode.

For example, if T2ML = 1b and TF2CEN = 1b, Timer 2 will clock every SYSCLK and capture every external clock divided by 8. If the SYSCLK is 24.5 MHz and the difference between two successive captures is 5984, then the external clock frequency is:

$$\frac{24.5 \text{ MHz}}{(5984/8)} = 0.032754 \text{ MHz or } 32.754 \text{ kHz}$$

This mode allows software to determine the external oscillator frequency when an RC network or capacitor is used to generate the clock source.

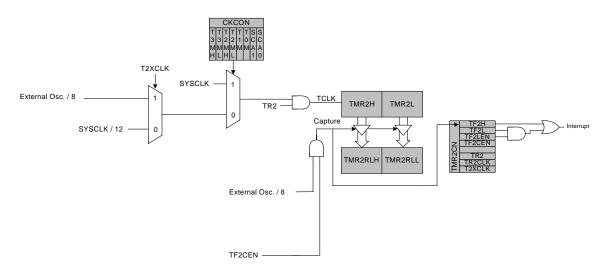


Figure 19.6. Timer 2 Capture Mode Block Diagram



## SFR Definition 19.8. TMR2CN: Timer 2 Control

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
TF2H	TF2L	TF2LEN	TF2CEN	T2SPLIT	TR2		T2XCLK	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressabl
							SFR Address	: 0xC8
Bit7:	TF2H: Time	r 2 High Byt	e Overflow	Flag.				
	Set by hard	ware when t	he Timer 2	high byte ov				
	this will occu							
	enabled, set TF2H is not	-					•	
Sit6:	TF2L: Timer		•	•			by contraro.	
	Set by hardw							
	set, an interr							
	will set wher ically cleared			s regardless	of the 11m	er 2 mode.	I his dit is n	ot automa
Bit5:	TF2LEN: Tir	•		ot Enable.				
	This bit enab	oles/disable	s Timer 2 L	ow Byte inte				
	rupts are en		•	•			of Timer 2 ov	erflows.
	This bit shou 0: Timer 2 Lo			•	er 2 in 16-b	it mode.		
	1: Timer 2 L	•	•					
Bit4:	TF2CEN. Ti	•	•					
	0: Timer 2 ca	•						
Bit3:	1: Timer 2 ca T2SPLIT: Ti	•		lo				
JILJ.	When this bi	•			bit timers v	with auto-re	eload.	
	0: Timer 2 o		•					
	1: Timer 2 o			to-reload tin	ners.			
Bit2:	TR2: Timer 2			n 9 hit mad	, this hit o	oobloo/dioc		J only:
	This bit enab TMR2L is al				e, this dit er	lables/ulsa		т опту,
	0: Timer 2 di	•						
	1: Timer 2 er							
Bit1:	Unused. Re							
Bit0:	T2XCLK: Tin This bit sele				mer 2 lf Tir	mer 2 is in	8-bit mode t	this bit
	selects the e							
	Select bits (	T2MH and 1	2ML in reg	ister CKCO	N) may still			
	external cloc							
	0: Timer 2 ex 1: Timer 2 ex							

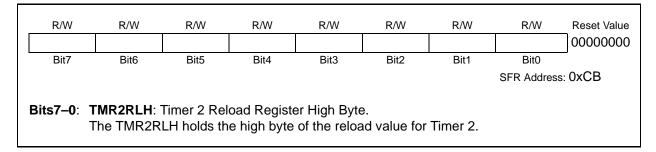


# C8051F52x/F52xA/F53x/F53xA

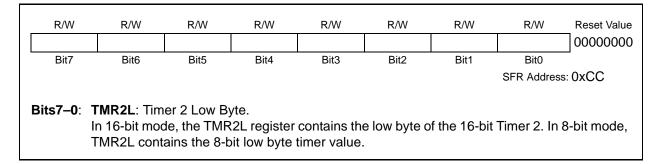
## SFR Definition 19.9. TMR2RLL: Timer 2 Reload Register Low Byte

	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
									00000000
	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
								SFR Addres	s: 0xCA
В		<b>FMR2RLL</b> : T FMR2RLL ho					2.		

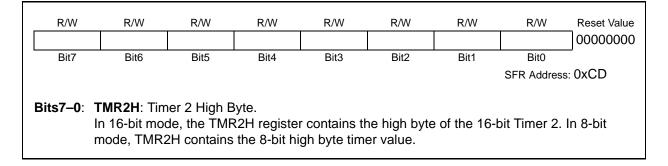
## SFR Definition 19.10. TMR2RLH: Timer 2 Reload Register High Byte



## SFR Definition 19.11. TMR2L: Timer 2 Low Byte



## SFR Definition 19.12. TMR2H Timer 2 High Byte





# 20. Programmable Counter Array (PCA0)

The Programmable Counter Array (PCA0) provides enhanced timer functionality while requiring less CPU intervention than the standard 8051 counter/timers. The PCA consists of a dedicated 16-bit counter/timer and three 16-bit capture/compare modules. Each capture/compare module has its own associated I/O line (CEXn) which is routed through the Crossbar to Port I/O when enabled (See Section "14.1. Priority Cross-bar Decoder" on page 120 for details on configuring the Crossbar). The counter/timer is driven by a programmable timebase that can select between six sources: system clock, system clock divided by four, system clock divided by twelve, the external oscillator clock source divided by 8, Timer 0 overflow, or an external clock signal on the ECI input pin. Each capture/compare module may be configured to operate independently in one of three modes: Edge-Triggered Capture, Software Timer, High-Speed Output, Frequency Output, 8-Bit PWM, or 16-Bit PWM (each mode is described in Section "20.2. Capture/Compare Modules" on page 199). The PCA is configured and controlled through the system controller's Special Function Registers. The PCA block diagram is shown in Figure 20.1

**Important Note:** The PCA Module 2 may be used as a watchdog timer (WDT), and is enabled in this mode following a system reset. Access to certain PCA registers is restricted while WDT mode is enabled. See Section "20.3. Watchdog Timer Mode" on page 205 for details.

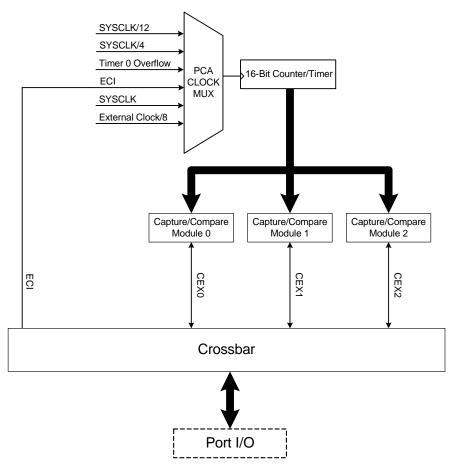


Figure 20.1. PCA Block Diagram



## 20.1. PCA Counter/Timer

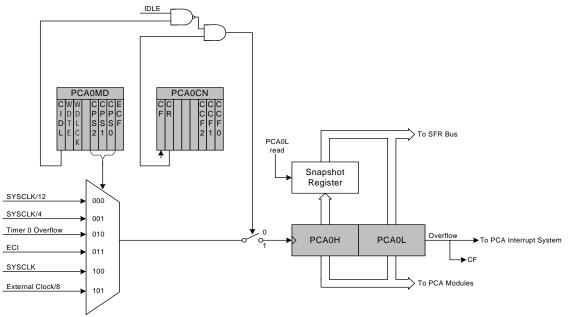
The 16-bit PCA counter/timer consists of two 8-bit SFRs: PCA0L and PCA0H. PCA0H is the high byte (MSB) of the 16-bit counter/timer and PCA0L is the low byte (LSB). Reading PCA0L automatically latches the value of PCA0H into a "snapshot" register; the following PCA0H read accesses this "snapshot" register. **Reading the PCA0L Register first guarantees an accurate reading of the entire 16-bit PCA0 counter.** Reading PCA0H or PCA0L does not disturb the counter operation. The CPS2-CPS0 bits in the PCA0MD register select the timebase for the counter/timer as shown in Table 20.1.

When the counter/timer overflows from 0xFFFF to 0x0000, the Counter Overflow Flag (CF) in PCA0MD is set to logic 1 and an interrupt request is generated if CF interrupts are enabled. Setting the ECF bit in PCA0MD to logic 1 enables the CF flag to generate an interrupt request. The CF bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software (Note: PCA0 interrupts must be globally enabled before CF interrupts are recognized. PCA0 interrupts are globally enabled by setting the EA bit (IE.7) and the EPCA0 bit in EIE1 to logic 1). Clearing the CIDL bit in the PCA0MD register allows the PCA to continue normal operation while the CPU is in Idle mode.

CPS2	CPS1	CPS0	Timebase
0	0	0	System clock divided by 12
0	0	1	System clock divided by 4
0	1	0	Timer 0 overflow
0	1	1	High-to-low transitions on ECI (max rate = system clock divided by 4)
1	0	0	System clock
1	0	1	External oscillator source divided by 8*

### Table 20.1. PCA Timebase Input Options

\*Note: External clock divided by 8 is synchronized with the system clock.







## 20.2. Capture/Compare Modules

Each module can be configured to operate independently in one of six operation modes: Edge-triggered Capture, Software Timer, High Speed Output, Frequency Output, 8-Bit Pulse Width Modulator, or 16-Bit Pulse Width Modulator. Each module has Special Function Registers (SFRs) associated with it in the CIP-51 system controller. These registers are used to exchange data with a module and configure the module's mode of operation.

Table 20.2 summarizes the bit settings in the PCA0CPMn registers used to select the PCA capture/compare module's operating modes. Setting the ECCFn bit in a PCA0CPMn register enables the module's CCFn interrupt. Note: PCA0 interrupts must be globally enabled before individual CCFn interrupts are recognized. PCA0 interrupts are globally enabled by setting the EA bit and the EPCA0 bit to logic 1. See Figure 20.3 for details on the PCA interrupt configuration.

PWM16	ECOM	CAPP	CAPN	MAT	TOG	PWM	ECCF	Operation Mode
Х	Х	1	0	0	0	0	Х	Capture triggered by positive edge on CEXn
Х	Х	0	1	0	0	0	Х	Capture triggered by negative edge on CEXn
Х	Х	1	1	0	0	0	Х	Capture triggered by transition on CEXn
Х	1	0	0	1	0	0	Х	Software Timer
Х	1	0	0	1	1	0	Х	High Speed Output
Х	1	0	0	Х	1	1	Х	Frequency Output
0	1	0	0	Х	0	1	Х	8-Bit Pulse Width Modulator
1	1	0	0	Х	0	1	Х	16-Bit Pulse Width Modulator
X = Don'	t Care	•		•	•	•	•	

#### Table 20.2. PCA0CPM Register Settings for PCA Capture/Compare Modules

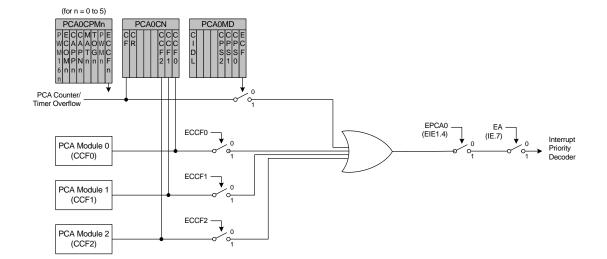


Figure 20.3. PCA Interrupt Block Diagram



#### 20.2.1. Edge-triggered Capture Mode

In this mode, a valid transition on the CEXn pin causes the PCA to capture the value of the PCA counter/timer and load it into the corresponding module's 16-bit capture/compare register (PCA0CPLn and PCA0CPHn). The CAPPn and CAPNn bits in the PCA0CPMn register are used to select the type of transition that triggers the capture: low-to-high transition (positive edge), high-to-low transition (negative edge), or either transition (positive or negative edge). When a capture occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1 and an interrupt request is generated if CCF interrupts are enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. If both CAPPn and CAPNn bits are set to logic 1, then the state of the Port pin associated with CEXn can be read directly to determine whether a rising-edge or falling-edge caused the capture.

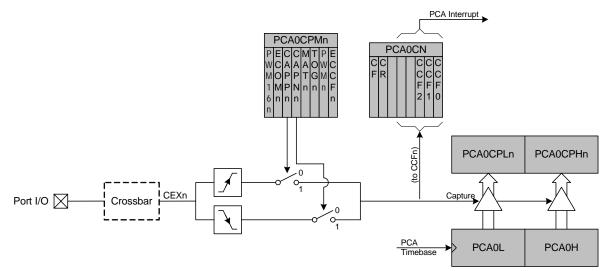


Figure 20.4. PCA Capture Mode Diagram

**Note:** The CEXn input signal must remain high or low for at least 2 system clock cycles to be recognized by the hardware.

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#### 20.2.2. Software Timer (Compare) Mode

In Software Timer mode, the PCA counter/timer value is compared to the module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn). When a match occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1 and an interrupt request is generated if CCF interrupts are enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. Setting the ECOMn and MATn bits in the PCA0CPMn register enables Software Timer mode.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.

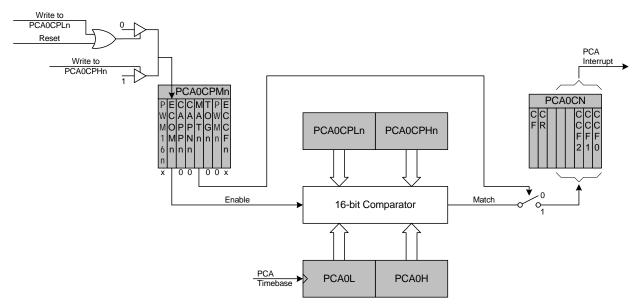


Figure 20.5. PCA Software Timer Mode Diagram



#### 20.2.3. High Speed Output Mode

In High Speed Output mode, a module's associated CEXn pin is toggled each time a match occurs between the PCA Counter and the module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn) Setting the TOGn, MATn, and ECOMn bits in the PCA0CPMn register enables the High-Speed Output mode.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.

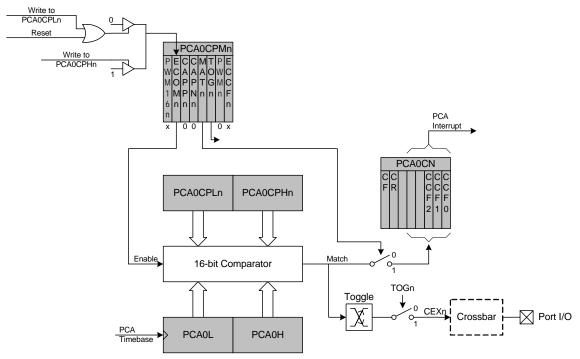


Figure 20.6. PCA High-Speed Output Mode Diagram

**Note:** The initial state of the Toggle output is logic 1 and is initialized to this state when the module enters High Speed Output Mode.



#### 20.2.4. Frequency Output Mode

Frequency Output Mode produces a programmable-frequency square wave on the module's associated CEXn pin. The capture/compare module high byte holds the number of PCA clocks to count before the output is toggled. The frequency of the square wave is then defined by Equation 20.1.

$$F_{CEXn} = \frac{F_{PCA}}{2 \times PCA0CPHn}$$

Note: A value of 0x00 in the PCA0CPHn register is equal to 256 for this equation.

#### Equation 20.1. Square Wave Frequency Output

Where  $F_{PCA}$  is the frequency of the clock selected by the CPS2-0 bits in the PCA mode register, PCA0MD. The lower byte of the capture/compare module is compared to the PCA counter low byte; on a match, CEXn is toggled and the offset held in the high byte is added to the matched value in PCA0CPLn. Frequency Output Mode is enabled by setting the ECOMn, TOGn, and PWMn bits in the PCA0CPMn register.

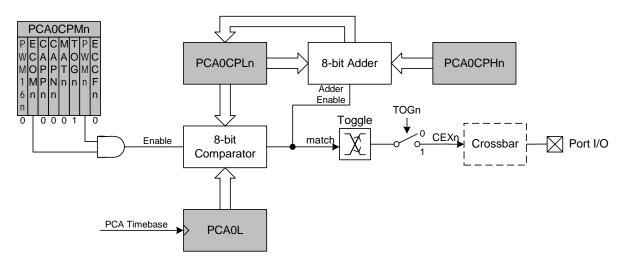


Figure 20.7. PCA Frequency Output Mode



#### 20.2.5. 8-Bit Pulse Width Modulator Mode

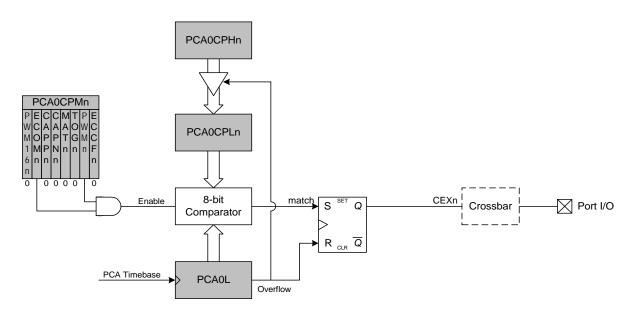
Each module can be used independently to generate a pulse width modulated (PWM) output on its associated CEXn pin. The frequency of the output is dependent on the timebase for the PCA counter/timer. The duty cycle of the PWM output signal is varied using the module's PCA0CPHn capture/compare register. When the value in the low byte of the PCA counter/timer (PCA0L) is equal to the value in PCA0CPLn, the output on the CEXn pin will be set. When the count value in PCA0L overflows, the CEXn output will be reset (see Figure 20.8). Also, when the counter/timer low byte (PCA0L) overflows from 0xFF to 0x00, PCA0CPLn is reloaded automatically with the value stored in the module's capture/compare high byte (PCA0CPHn) without software intervention. Setting the ECOMn and PWMn bits in the PCA0CPMn register enables 8-Bit Pulse Width Modulator mode. The duty cycle for 8-Bit PWM Mode is given by Equation 20.2.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.

$$DutyCycle = \frac{(256 - PCA0CPHn)}{256}$$

Equation 20.2. 8-Bit PWM Duty Cycle

Using Equation 20.2, the largest duty cycle is 100% (PCA0CPHn = 0), and the smallest duty cycle is 0.39% (PCA0CPHn = 0xFF). A 0% duty cycle may be generated by clearing the ECOMn bit to '0'.







#### 20.2.6. 16-Bit Pulse Width Modulator Mode

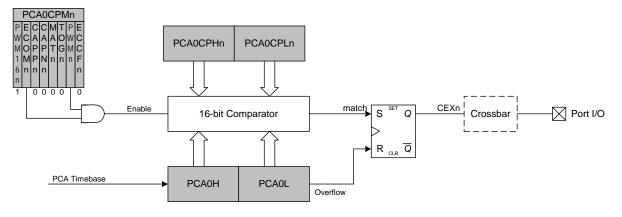
A PCA module may also be operated in 16-Bit PWM mode. In this mode, the 16-bit capture/compare module defines the number of PCA clocks for the low time of the PWM signal. When the PCA counter matches the module contents, the output on CEXn is asserted high; when the counter overflows, CEXn is asserted low. To output a varying duty cycle, new value writes should be synchronized with PCA CCFn match interrupts. 16-Bit PWM Mode is enabled by setting the ECOMn, PWMn, and PWM16n bits in the PCA0CPMn register. For a varying duty cycle, match interrupts should be enabled (ECCFn = 1 AND MATn = 1) to help synchronize the capture/compare register writes. The duty cycle for 16-Bit PWM Mode is given by Equation 20.3.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.

$$DutyCycle = \frac{(65536 - PCA0CPn)}{65536}$$

#### Equation 20.3. 16-Bit PWM Duty Cycle

Using Equation 20.3, the largest duty cycle is 100% (PCA0CPn = 0), and the smallest duty cycle is 0.0015% (PCA0CPn = 0xFFFF). A 0% duty cycle may be generated by clearing the ECOMn bit to '0'.





#### 20.3. Watchdog Timer Mode

A programmable watchdog timer (WDT) function is available through the PCA Module 2. The WDT is used to generate a reset if the time between writes to the WDT update register (PCA0CPH2) exceed a specified limit. The WDT can be configured and enabled/disabled as needed by software.

With the WDTE bit set in the PCA0MD register, Module 2 operates as a watchdog timer (WDT). The Module 2 high byte is compared to the PCA counter high byte; the Module 2 low byte holds the offset to be used when WDT updates are performed. The Watchdog Timer is enabled on reset. Writes to some PCA registers are restricted while the Watchdog Timer is enabled.

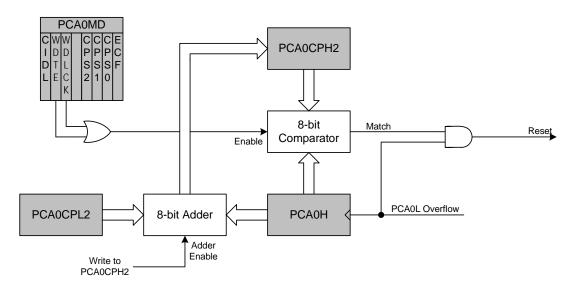


#### 20.3.1. Watchdog Timer Operation

While the WDT is enabled:

- PCA counter is forced on.
- Writes to PCA0L and PCA0H are not allowed.
- PCA clock source bits (CPS2-CPS0) are frozen.
- PCA Idle control bit (CIDL) is frozen.
- Module 2 is forced into software timer mode.
- Writes to the Module 2 mode register (PCA0CPM2) are disabled.

While the WDT is enabled, writes to the CR bit will not change the PCA counter state; the counter will run until the WDT is disabled. The PCA counter run control (CR) will read zero if the WDT is enabled but user software has not enabled the PCA counter. If a match occurs between PCA0CPH2 and PCA0H while the WDT is enabled, a reset will be generated. To prevent a WDT reset, the WDT may be updated with a write of any value to PCA0CPH2. Upon a PCA0CPH2 write, PCA0H plus the offset held in PCA0CPL2 is loaded into PCA0CPH2 (See Figure 20.10).



#### Figure 20.10. PCA Module 2 with Watchdog Timer Enabled



Note that the 8-bit offset held in PCA0CPH2 is compared to the upper byte of the 16-bit PCA counter. This offset value is the number of PCA0L overflows before a reset. Up to 256 PCA clocks may pass before the first PCA0L overflow occurs, depending on the value of the PCA0L when the update is performed. The total offset is then given (in PCA clocks) by Equation 20.4, where PCA0L is the value of the PCA0L register at the time of the update.

 $Offset = (256 \times PCA0CPL2) + (256 - PCA0L)$ 

#### Equation 20.4. Watchdog Timer Offset in PCA Clocks

The WDT reset is generated when PCA0L overflows while there is a match between PCA0CPH2 and PCA0H. Software may force a WDT reset by writing a '1' to the CCF2 flag (PCA0CN.2) while the WDT is enabled.

#### 20.3.2. Watchdog Timer Usage

To configure the WDT, perform the following tasks:

- Disable the WDT by writing a '0' to the WDTE bit.
- Select the desired PCA clock source (with the CPS2-CPS0 bits).
- Load PCA0CPL2 with the desired WDT update offset value.
- Configure the PCA Idle mode (set CIDL if the WDT should be suspended while the CPU is in Idle mode).
- Enable the WDT by setting the WDTE bit to '1'.

The PCA clock source and Idle mode select cannot be changed while the WDT is enabled. The watchdog timer is enabled by setting the WDTE or WDLCK bits in the PCA0MD register. When WDLCK is set, the WDT cannot be disabled until the next system reset. If WDLCK is not set, the WDT is disabled by clearing the WDTE bit.

The WDT is enabled following any reset. The PCA0 counter clock defaults to the system clock divided by 12, PCA0L defaults to 0x00, and PCA0CPL2 defaults to 0x00. Using Equation 20.4, this results in a WDT timeout interval of 3072 system clock cycles. Table 20.3 lists some example timeout intervals for typical system clocks.



System Clock (Hz)	PCA0CPL2	Timeout Interval (ms)
24,500,000	255	32.1
24,500,000	128	16.2
24,500,000	32	4.1
18,432,000	255	42.7
18,432,000	128	21.5
18,432,000	32	5.5
11,059,200	255	71.1
11,059,200	128	35.8
11,059,200	32	9.2
3,062,500	255	257
3,062,500	128	129.5
3,062,500	32	33.1
191,406 <sup>2</sup>	255	4109
191,406 <sup>2</sup>	128	2070
191,406 <sup>2</sup>	32	530
32,000	255	24576
32,000	128	12384
32,000	32	3168
Notes: 1. Assumes SYSCLK / value of 0x00 at the		k source, and a PCA0L

# Table 20.3. Watchdog Timer Timeout Intervals<sup>1</sup>

2. Internal oscillator reset frequency.



## 20.4. Register Descriptions for PCA

Following are detailed descriptions of the special function registers related to the operation of the PCA.

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu	
CF	CR	Reserved	Reserved	Reserved	CCF2	CCF1	CCF0	0000000	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressabl	
							SFR Address	s: 0xD8	
Bit7:	<b>CF</b> : PCA Co Set by hardy Counter/Tim to the PCA i	ware when the the ser overflow nterrupt ser	ne PCA Cou (CF) interr vice routine	unter/Timer oupt is enable	ed, setting	this bit caus	ses the CPl	J to vector	
Bit6:	must be cleared by software. <b>CR</b> : PCA Counter/Timer Run Control. This bit enables/disables the PCA Counter/Timer. 0: PCA Counter/Timer disabled. 1: PCA Counter/Timer enabled.								
Bits5–3:	Reserved.								
Bit2:	CCF2: PCA This bit is see enabled, see bit is not aut	et by hardwa tting this bit comatically c	re when a l causes the leared by h	match or cap CPU to vect ardware and	or to the P	CA interrup	ot service ro		
Bit1:	CCF1: PCA This bit is see enabled, see bit is not aut	et by hardwa tting this bit	re when a causes the	match or cap CPU to vect	or to the P	CA interrup	ot service ro		
Bit0:	<b>CCF0</b> : PCA This bit is see enabled, see bit is not aut	et by hardwa tting this bit	re when a causes the	match or cap CPU to vect	or to the P	CA interrup	ot service ro	•	

## SFR Definition 20.1. PCA0CN: PCA Control



Bit6:	Specifies P 0: PCA cor	CA behave to	Bit Timer Idle vior when	4 Bit3	CPS1 Bit2	CPS0 Bit1	ECF Bit0	0100000							
Bit7: Bit6:	CIDL: PCA Specifies P 0: PCA cor 1: PCA ope	Counter/ CA behavioritinues to	Timer Idle /ior when	e Control.	Bit2	Bit1	Bit0								
Bit6:	Specifies P 0: PCA cor 1: PCA ope	CA behave to	vior when												
Bit6:	Specifies P 0: PCA cor 1: PCA ope	CA behave to	vior when				SFR Addres	s: 0xD9							
Bit6:	Specifies P 0: PCA cor 1: PCA ope	CA behave to	vior when												
Bit6:	0: PCA cor 1: PCA ope	ntinues to		<b>CIDL</b> : PCA Counter/Timer Idle Control. Specifies PCA behavior when CPU is in Idle Mode.											
Bit6:		eration is a	0: PCA continues to function normally while the system controller is in Idle Mode.												
	WDTE: Wa		1: PCA operation is suspended while the system controller is in Idle Mode.												
		•													
				is used as the v	vatchdog tir	ner.									
	0: Watchdog Timer disabled. 1: PCA Module 2 enabled as Watchdog Timer.														
				-											
	WDLCK: Watchdog Timer Lock This bit locks/unlocks the Watchdog Timer Enable. When WDLCK is set, the Watch														
				til the next syste		WELEN		atonidog							
	0: Watchdo			•											
	1: Watchdo	-													
				don't care.											
3its3–1∶	I: CPS2–CPS0: PCA Counter/Timer Pulse Select.														
	These bits select the timebase source for the PCA counter.														
I	CPS2	CPS1	CPS0		т	imebase									
·	0	0	0	System clock di											
	0	0	1	System clock di											
	0	1	0	Timer 0 overflow											
	0	4	4	High-to-low trar	sitions on E	ECI (max ra	te = systen	n clock							
	0	1	1	divided by 4)		,	•								
	1	0	0	System clock											
	1	0	1	External clock of	livided by 8	*									
	1	1	0	Reserved											
	1	1	1	Reserved											
			•	Reserveu		*Note: External clock divided by 8 is synchronized with the system clock.									



Rev. 0.5

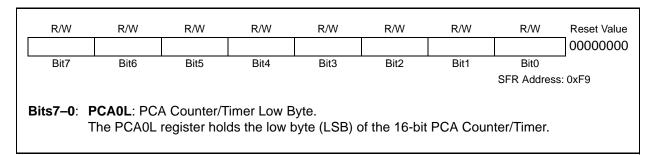
## SFR Definition 20.3. PCA0CPMn: PCA Capture/Compare Mode

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value		
PWM16	in ECOMn	CAPPn	CAPNn	MATn	TOGn	PWMn	ECCFn	00000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0			
SFR Addre	ess: PCA0CPM0: (	0xDA, PCA0C	PM1: 0xDB, P	CA0CPM2: 0>	DC					
D'/7										
Bit7:	PWM16n: 16					mada ia an	oblad (D)A	/Mac 1)		
	This bit selec 0: 8-bit PWM		bae when P	uise wiath	wodulation	mode is en	abled (PW	m = 1).		
	1: 16-bit PWN									
Bit6:	ECOMn: Cor		Inction Enab	مار						
Ditto.	This bit enab				on for PCA	module n				
	0: Disabled.					module n.				
	1: Enabled.									
Bit5:	CAPPn: Cap	ture Positiv	e Function I	Enable.						
	This bit enab				ture for PC/	A module n				
	0: Disabled.		·	• •						
	1: Enabled.									
Bit4:	CAPNn: Cap	-								
	This bit enab	les/disables	s the negativ	ve edge ca	oture for PC	A module r	۱.			
	0: Disabled.									
	1: Enabled.									
Bit3:	MATn: Match Function Enable.									
	This bit enables/disables the match function for PCA module n. When enabled, matches of									
	the PCA counter with a module's capture/compare register cause the CCFn bit in PCA0MD register to be set to logic 1.									
	0: Disabled.	set to logic	<i>i</i> I.							
	1: Enabled.									
Bit2:	TOGn: Toggl	e Function	Enable							
BILZ.	This bit enab			function for	PCA modu	ile n. When	enabled.	matches of		
	the PCA cour									
	CEXn pin to t									
	Output Mode				0		•	. ,		
	0: Disabled.									
	1: Enabled.									
Bit1:	PWMn: Pulse									
	This bit enabl									
	modulated sig			•						
	mode is used			gic 1. If the	IOGn bit is	s also set, th	ne module	operates ir		
	Frequency O	utput Mode	•							
	0: Disabled.									
Bit0:	1: Enabled. ECCFn: Cap	turo/Compo	aro Eloa Into	rrunt Ench						
	This bit sets t					CEn) interru	Int			
	0: Disable CC			uic, comp			·Ρ··			
	1: Enable a C			nterrupt re	ouest when	CCFn is se	et.			

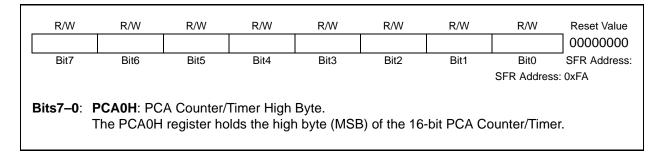


# C8051F52x/F52xA/F53x/F53xA

## SFR Definition 20.4. PCA0L: PCA Counter/Timer Low Byte



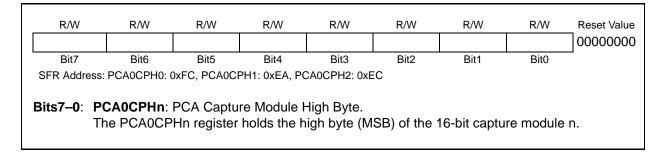
## SFR Definition 20.5. PCA0H: PCA Counter/Timer High Byte



## SFR Definition 20.6. PCA0CPLn: PCA Capture Module Low Byte

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value		
								0000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0			
SFR Address	SFR Address: PCA0CPL0: 0xFB, PCA0CPL1: 0xEA, PCA0CPL2: 0xEB									
Bits7–0: I	Bits7–0: PCA0CPLn: PCA Capture Module Low Byte.									
٦	The PCA0CP	Ln register	holds the lo	ow byte (LS	B) of the 16	6-bit capture	e module r	).		
		Ū.				•				

## SFR Definition 20.7. PCA0CPHn: PCA Capture Module High Byte





## 21. Device Specific Behavior

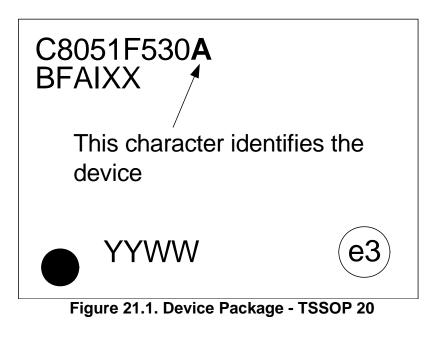
This chapter contains behavioral differences between C8051F52x/F53x devices and C8051F52xA/F53xA devices.

These differences do not affect the functionality or performance of most systems and are described below.

### 21.1. Device Identification

The Part Number identifier on the top side of the device package can be used for decoding device information. On C8051F52xA/F53xA devices, the part number will end with the letter "A." C8051F52x/F53x devices will not have this letter.

Figures 21.1, 21.2, and 21.3 show how to find the part number on the top side of the device package.



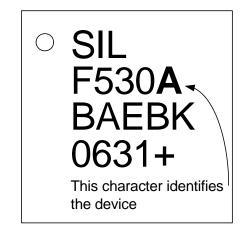


Figure 21.2. Device Package - QFN 20



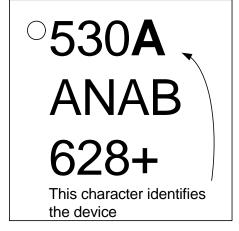


Figure 21.3. Device Package - DFN 10

### 21.2. Reset Pin Behavior

The reset behavior of C8051F52x/F53x differs from C8051F52xA/F53xA devices. The differences affect the state of the RST pin during a VDD Monitor reset.

On C8051F52x/F53x devices, a V<sub>DD</sub> Monitor reset does not affect the state of the RST pin. On C8051F52xA/F53xA devices, a V<sub>DD</sub> Monitor reset will pull the RST pin low for the duration of the brownout condition.

#### 21.3. Reset Time Delay

The reset time delay on C8051F52x/F53x devices differs from C8051F52xA/F53xA devices.

On C8051F52x/F53x devices, the reset time delay will be as long as 80 ms following a power-on reset, meaning it can take up to 80 ms to begin code execution. Subsequent resets will not cause the long delay. On C8051F52xA/F53xA devices, the startup time is around 350  $\mu$ s.

#### 21.4. UART Pins

The location of the pins used by the serial UART interface is different between C8051F52x/F53x and C8051F52xA/F53xA devices.

On C8051F52x/F53x devices, the TX and RX pins used by the UART interface are mapped to the P0.3 (TX) and P0.4 (RX) pins. On C8051F52xA/F53xA, the TX and RX pins used by the UART interface are mapped to the P0.4 (TX) and P0.5 (RX) pins.

**Important Note:** On C8051F52xA/53xA devices, the UART pins must be skipped if the UART is enabled in order for peripherals to appear on port pins beyond the UART on the crossbar. For example, with the SPI and UART enabled on the crossbar with the SPI on P1.0-P1.3, the UART pins must be skipped using P0SKIP for the SPI pins to appear correctly.



### 21.5. LIN

The LIN peripheral behavior in C8051F52x/F53x devices is different than the behavior of C8051F52xA/F53xA devices. The differences are:

#### 21.5.1. Stop Bit Check

On C8051F52x/F53x devices, the stop bits of the fields in the LIN frame are not checked and no error is generated if the stop bits could not be sent or received correctly. On C8051F52xA/F53xA devices, the stop bits are checked, and an error will be generated if the stop bit was not sent or received correctly.

#### 21.5.2. Synch Break and Synch Field Length Check

On C8051F52x/F53x devices, the check of sync field length versus sync break length is incorrect. On C8051F52xA/F53xA devices, the sync break length must be larger than 10 bit times (of the measured bit time) to enable the synchronization.

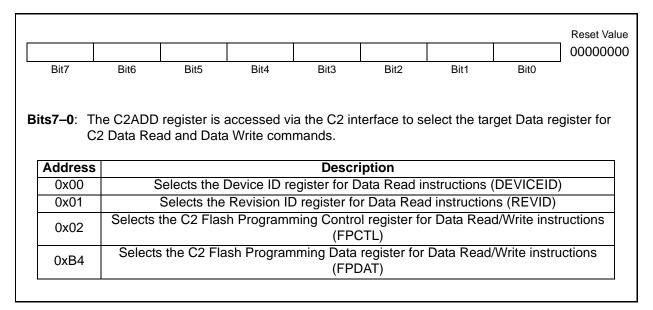


## 22. C2 Interface

C8051F52x/F52xA/F53x/F53xA devices include an on-chip Silicon Laboratories 2-Wire (C2) debug interface to allow Flash programming and in-system debugging with the production part installed in the end application. The C2 interface uses a clock signal (C2CK) and a bi-directional C2 data signal (C2D) to transfer information between the device and a host system. See the C2 Interface Specification for details on the C2 protocol.

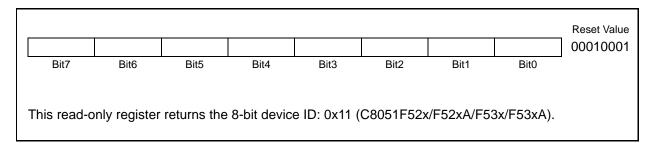
## 22.1. C2 Interface Registers

The following describes the C2 registers necessary to perform Flash programming functions through the C2 interface. All C2 registers are accessed through the C2 interface as described in the C2 Interface Specification.



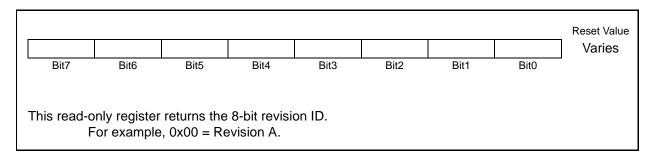
## C2 Register Definition 22.1. C2ADD: C2 Address

## C2 Register Definition 22.2. DEVICEID: C2 Device ID

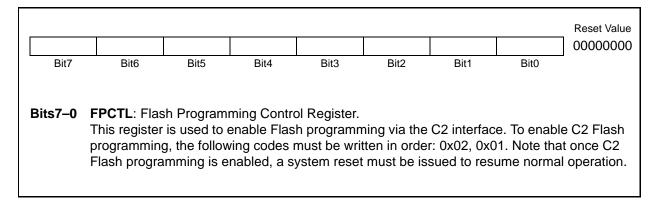




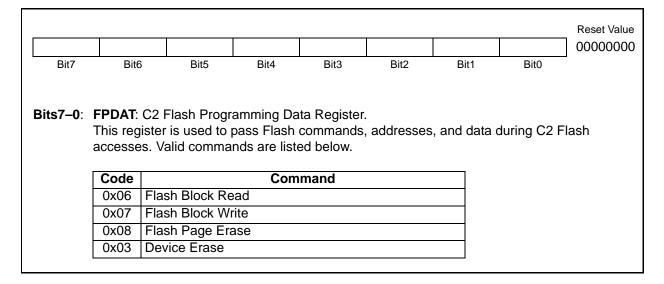
## C2 Register Definition 22.3. REVID: C2 Revision ID



## C2 Register Definition 22.4. FPCTL: C2 Flash Programming Control



## C2 Register Definition 22.5. FPDAT: C2 Flash Programming Data





## 22.2. C2 Pin Sharing

The C2 protocol allows the C2 pins to be shared with user functions so that in-system debugging and Flash programming functions may be performed. This is possible because C2 communication is typically performed when the device is in the halt state, where all on-chip peripherals and user software are stalled. In this halted state, the C2 interface can safely 'borrow' the C2CK (/RST) and C2D (P0.1 or P0.6) pins. In most applications, external resistors are required to isolate C2 interface traffic from the user application. A typical isolation configuration is shown in Figure 22.1.

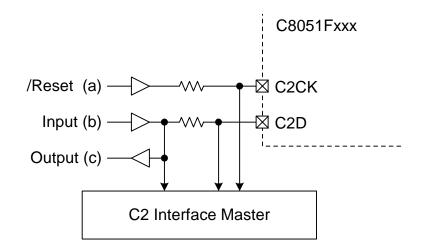


Figure 22.1. Typical C2 Pin Sharing

The configuration in Figure 22.1 assumes the following:

- 1. The user input (b) cannot change state while the target device is halted.
- 2. The /RST pin on the target device is used as an input only.

Additional resistors may be necessary depending on the specific application.



# **DOCUMENT CHANGE LIST**

#### Revision 0.3 to 0.4

- Updated all specification tables.
- Added 'F52xA and 'F53xA information.
- Updated the Selectable Gain section in the ADC chapter.
- Updated the External Crystal Example in the Oscillators chapter.
- Updated the LIN chapter.

#### Revision 0.4 to 0.5

- Updated all specification tables.
- Updated Figures 1.1, 1.2, 1.3, and 1.4.
- Updated Chapter 4 pinout diagrams and tables.



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